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(54) **AUDIO DRIVER AND POWER SUPPLY UNIT ARCHITECTURE**

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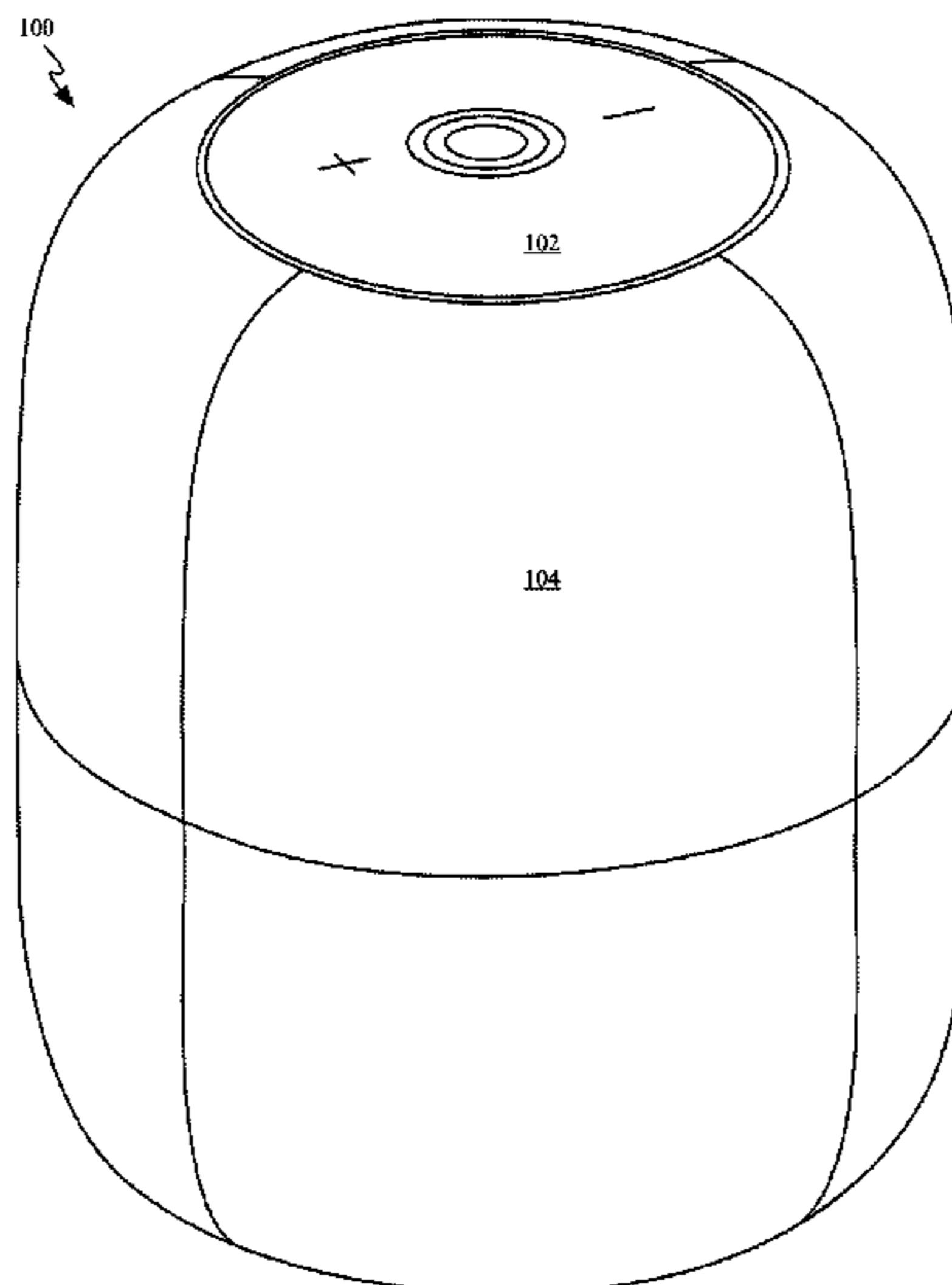
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(57) **ABSTRACT**

This disclosure relates to speakers and more specifically to an array speaker for distributing music uniformly across a room. A number of audio drivers can be radially distributed within a speaker housing so that an output of the drivers is distributed evenly throughout the room. In some embodiments, the exit geometry of the audio drivers can be configured to bounce off a surface supporting the array speaker to improve the distribution of music throughout the room. The array speaker can include a number of vibration isolation elements distributed within a housing of the array speaker. The vibration isolation elements can be configured reduce the strength of forces generated by a subwoofer of the array speaker.

22 Claims, 36 Drawing Sheets



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See application file for complete search history.

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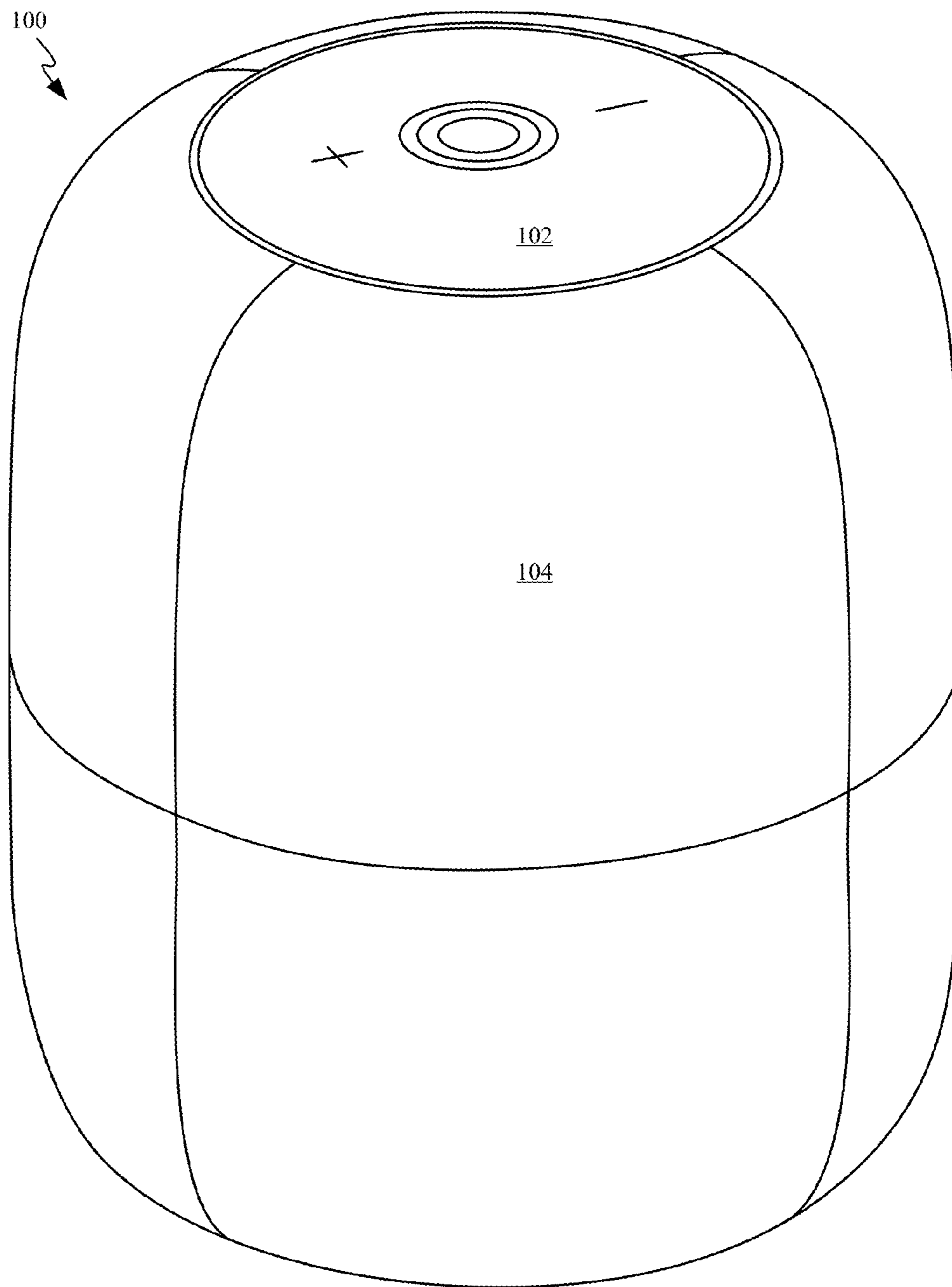


FIG. 1

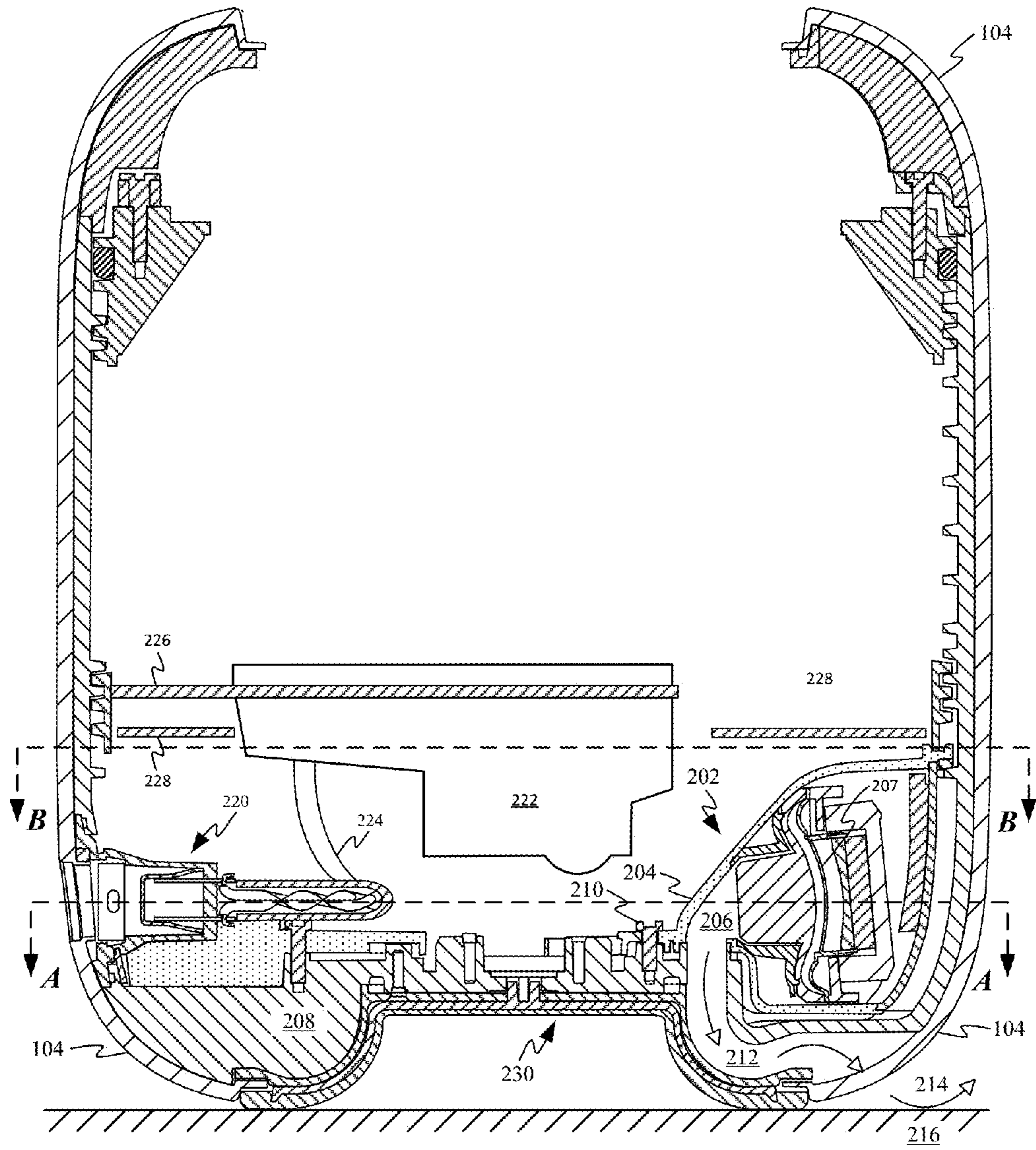


FIG. 2A

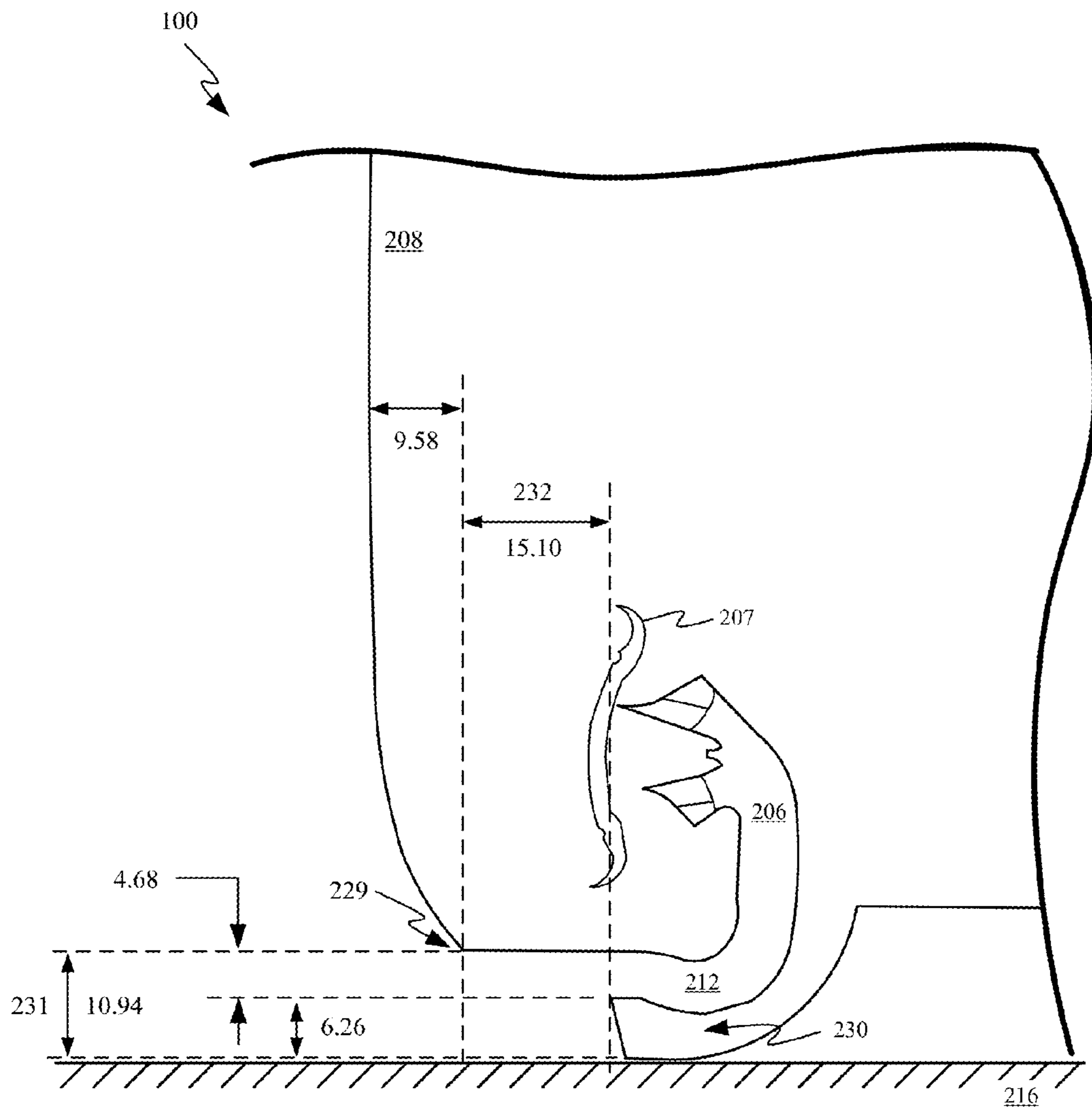


FIG. 2B

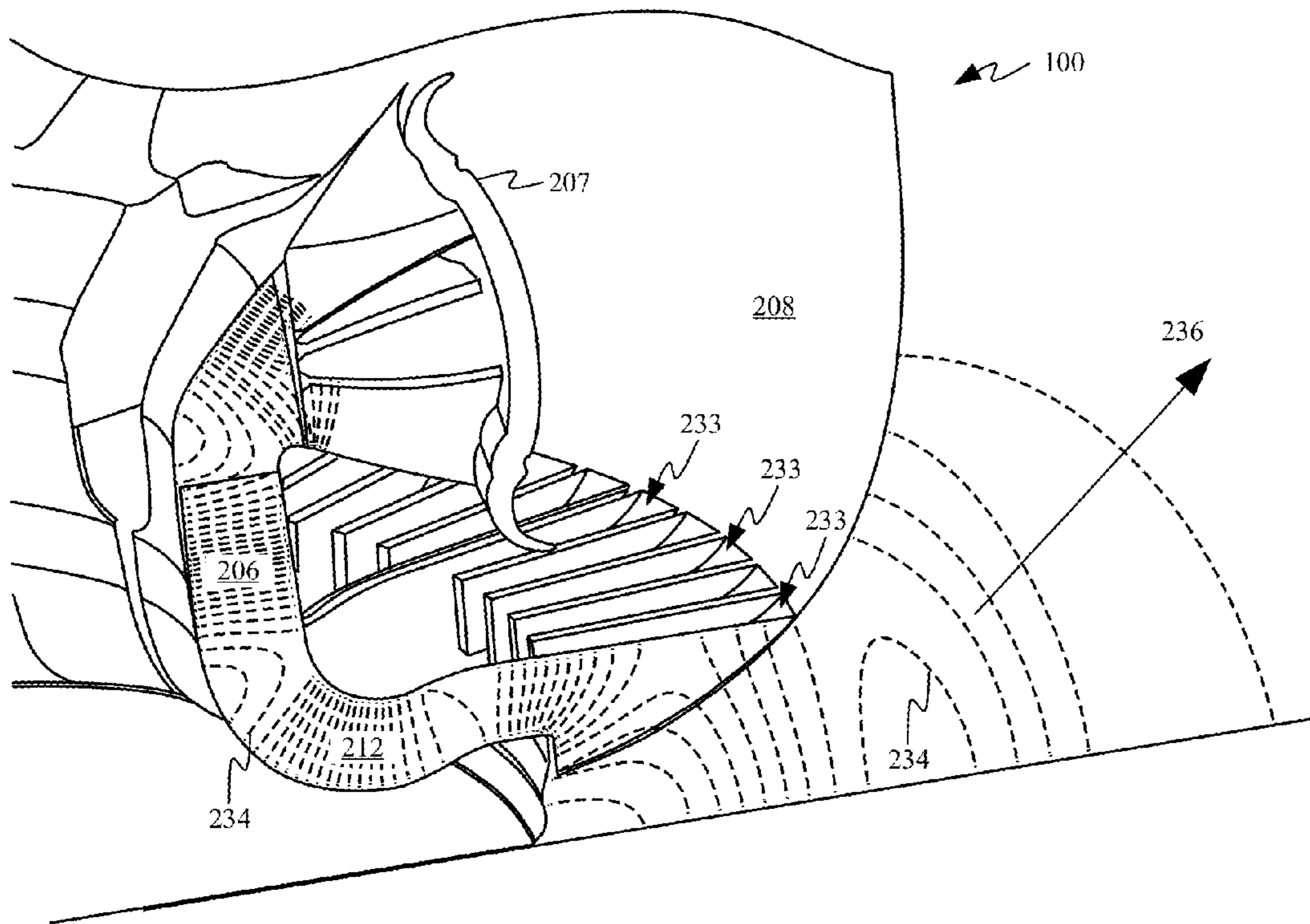


FIG. 2C

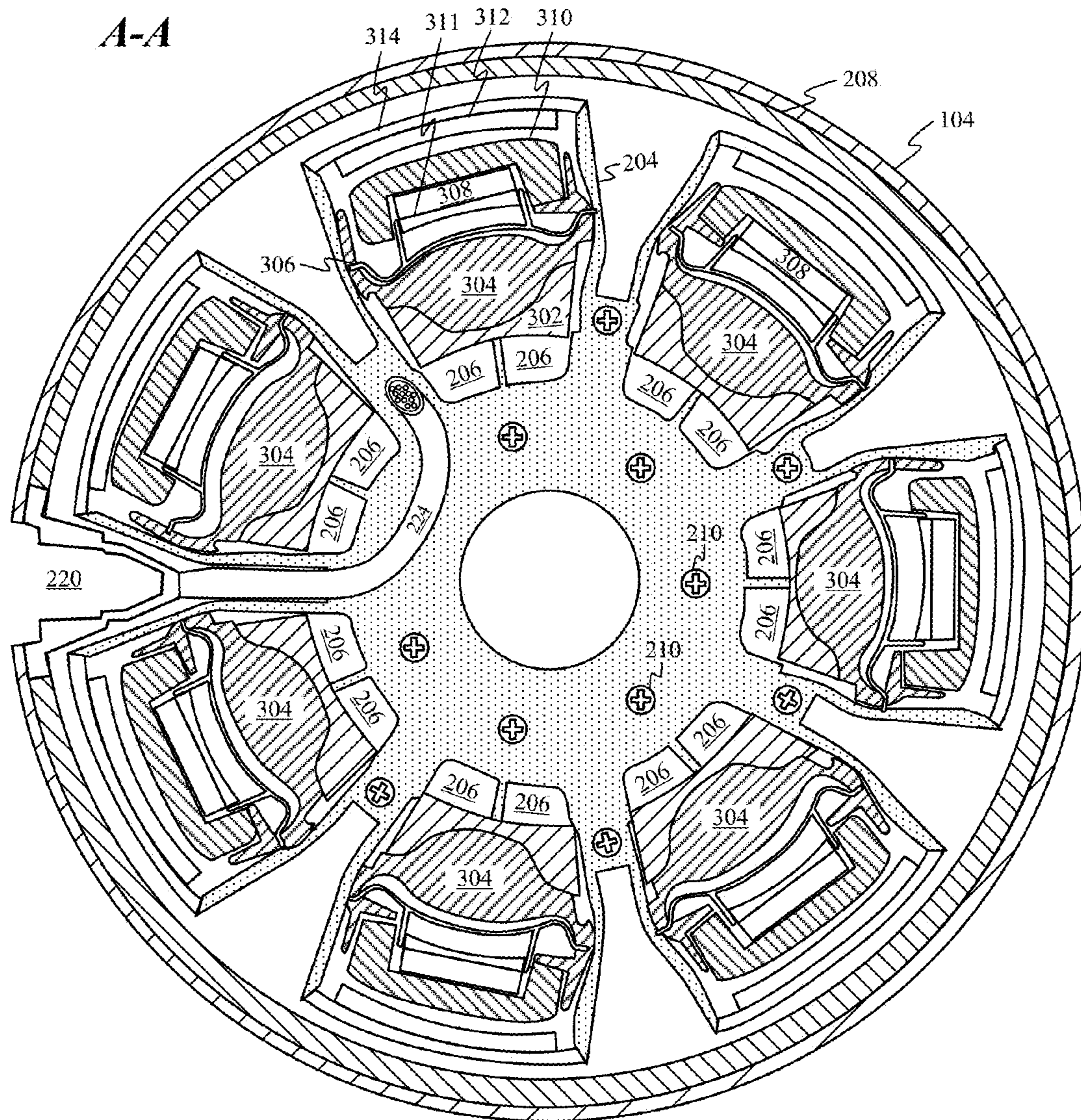


FIG. 3A

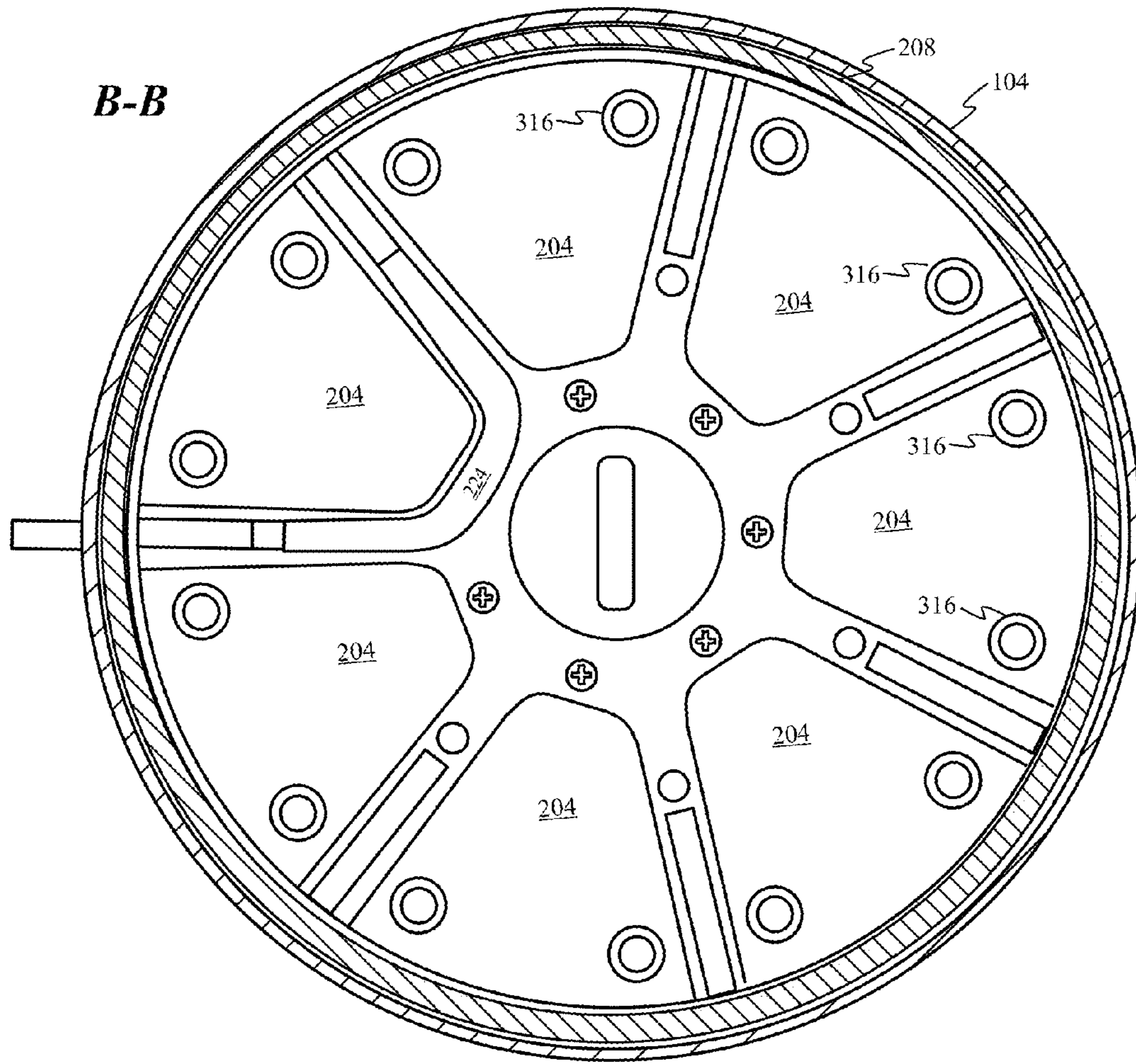


FIG. 3B

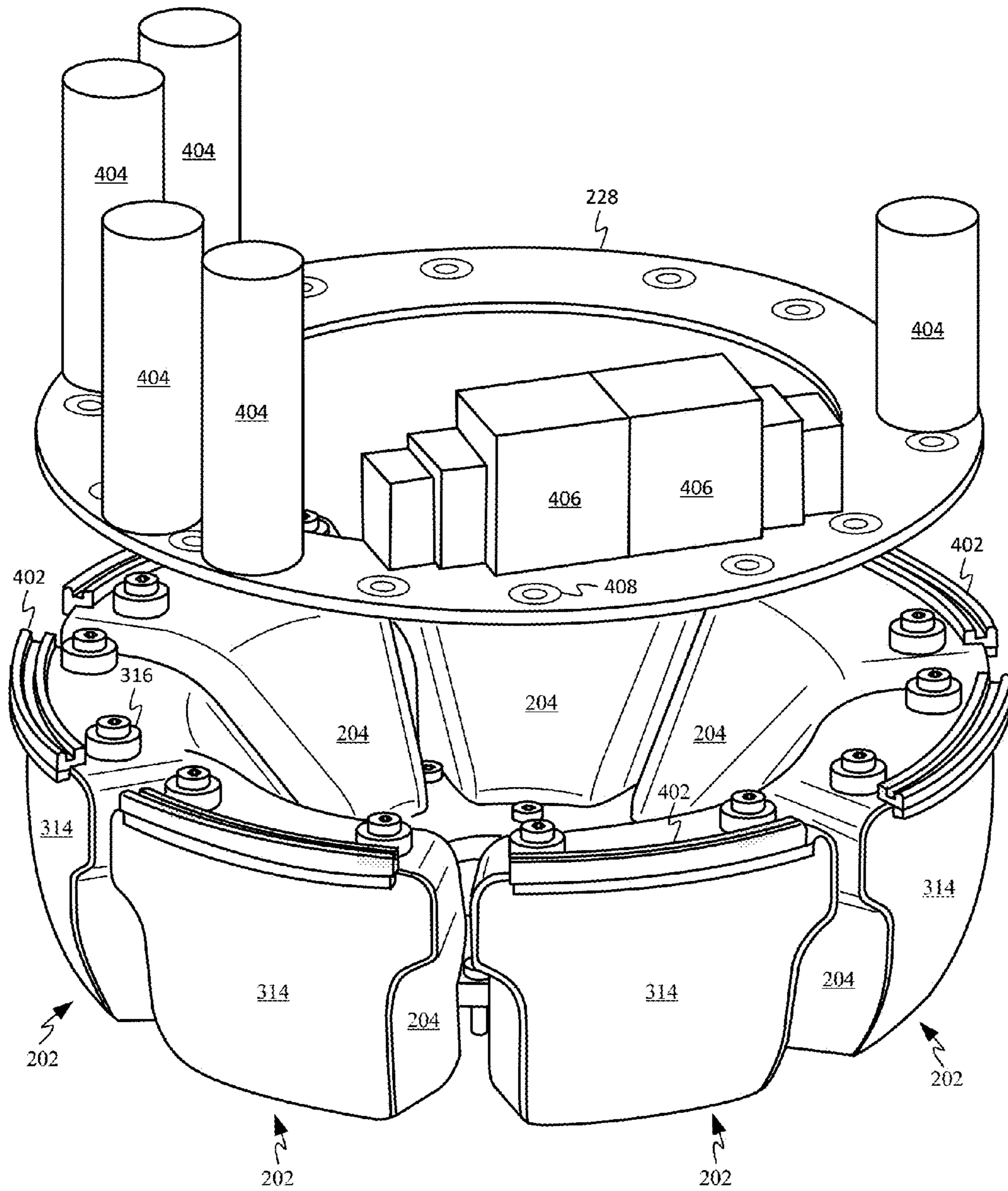


FIG. 4

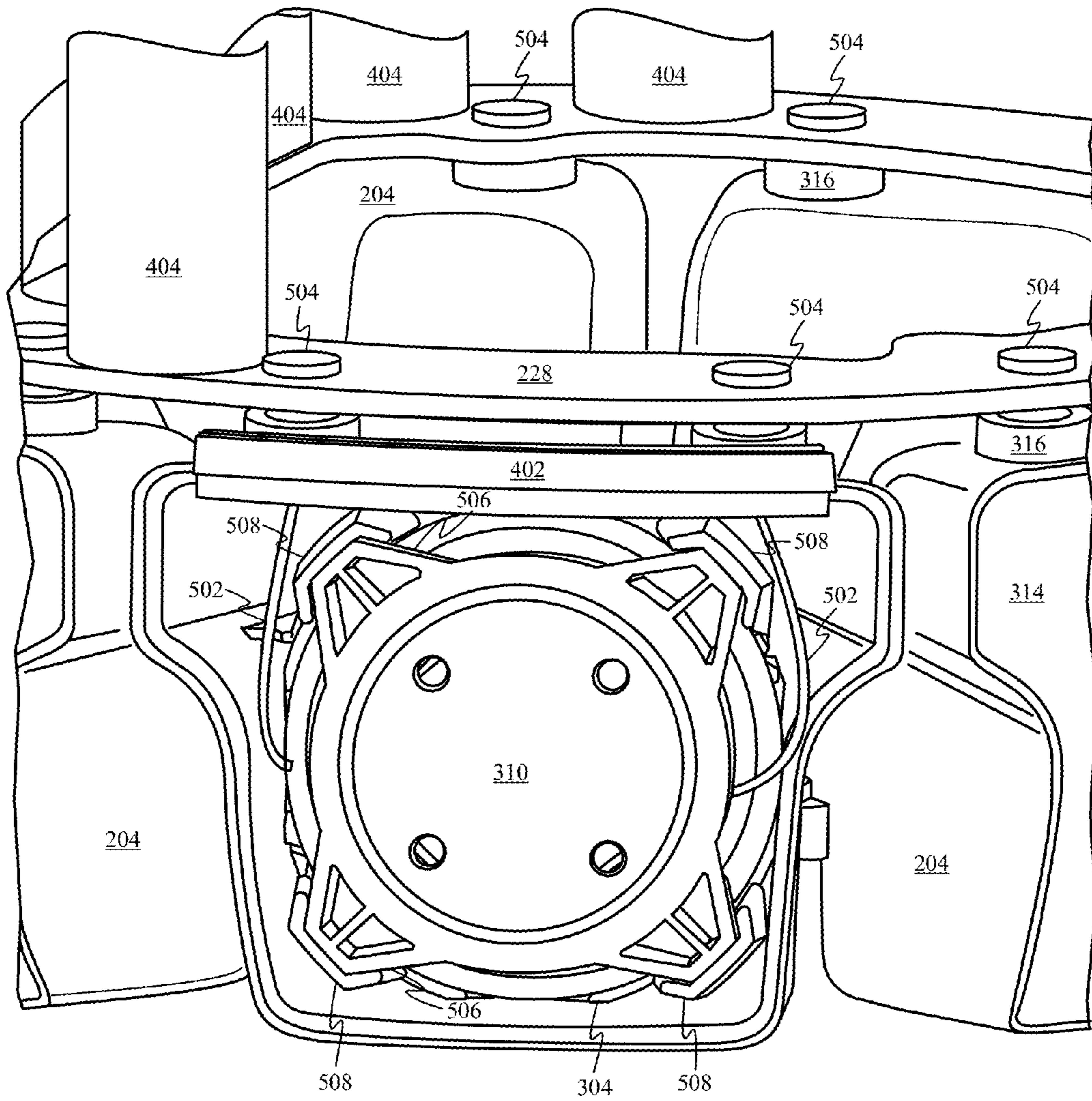


FIG. 5A

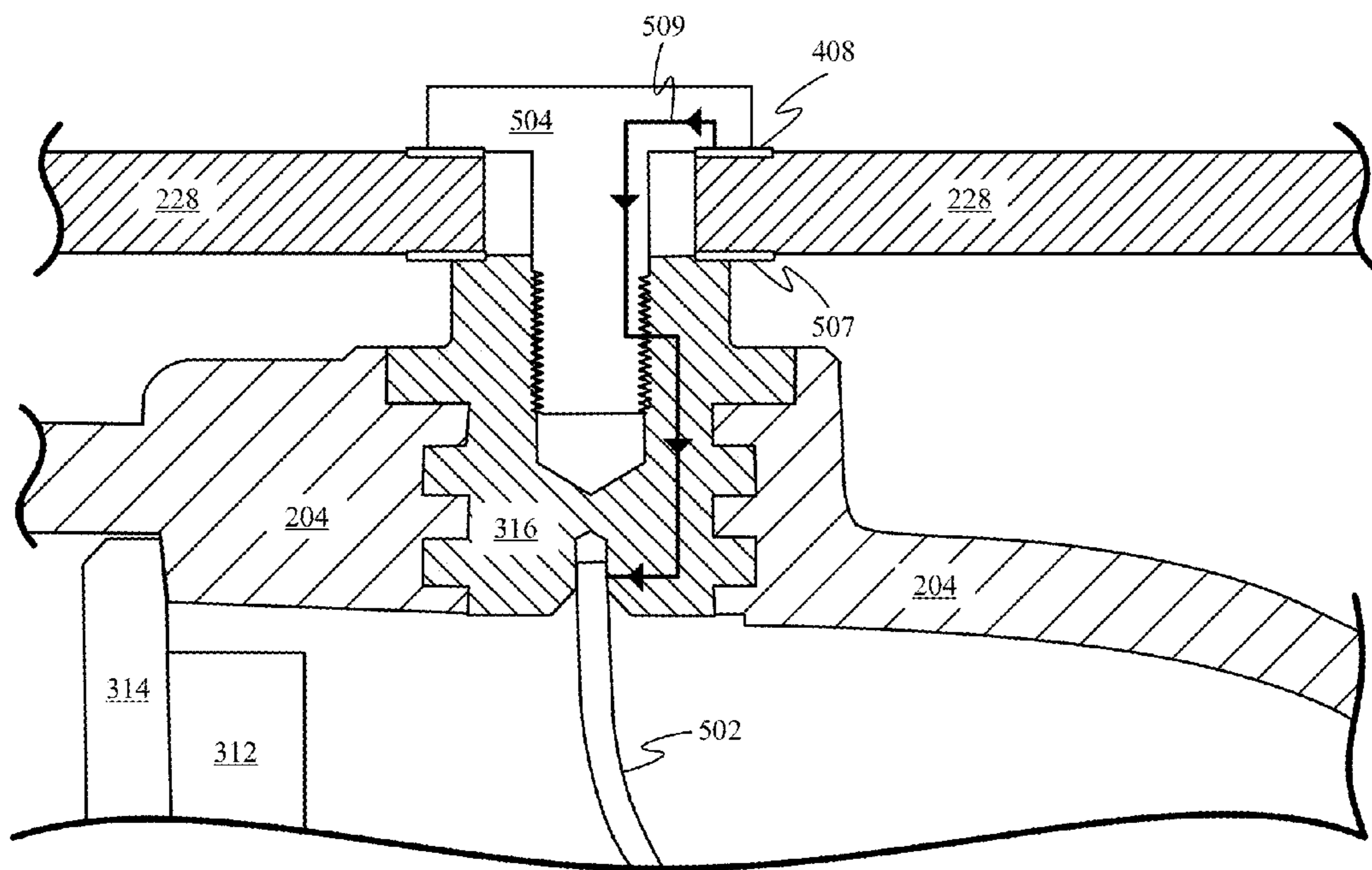


FIG. 5B

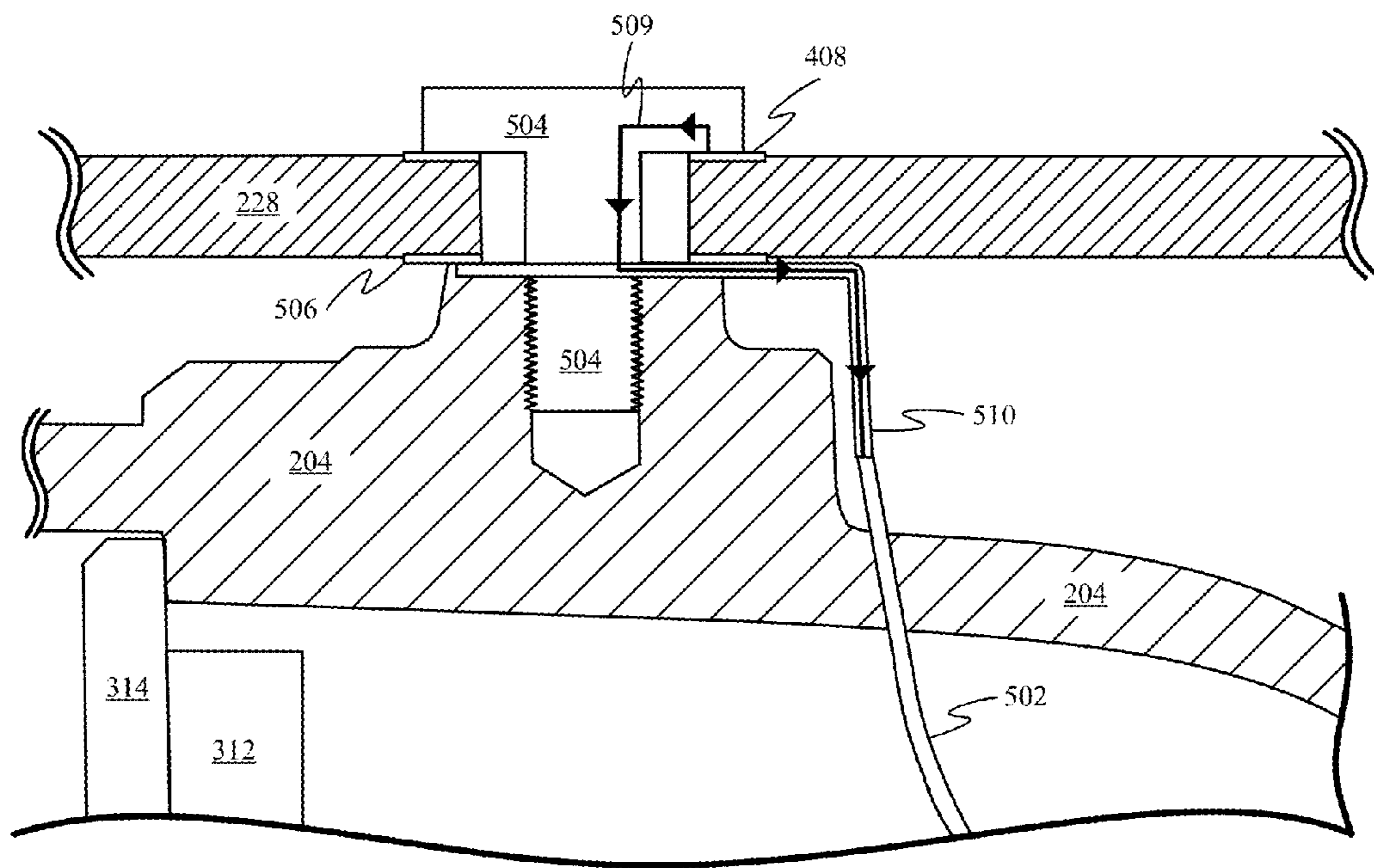


FIG. 5C

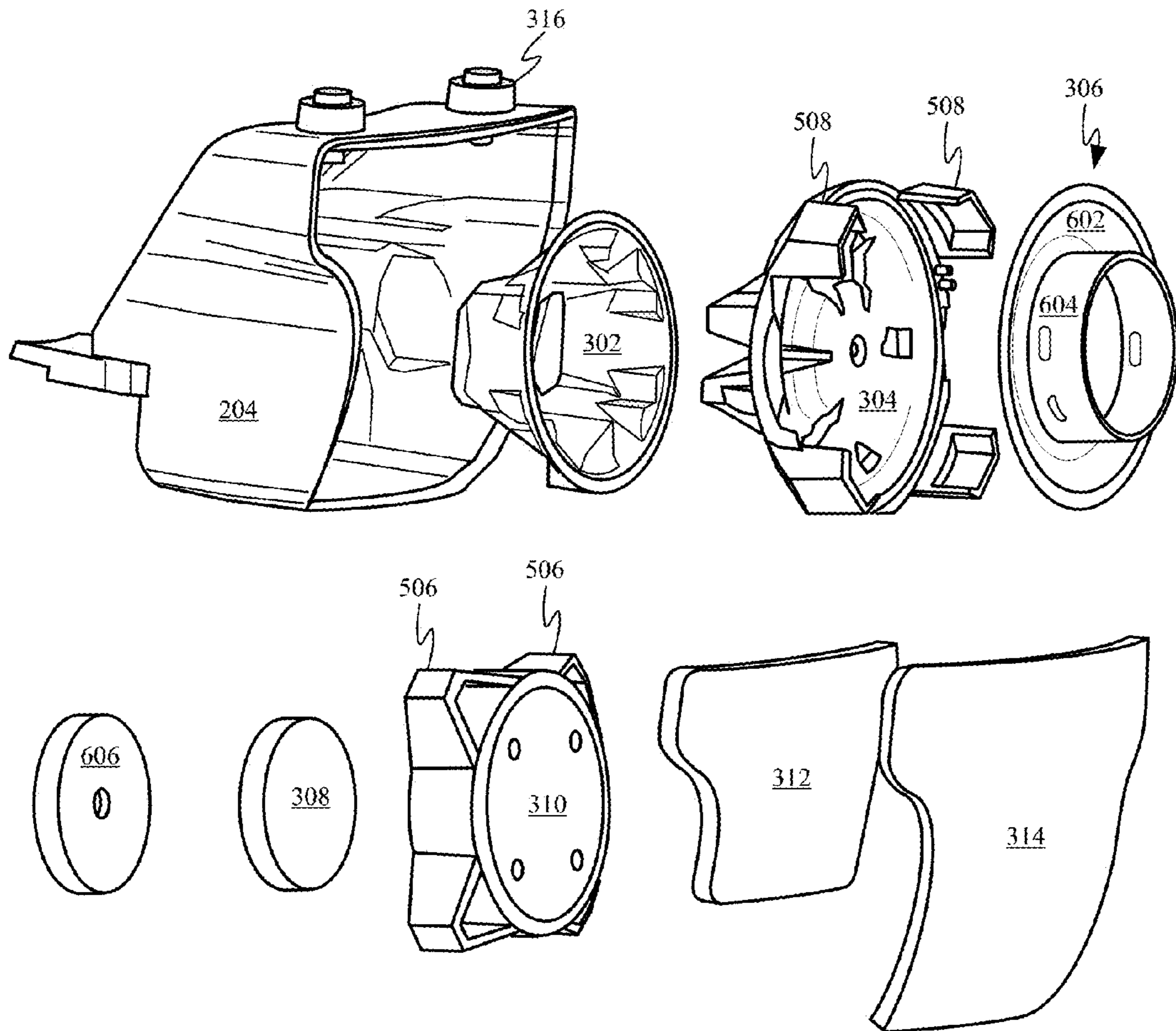


FIG. 6

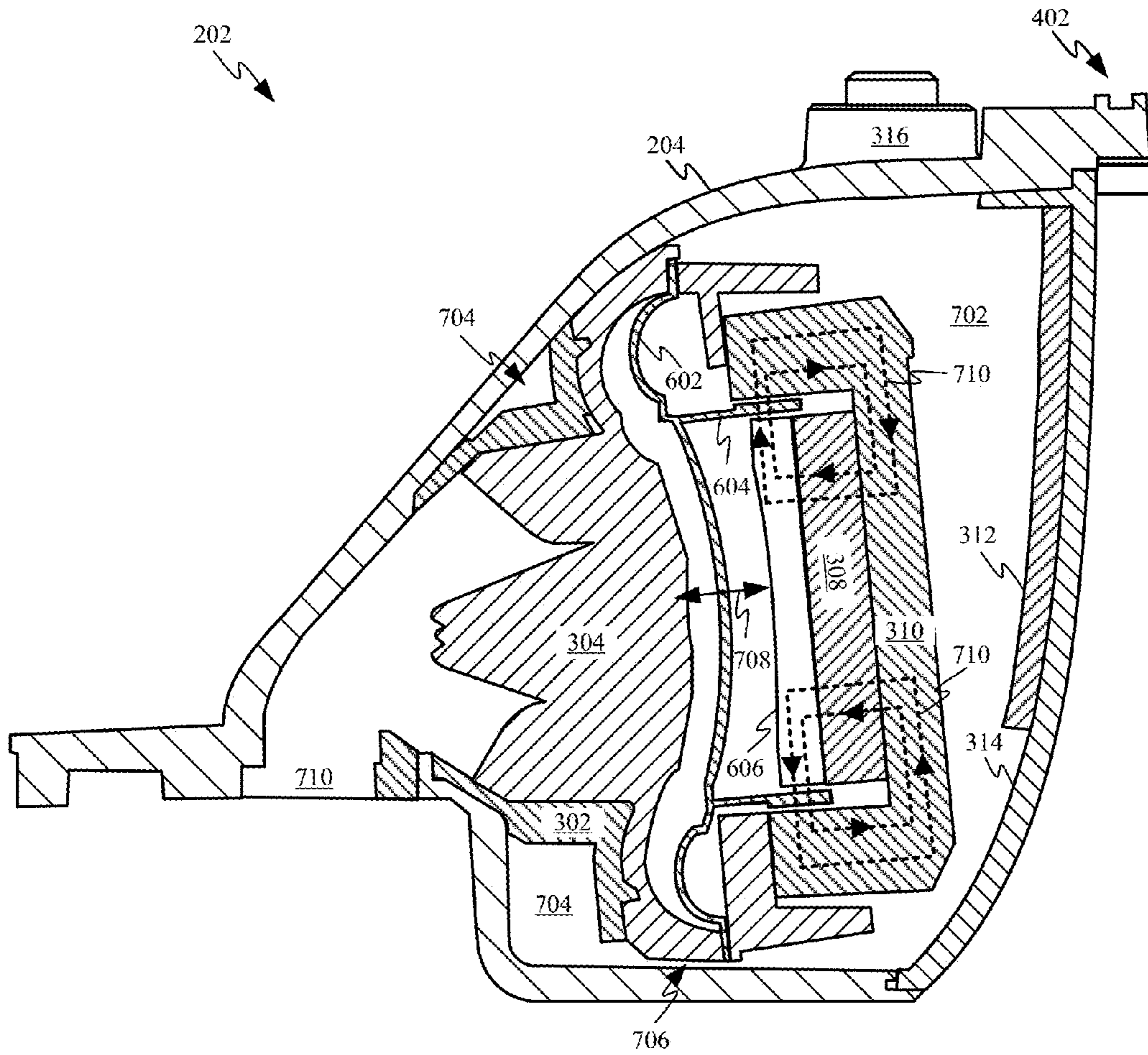


FIG. 7

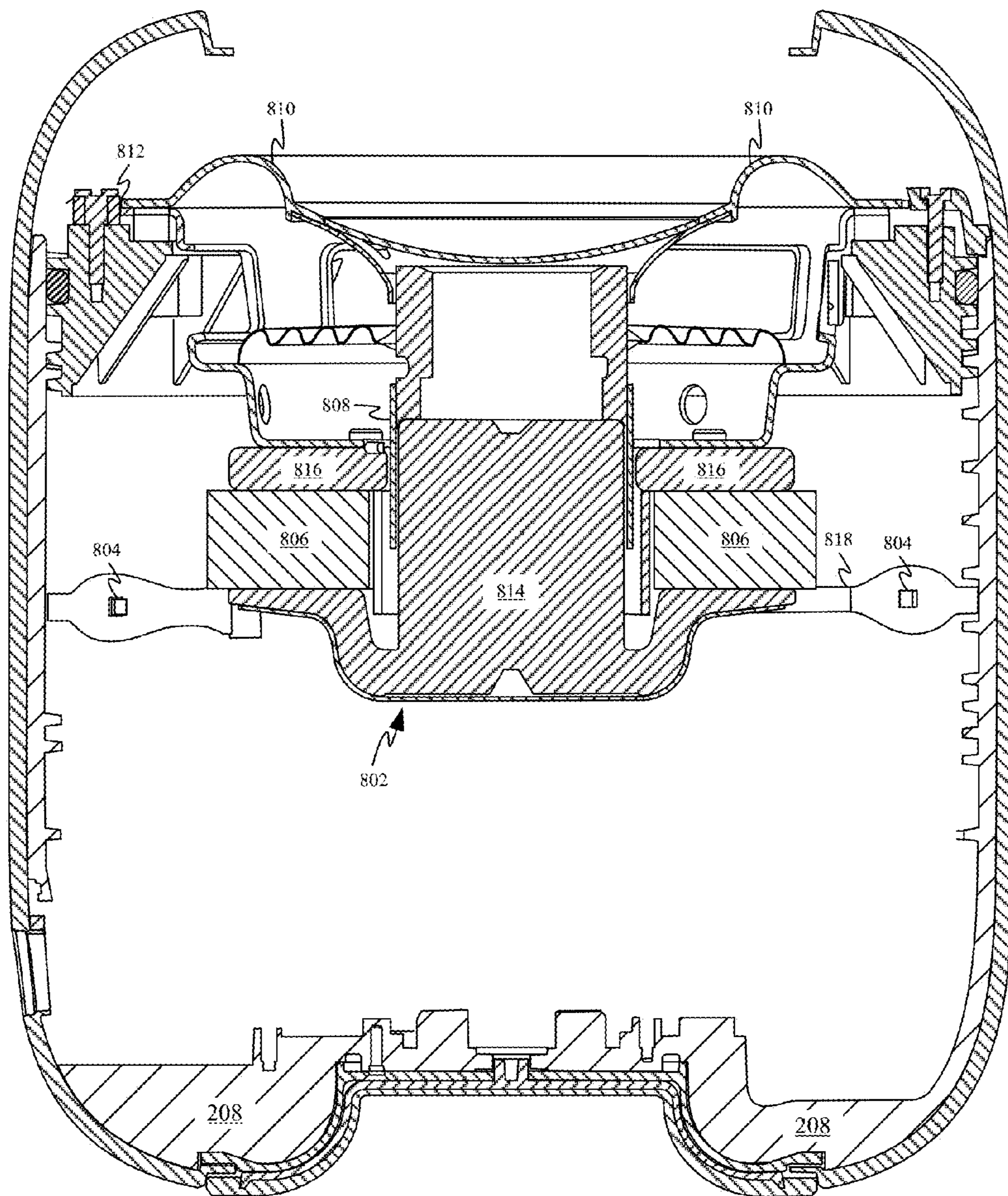


FIG. 8

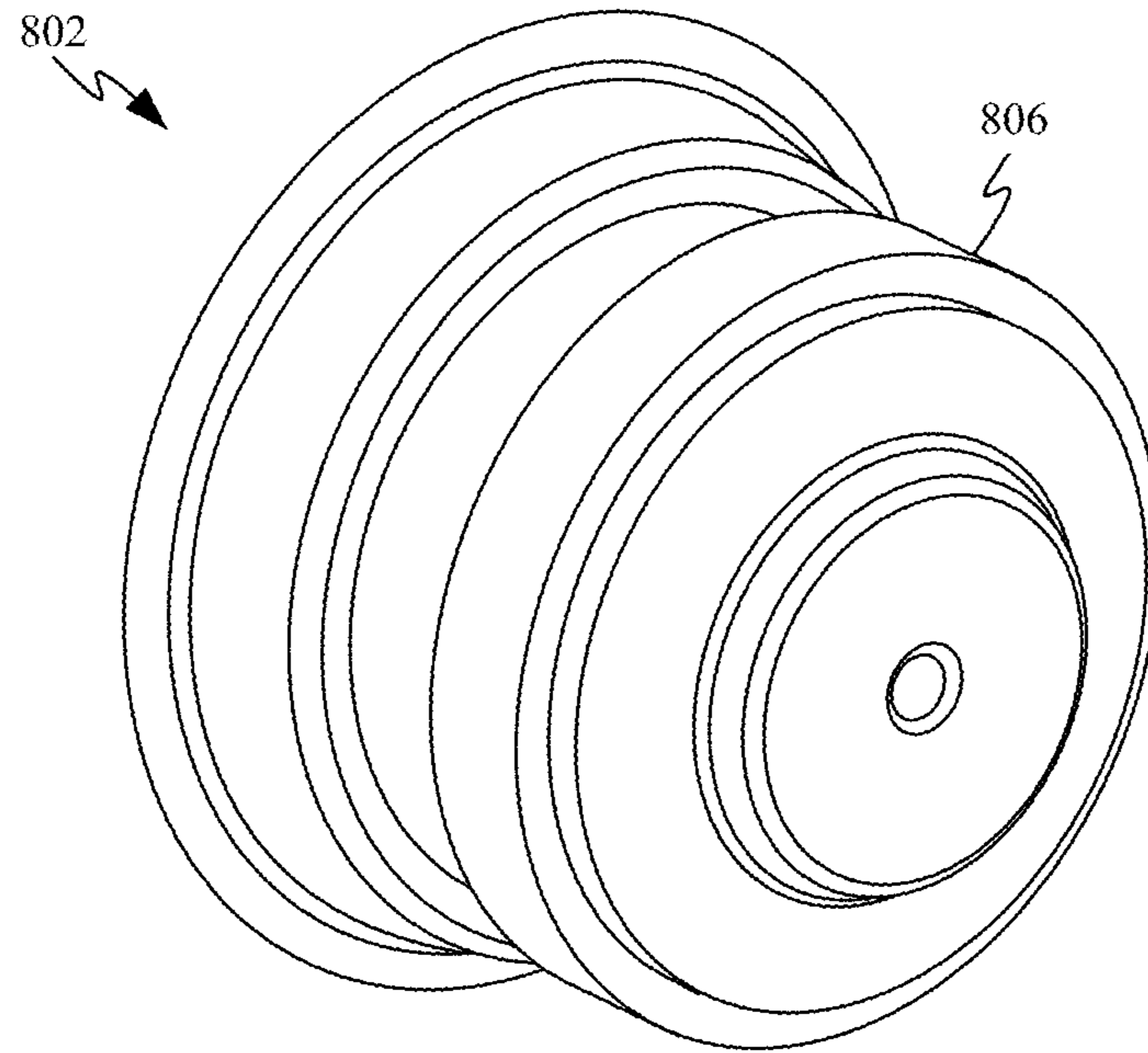


FIG. 9A

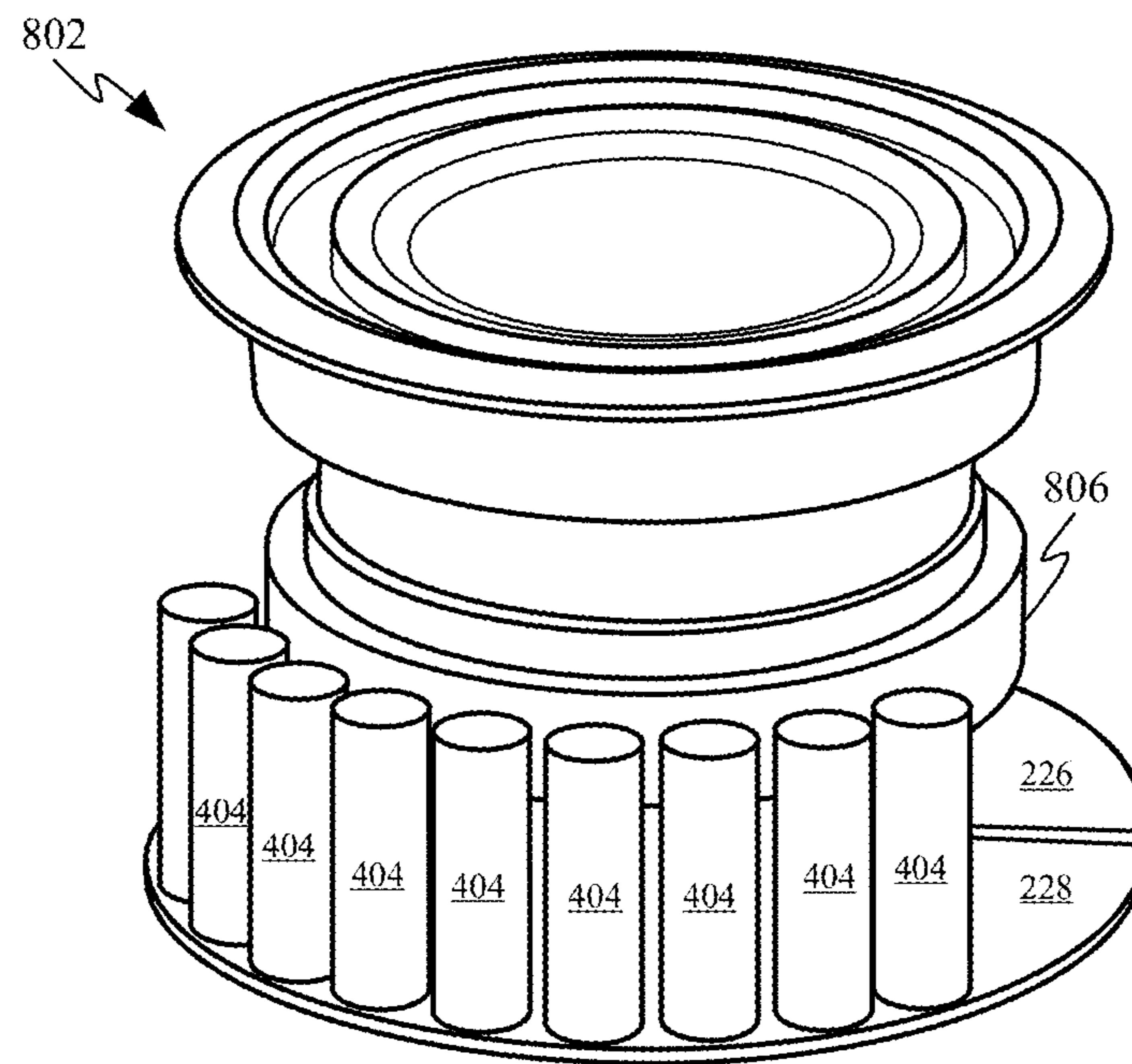


FIG. 9B

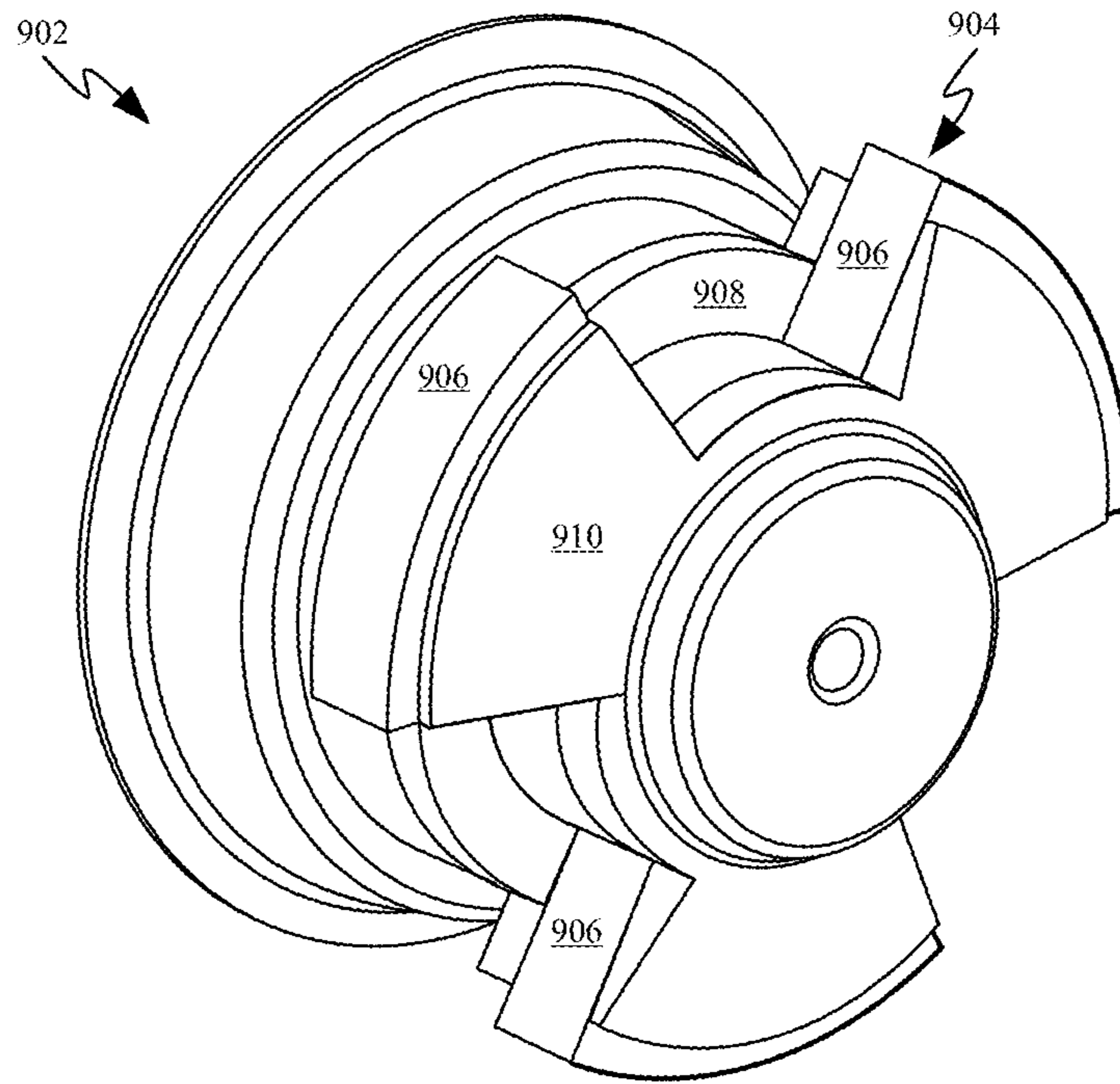


FIG. 9C

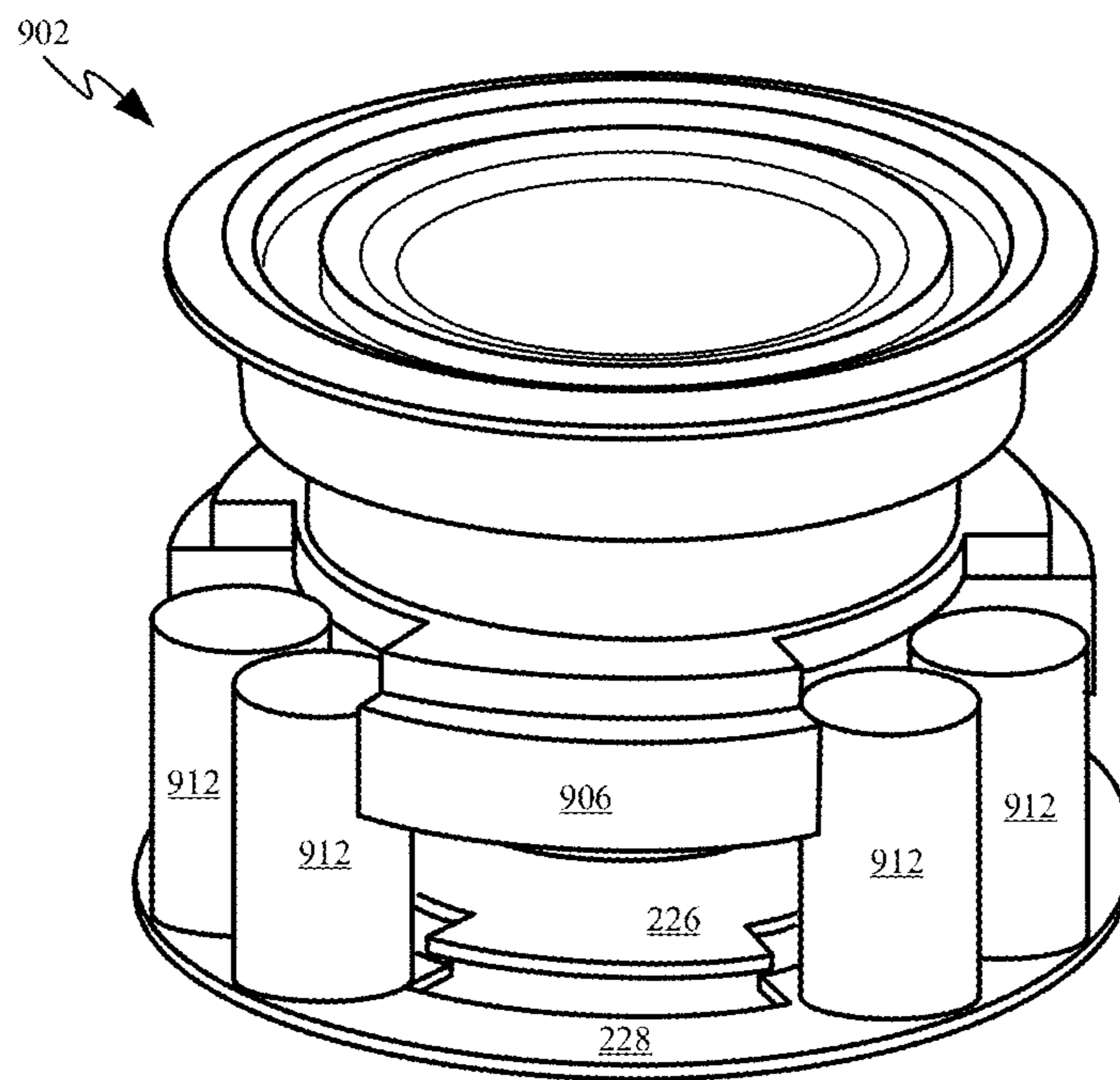


FIG. 9D

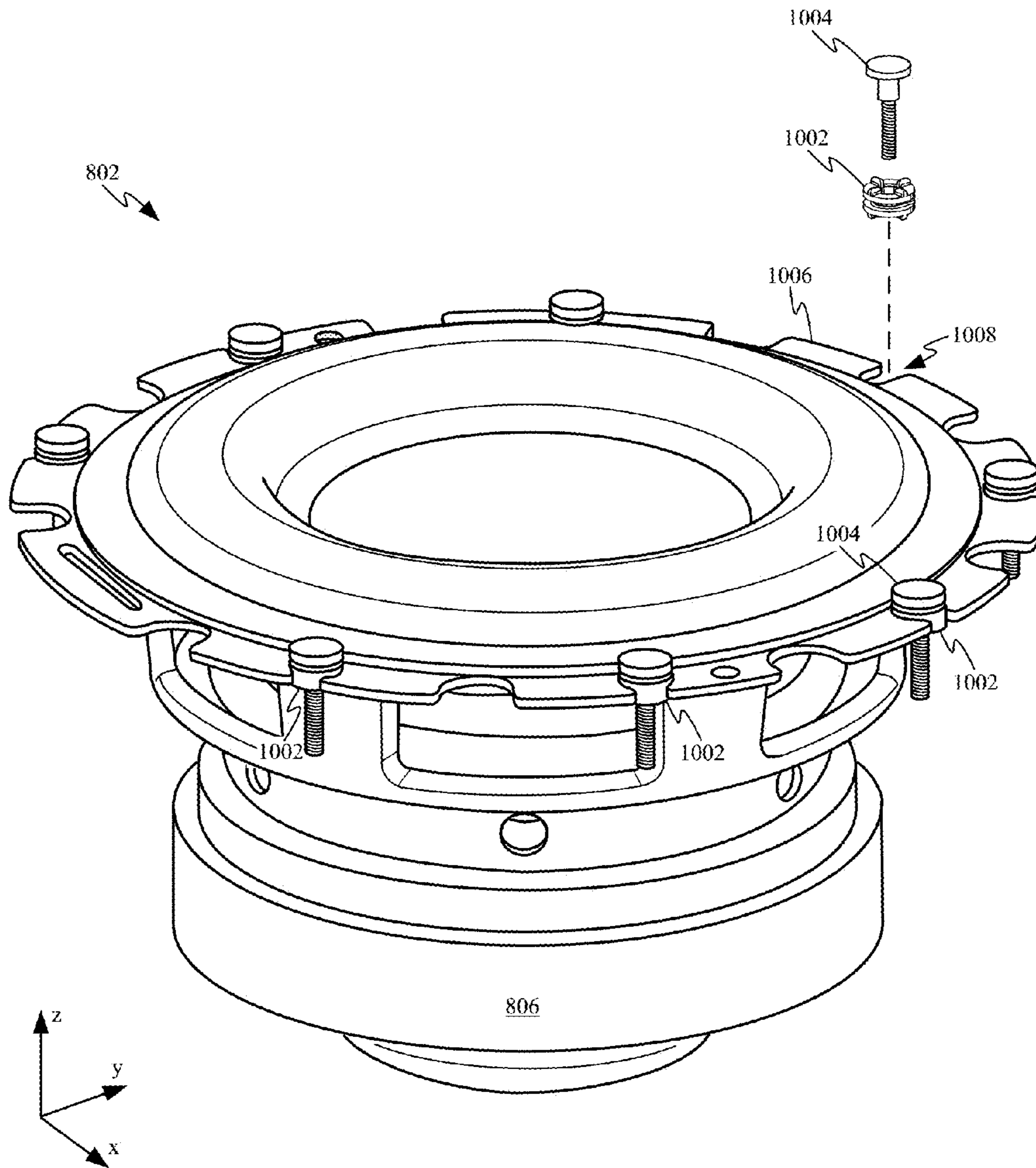


FIG. 10A

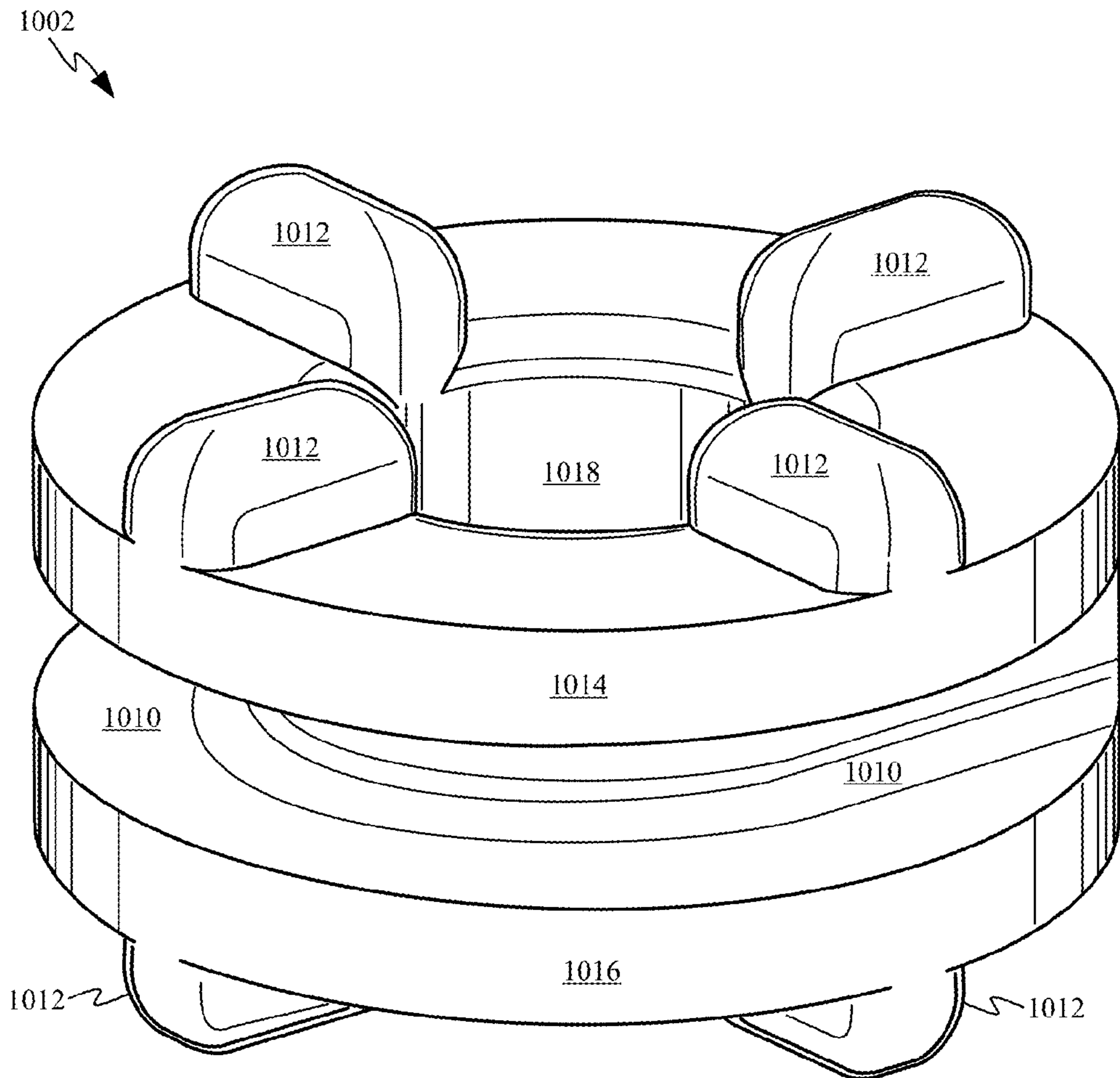


FIG. 10B

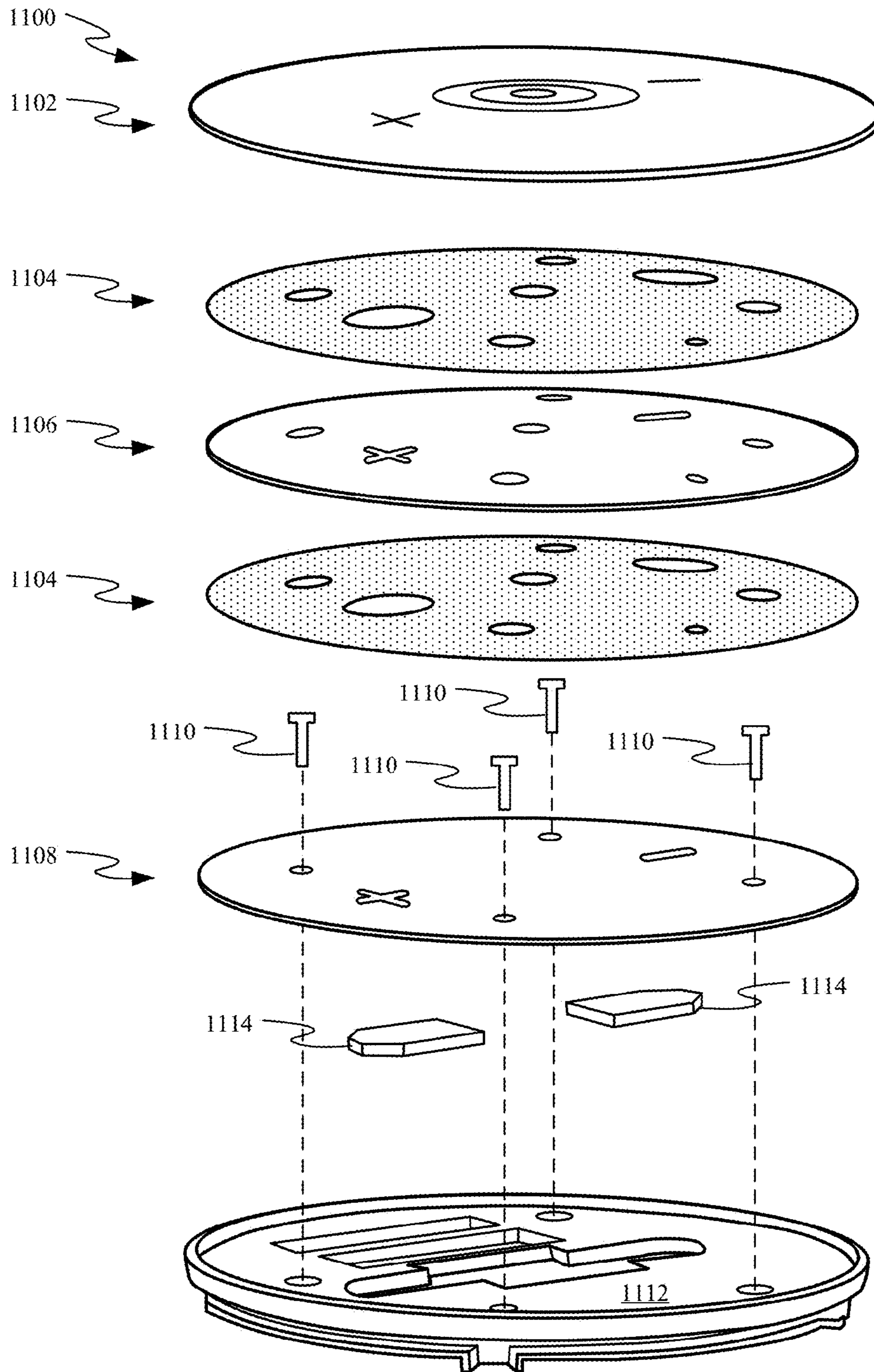


FIG. 11A

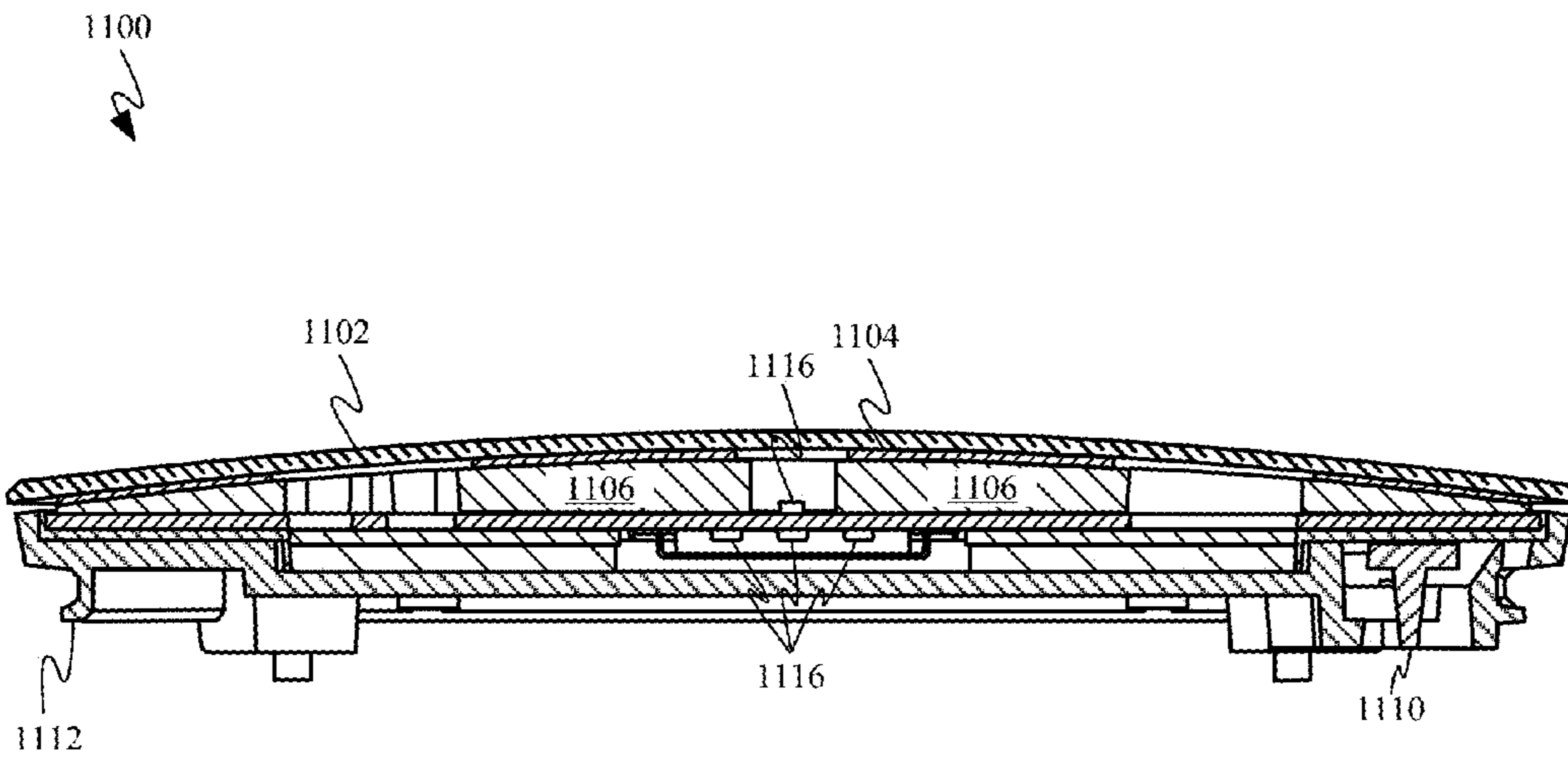


FIG. 11B

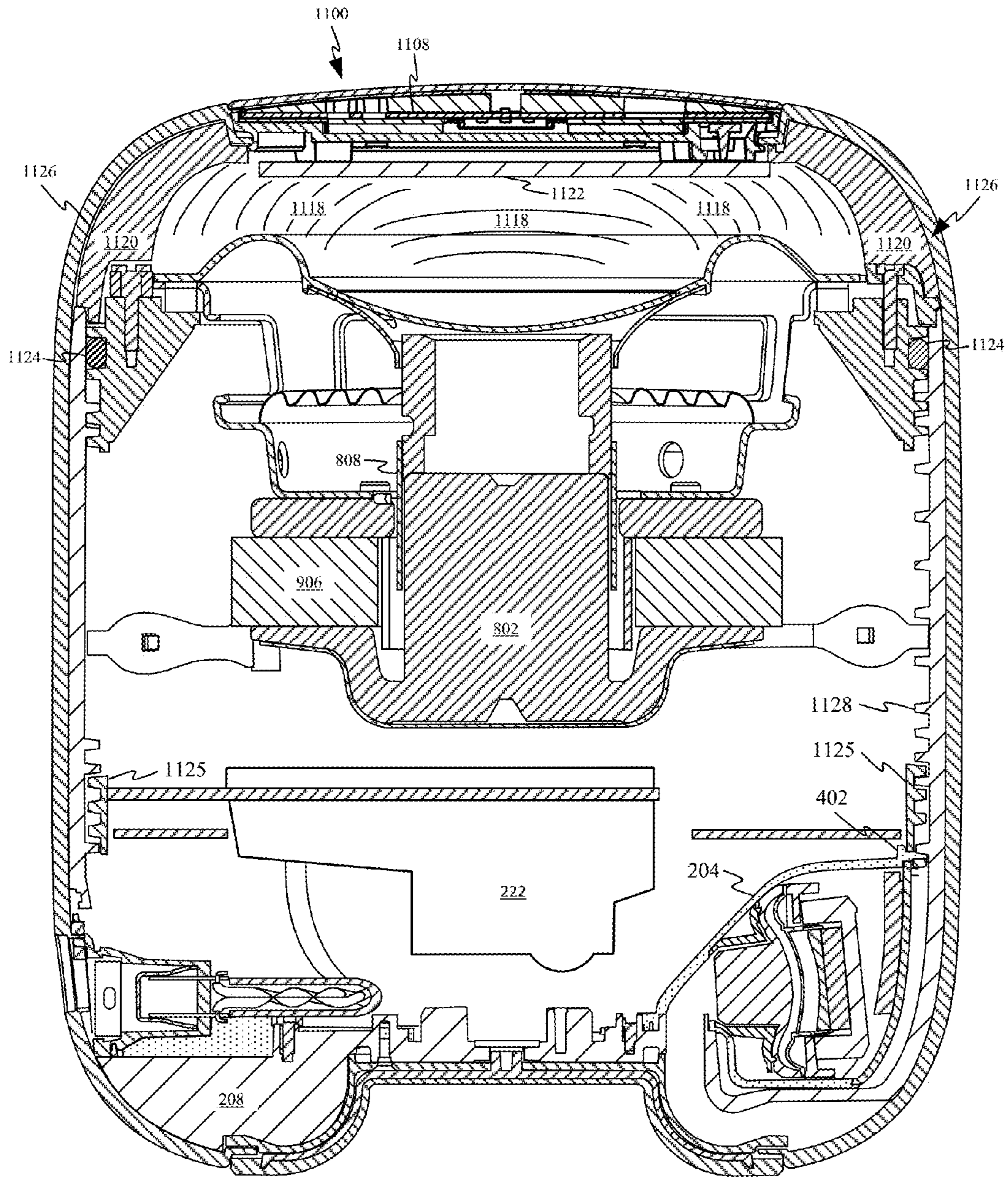


FIG. 11C

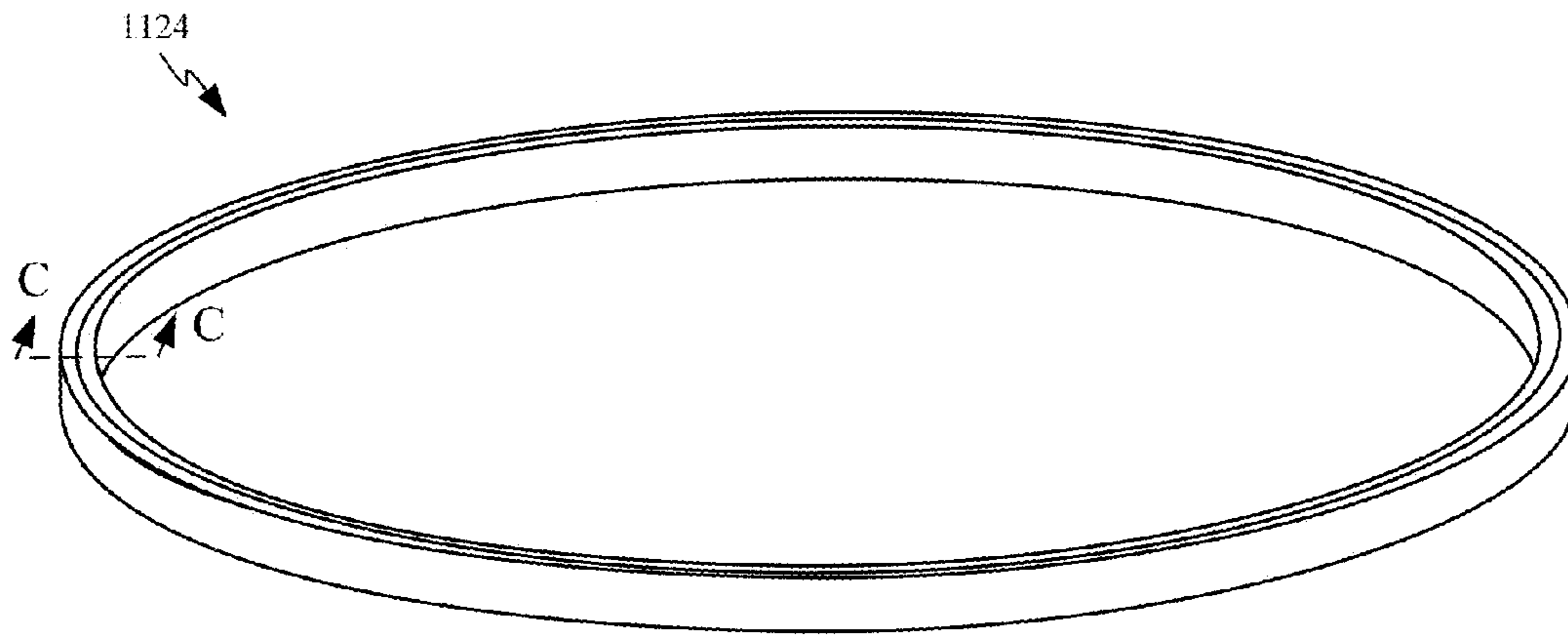


FIG. 12A

C-C

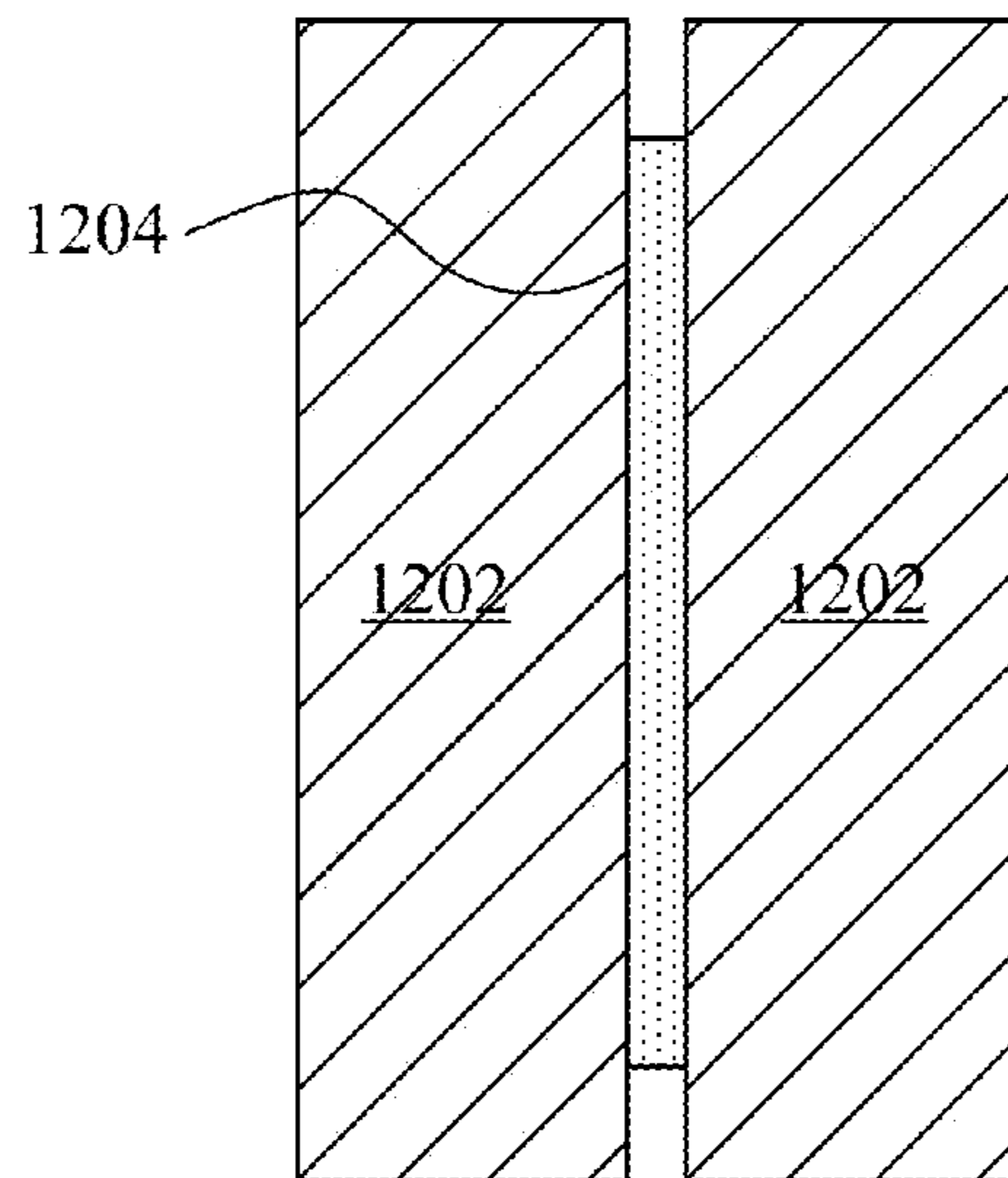


FIG. 12B

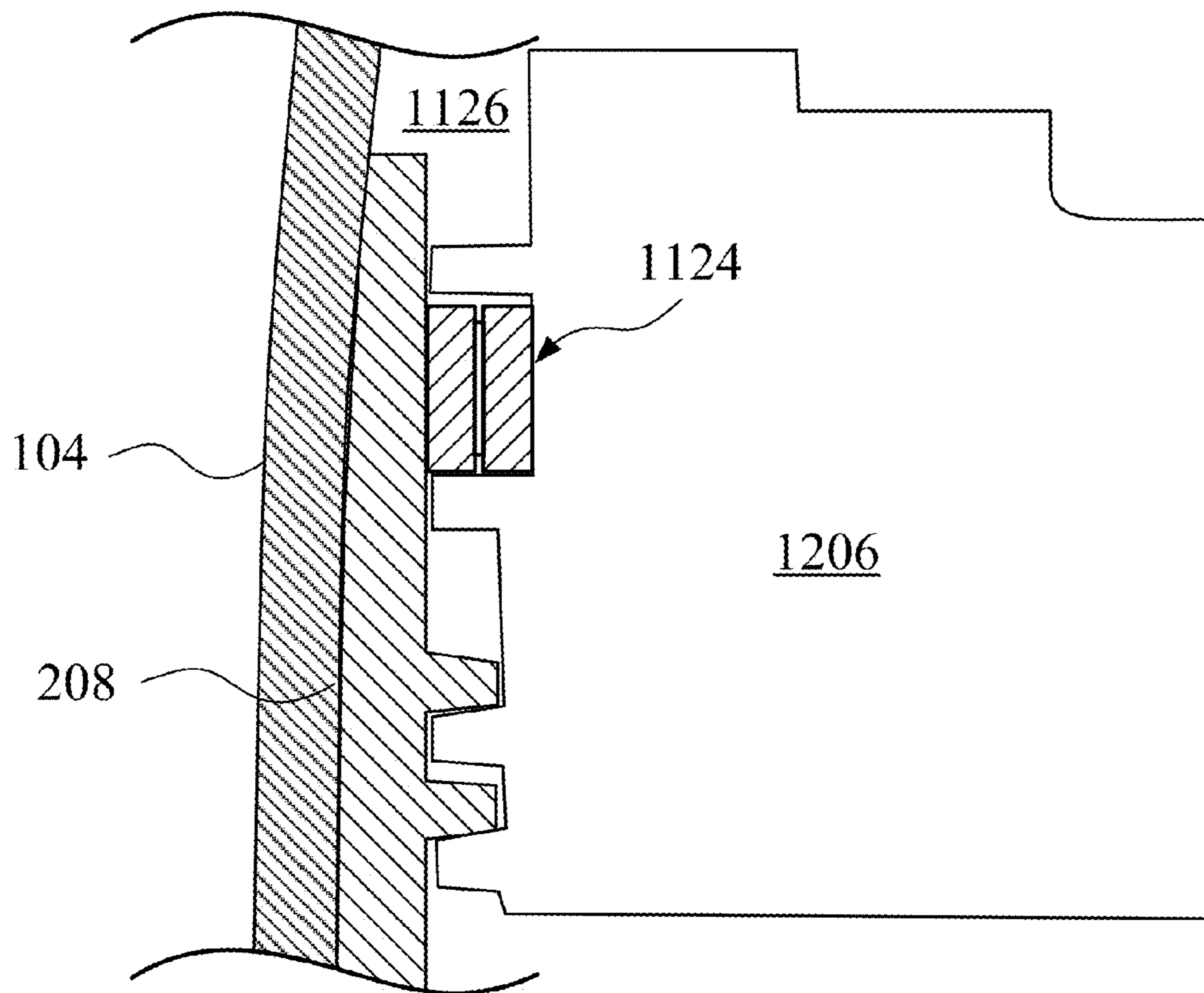


FIG. 12C

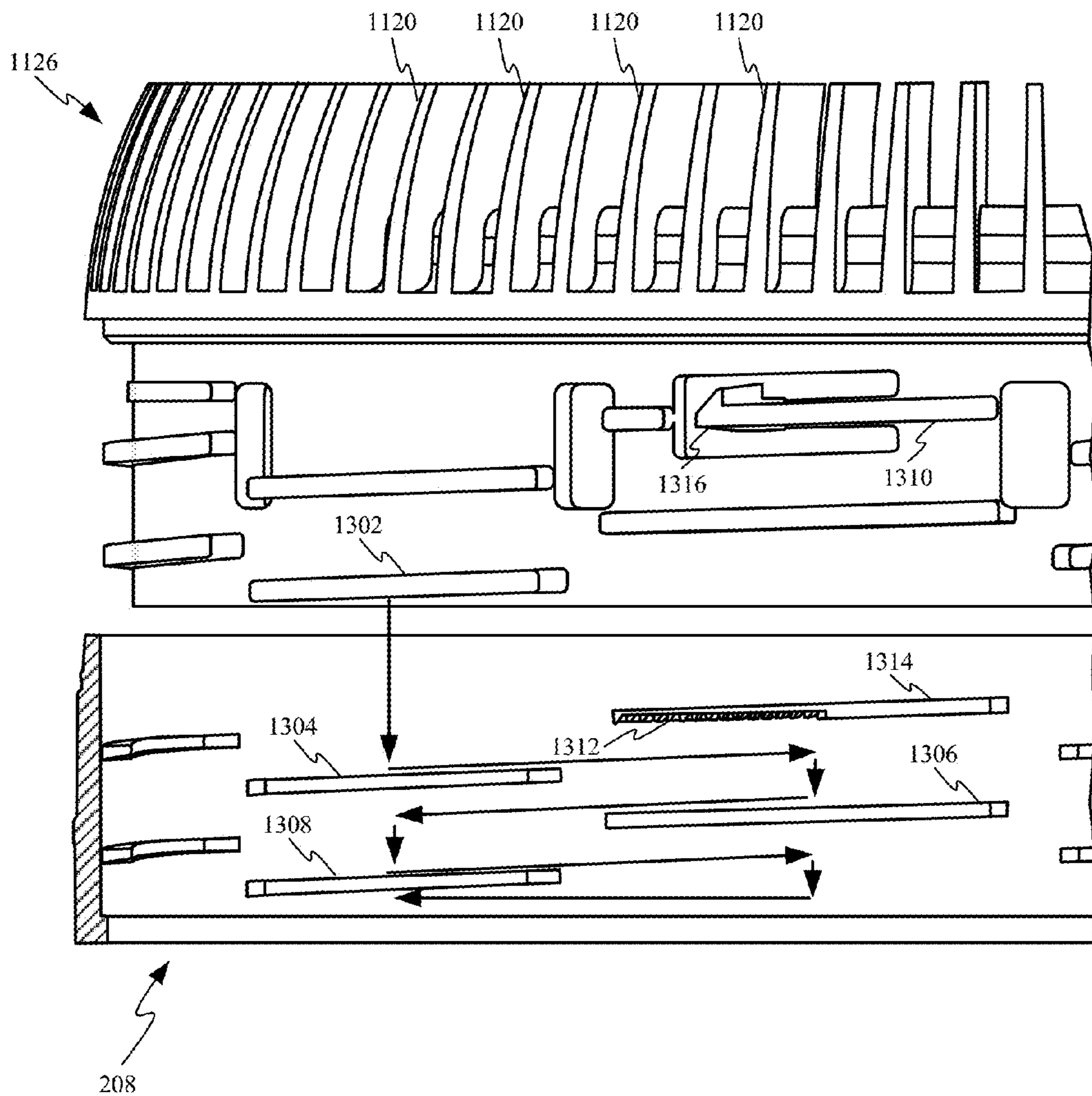


FIG. 13A

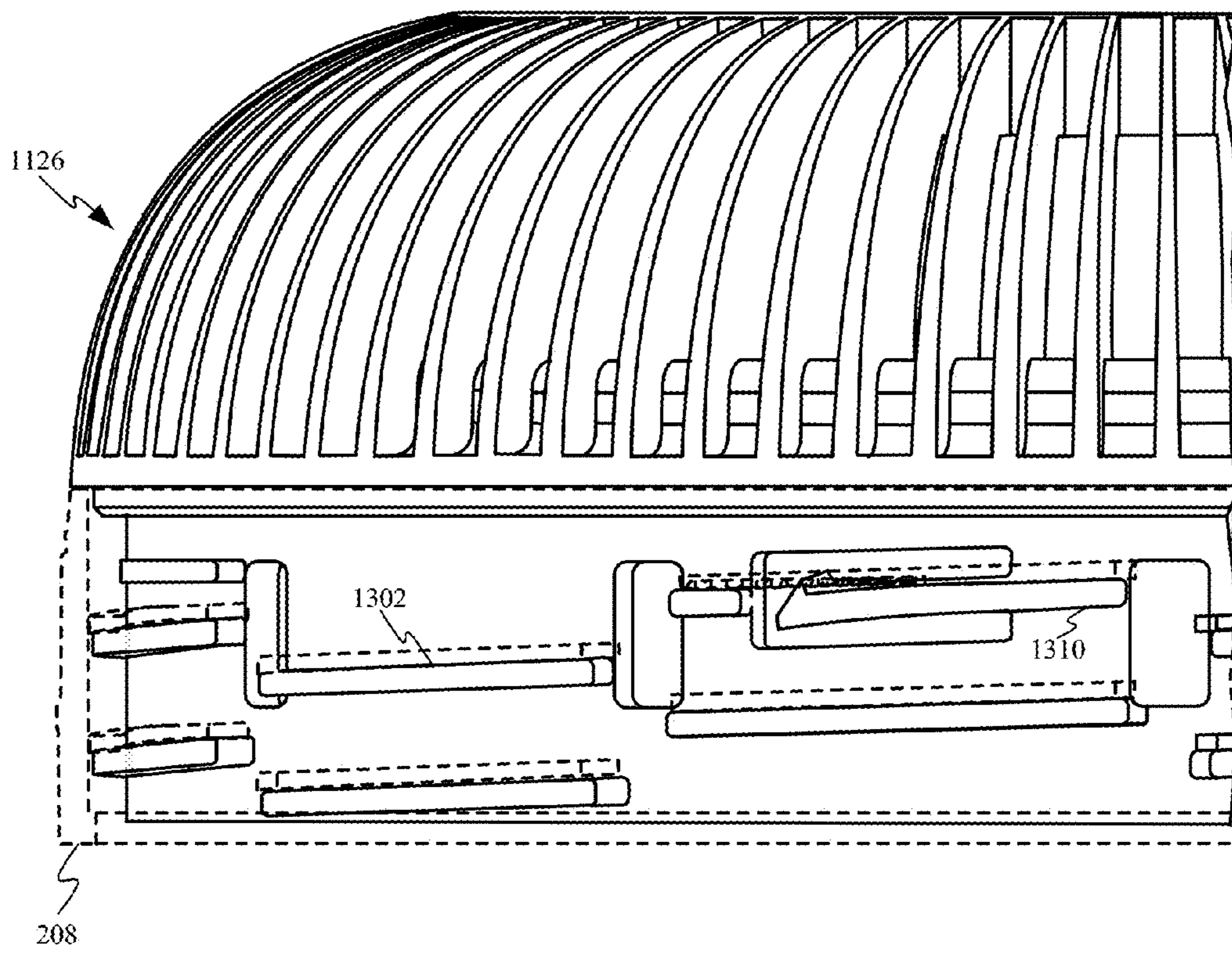


FIG. 13B

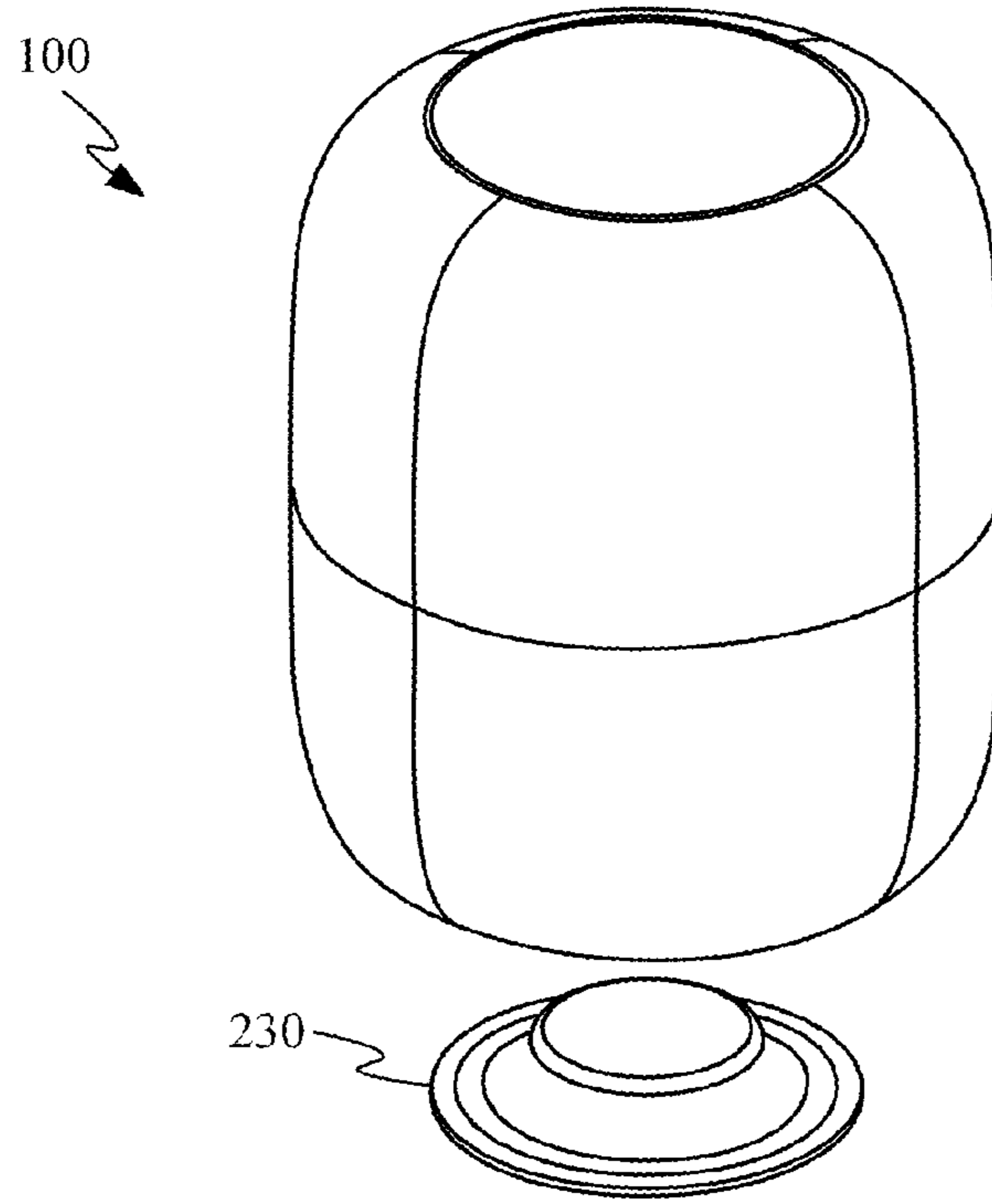


FIG. 14A

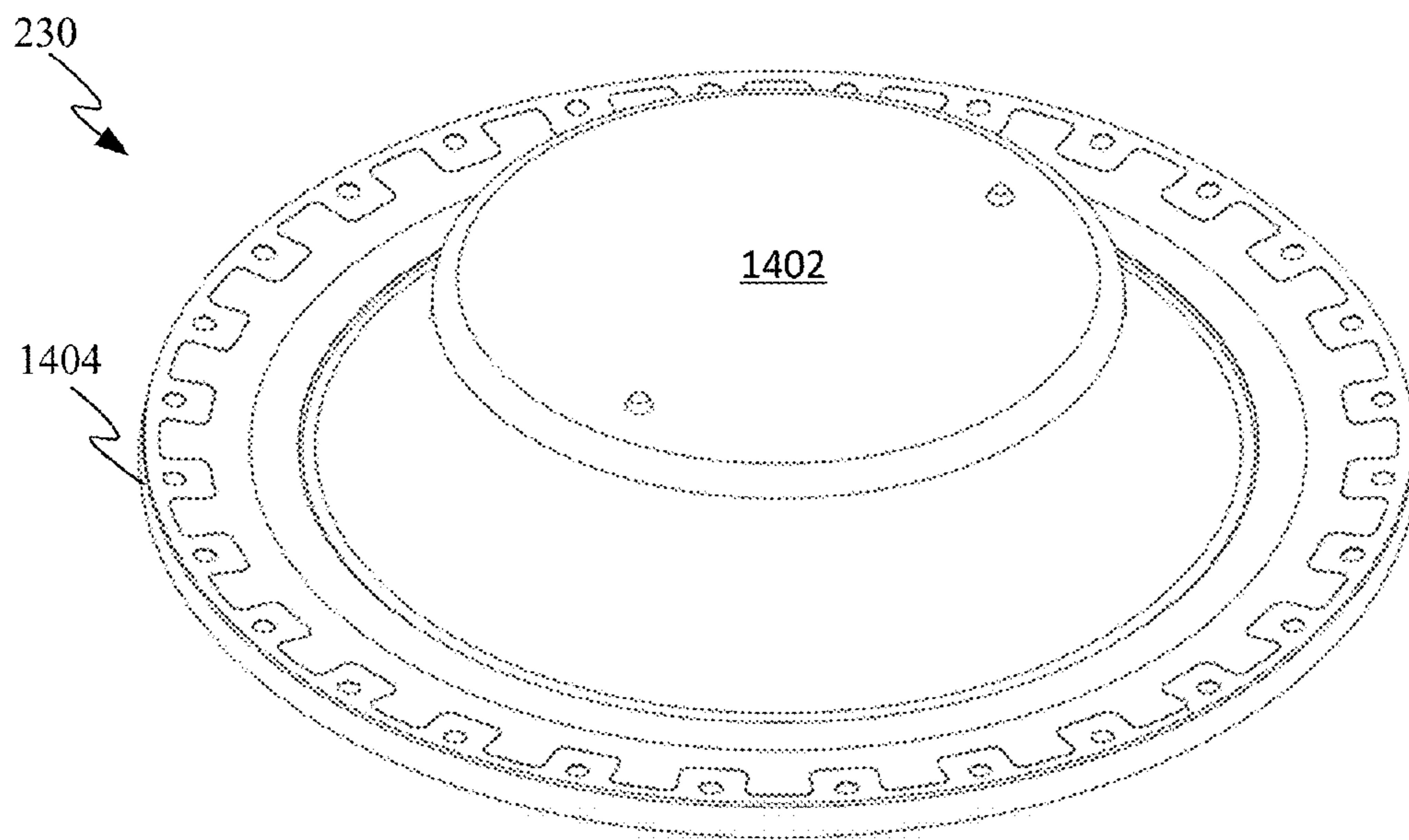


FIG. 14B

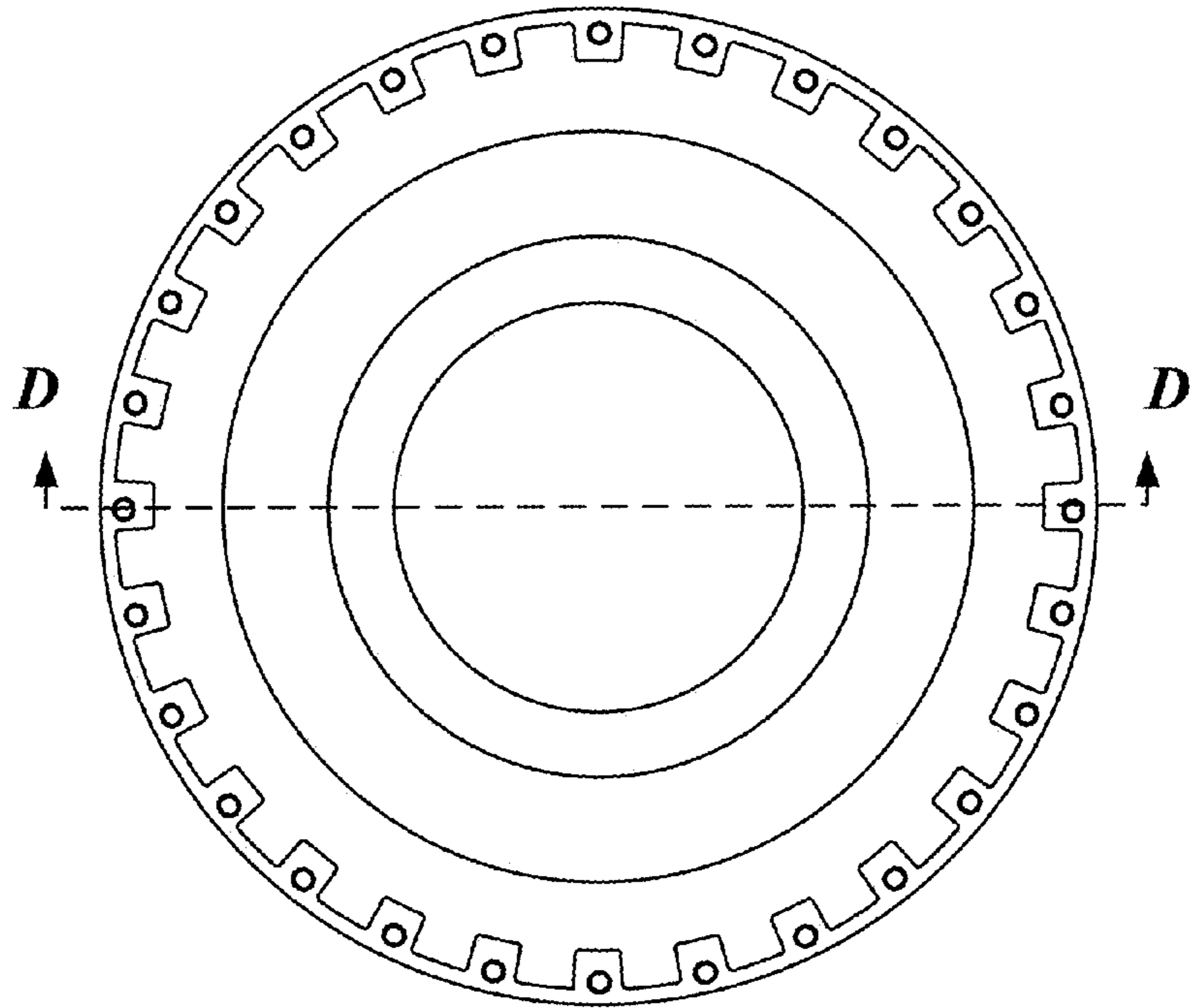


FIG. 14C

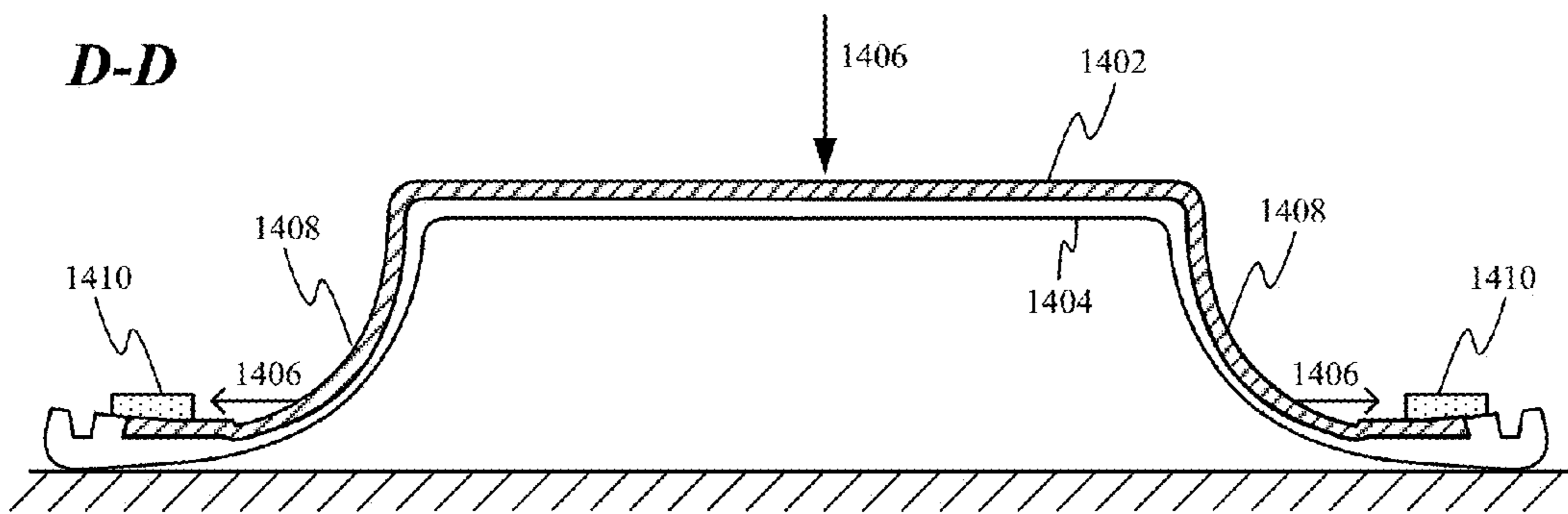


FIG. 14D

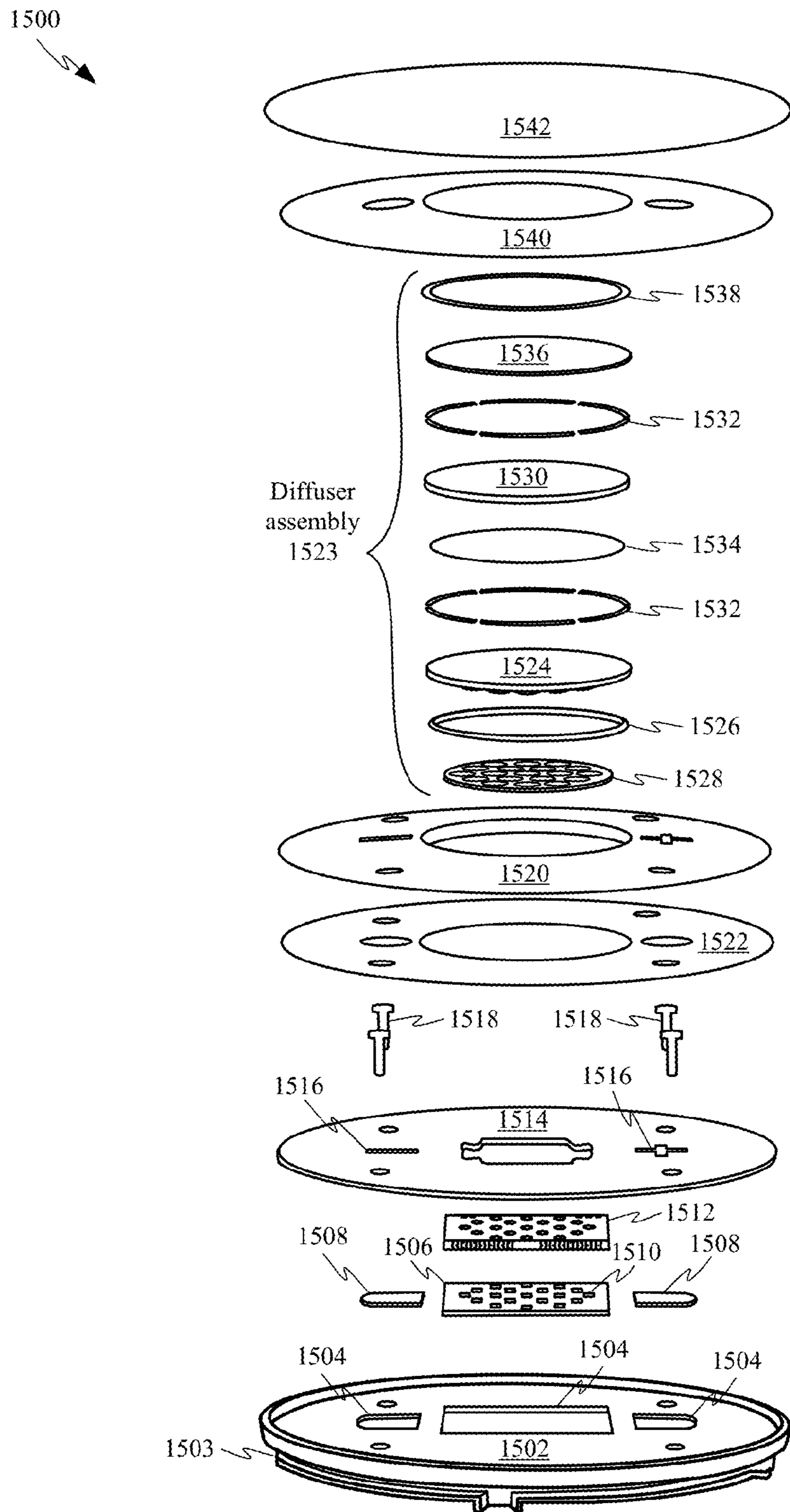


FIG. 15

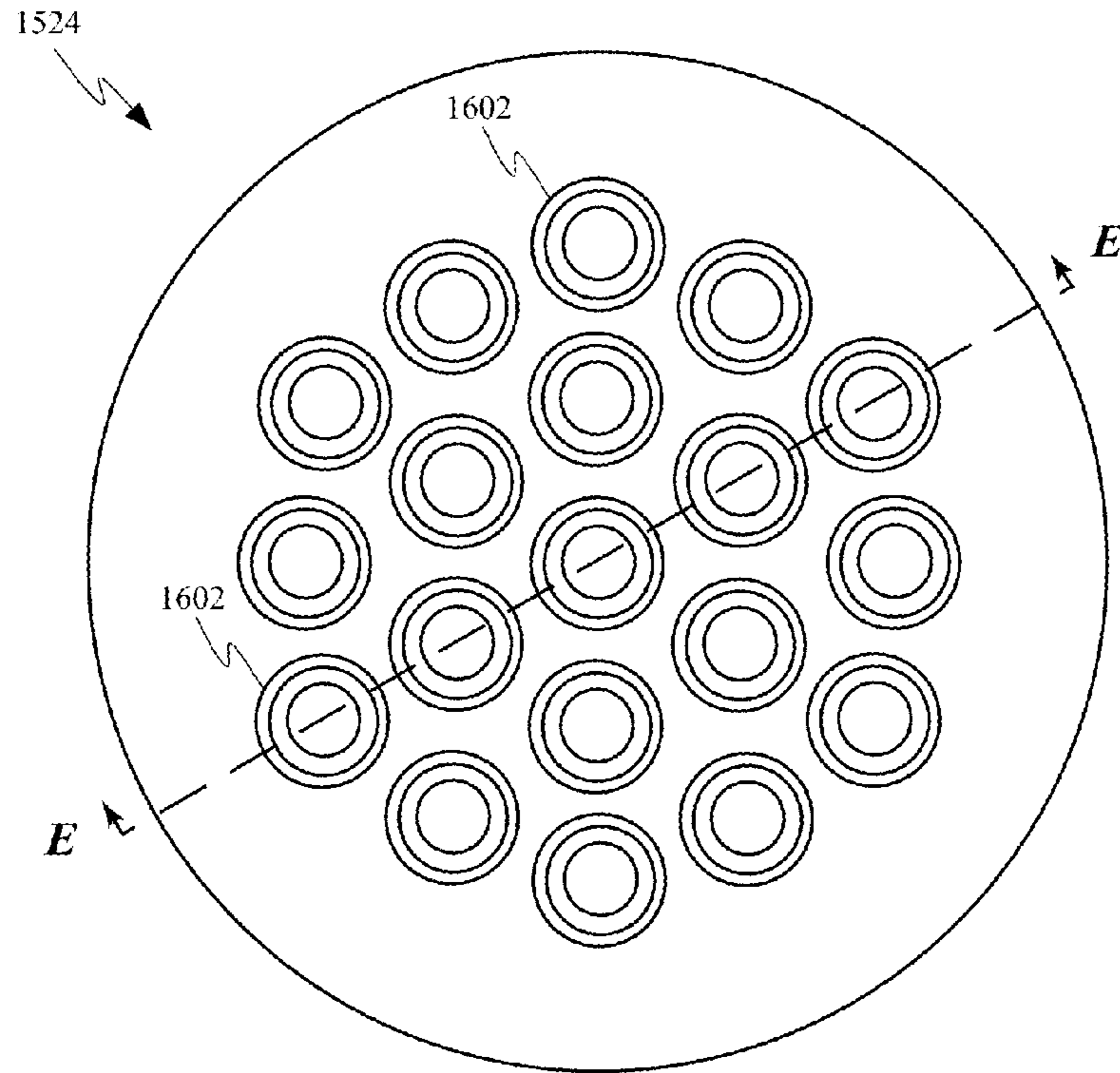


FIG. 16A

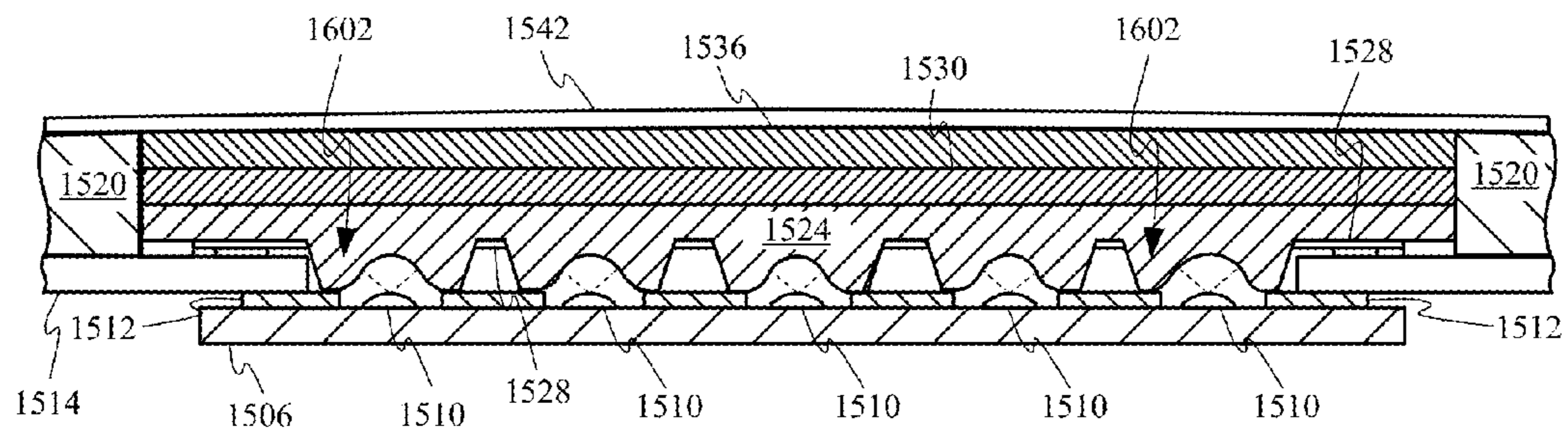


FIG. 16B

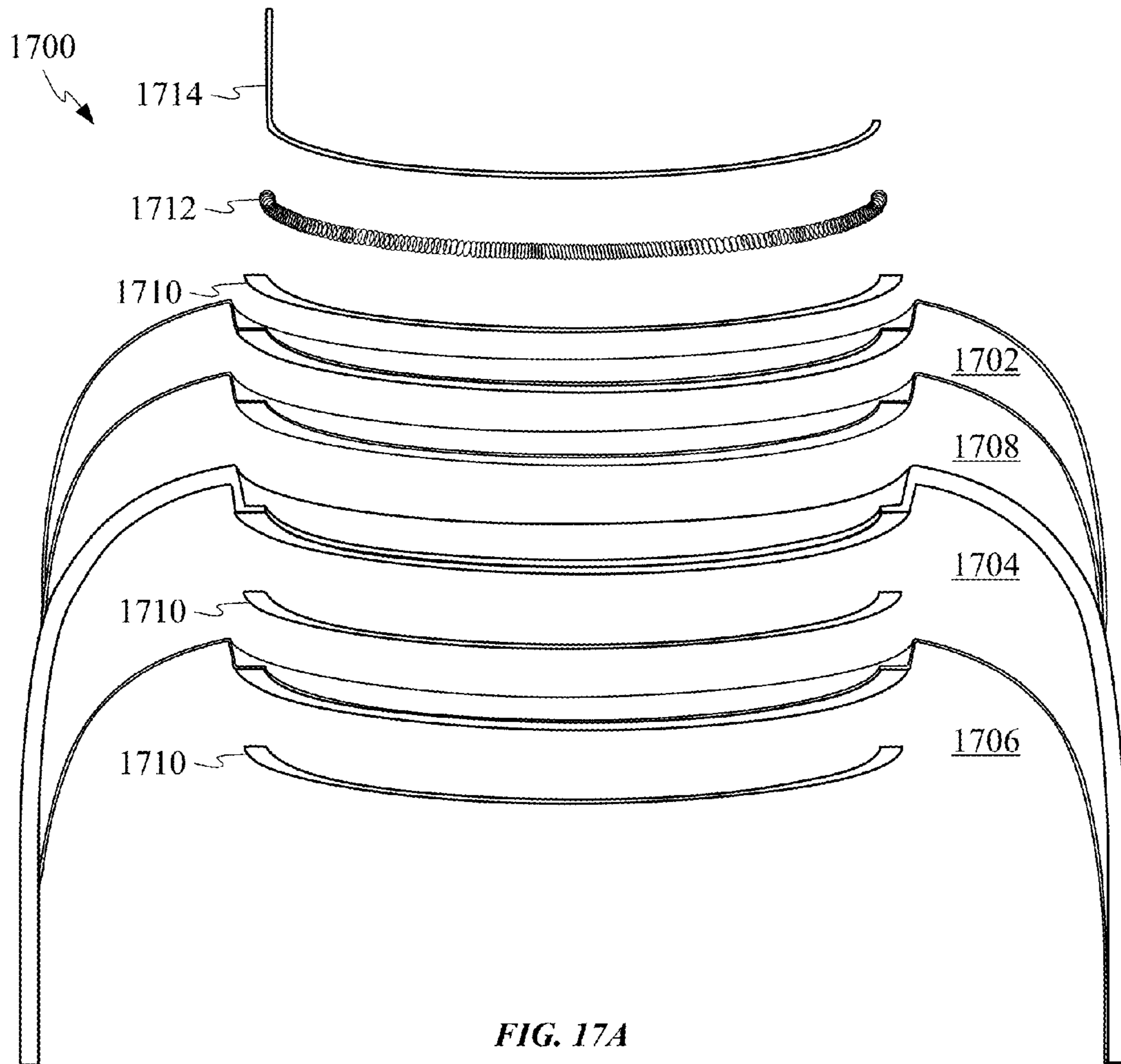


FIG. 17A

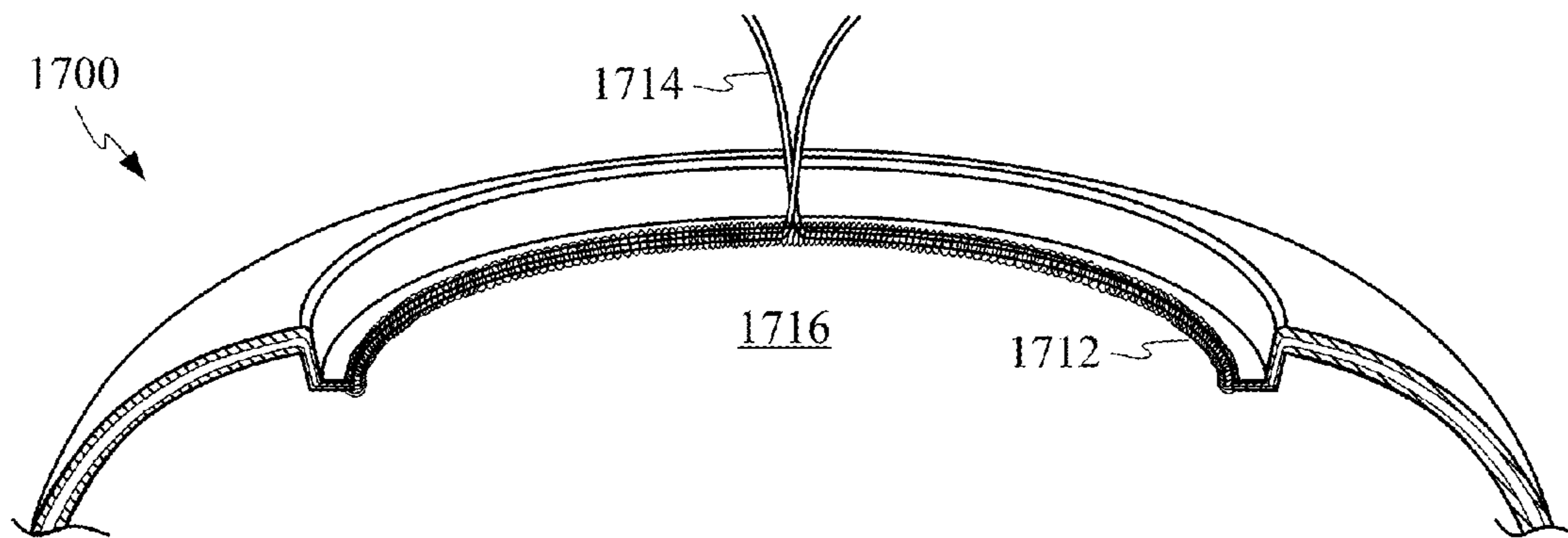


FIG. 17B

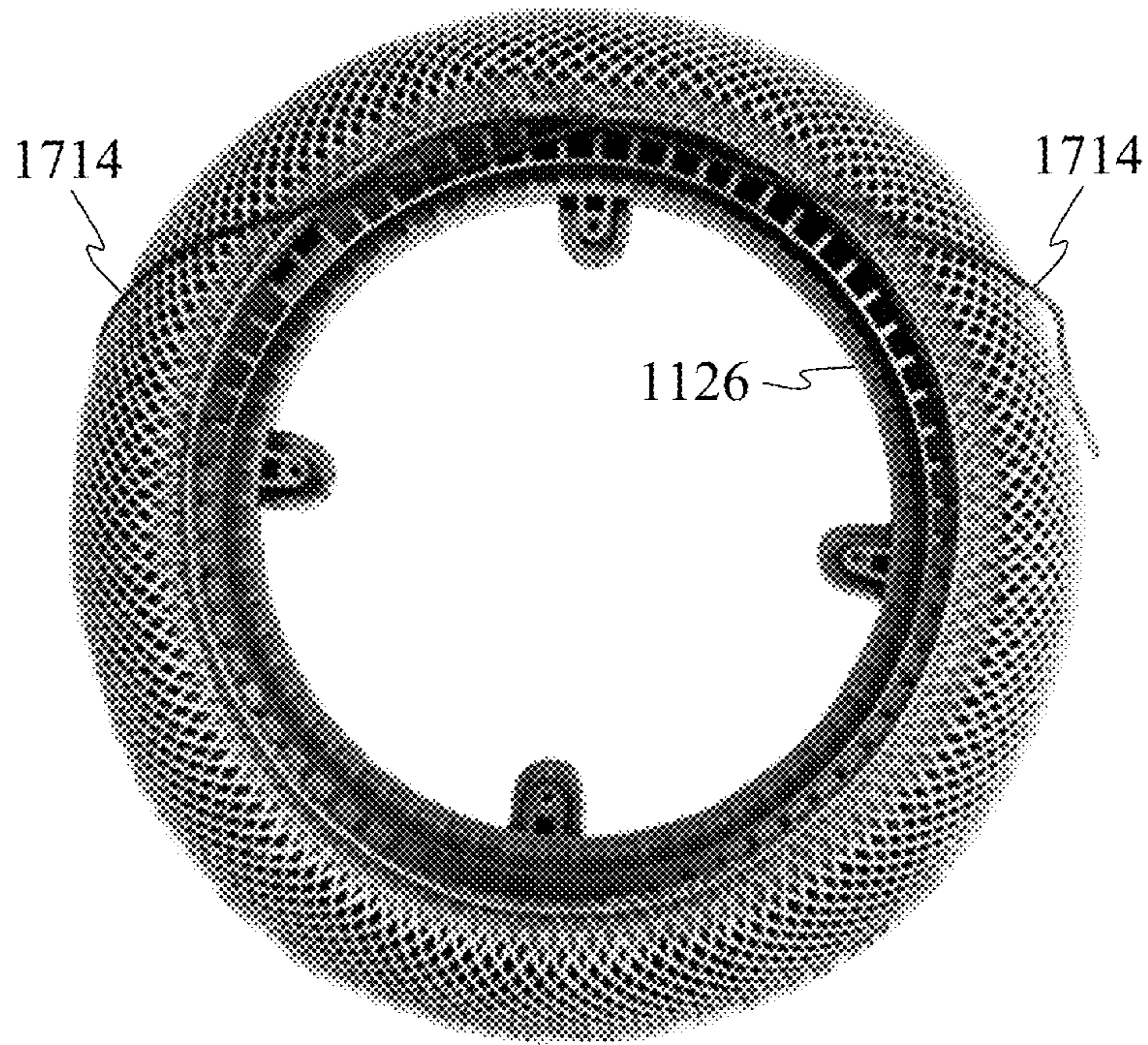


FIG. 17C

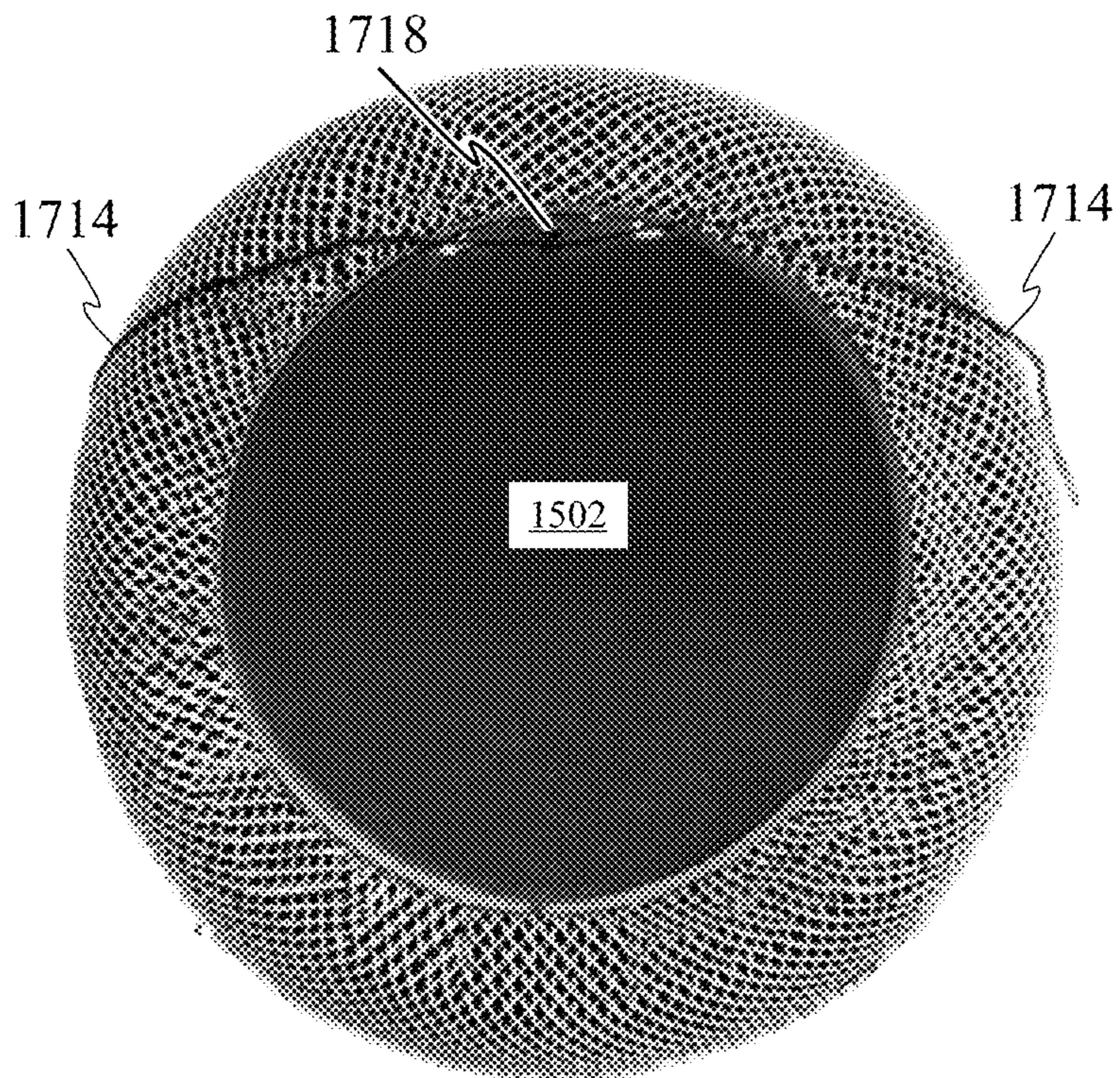


FIG. 17D

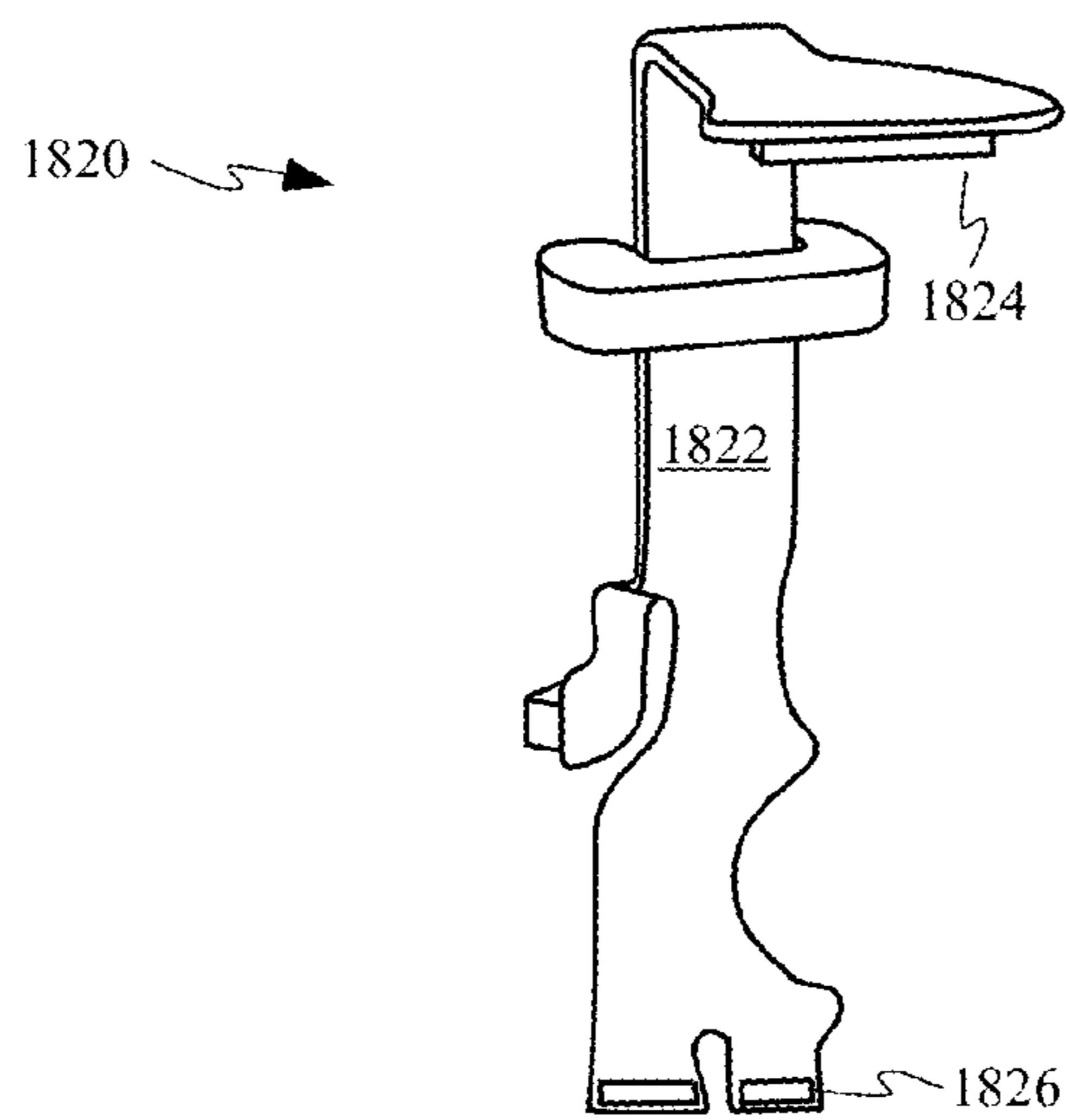
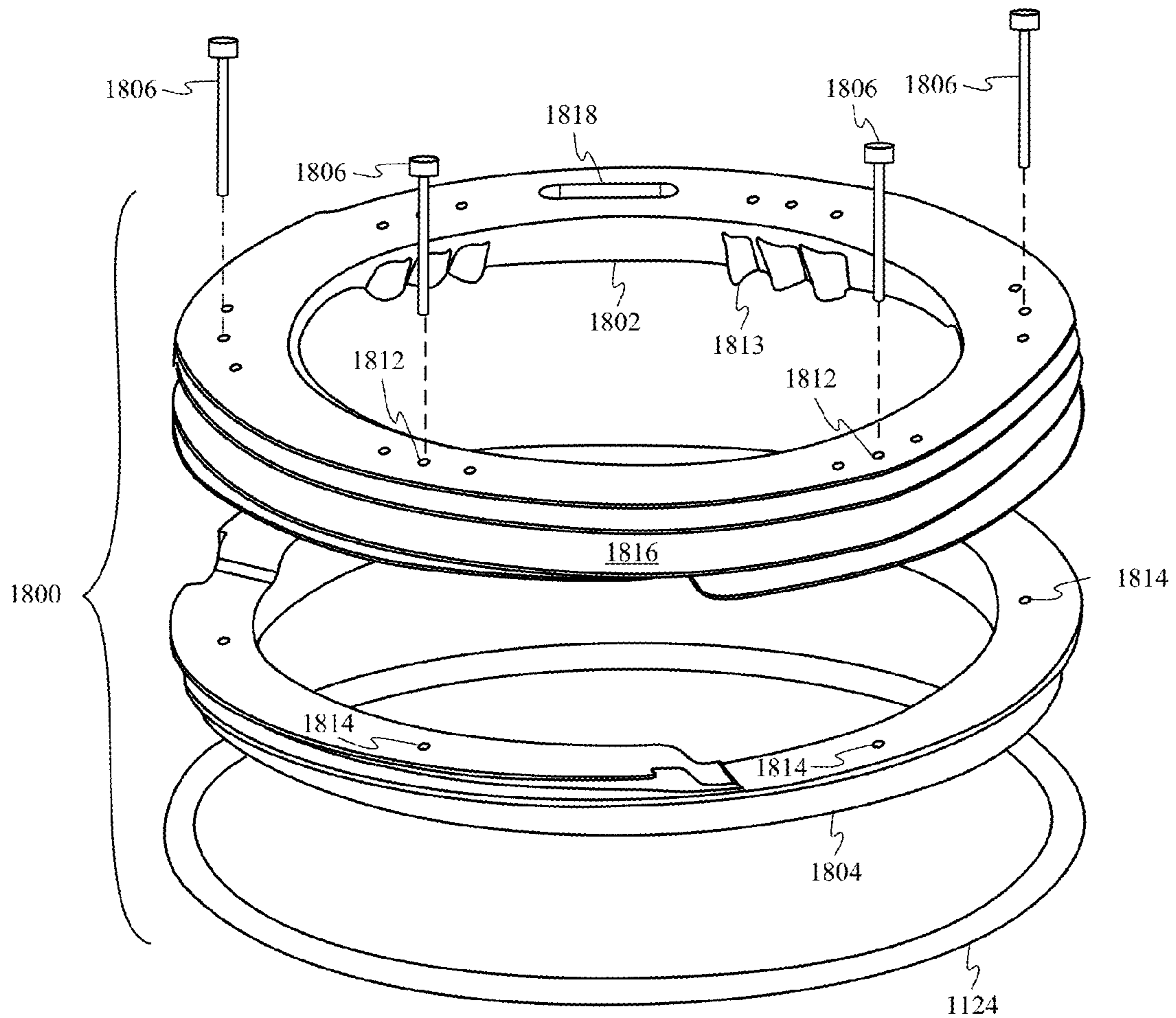


FIG. 18

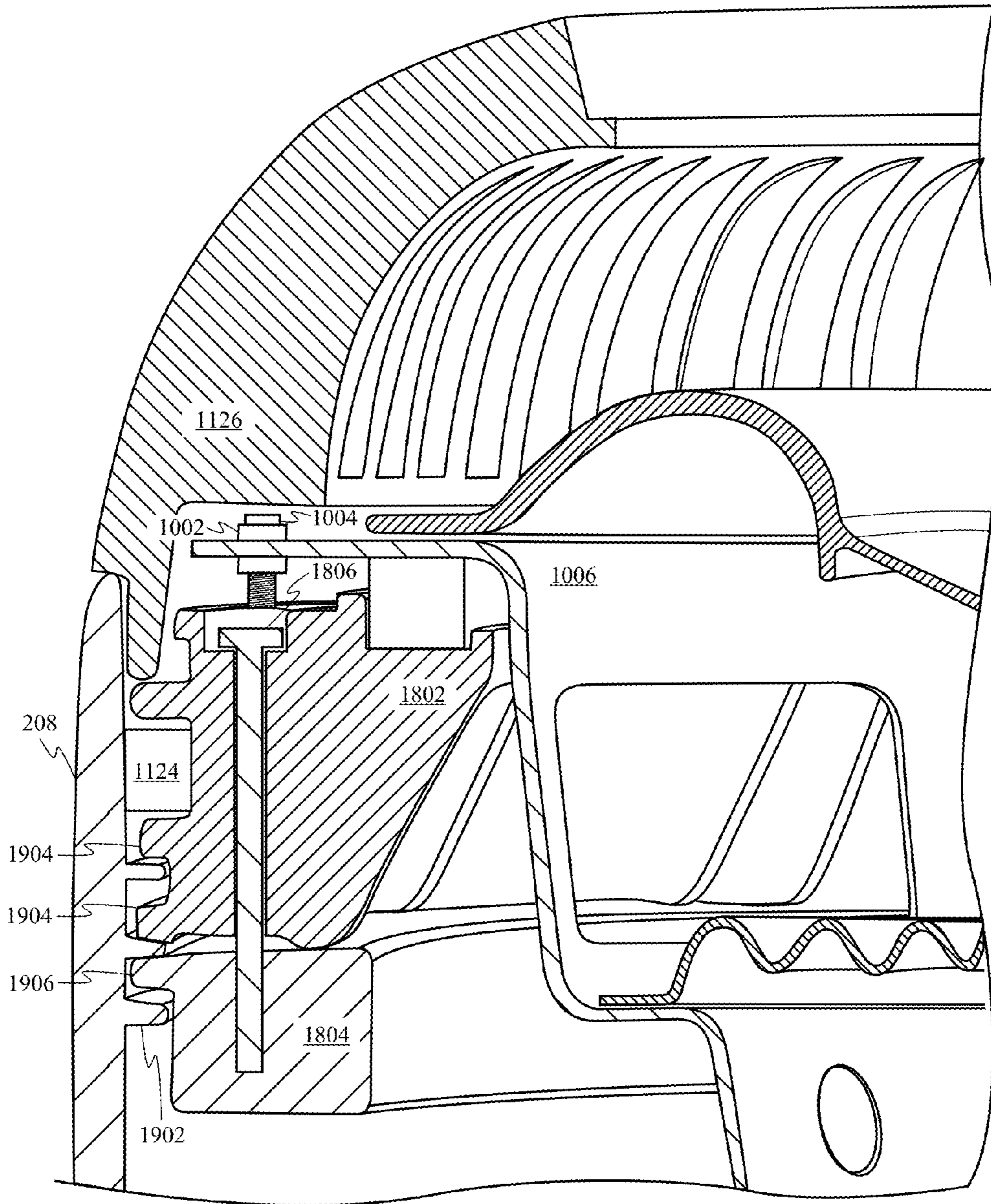


FIG. 19

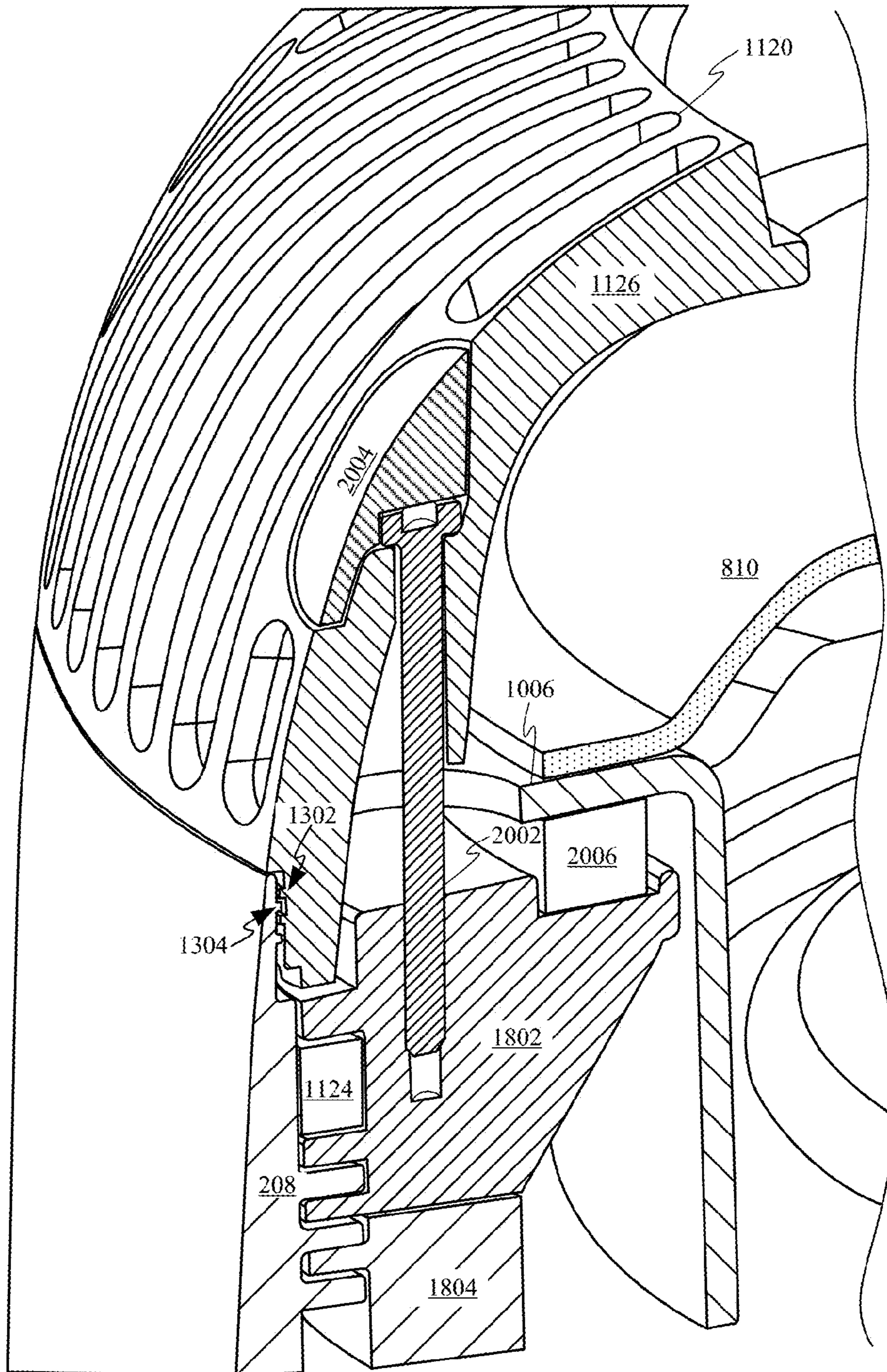


FIG. 20

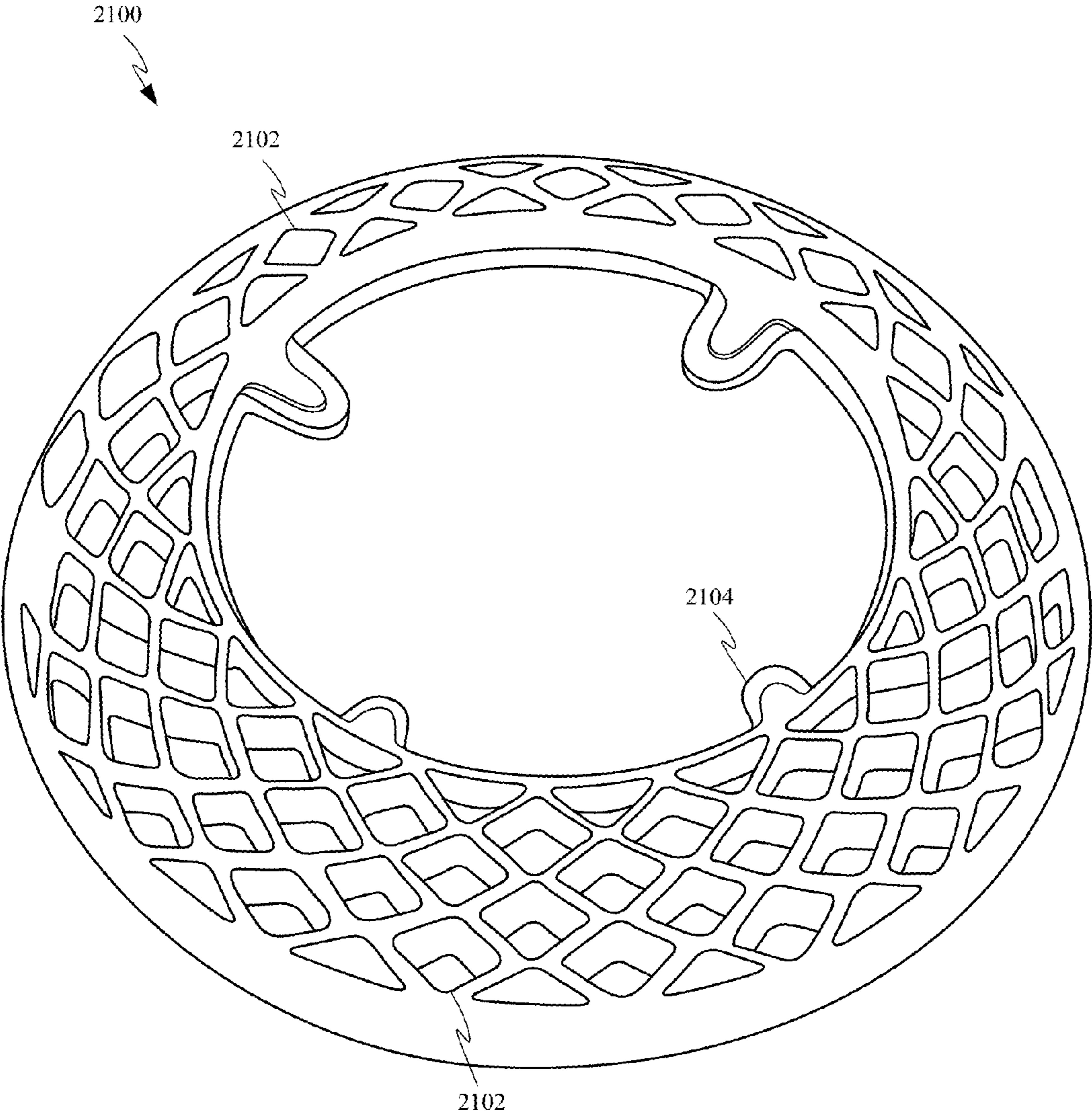


FIG. 21

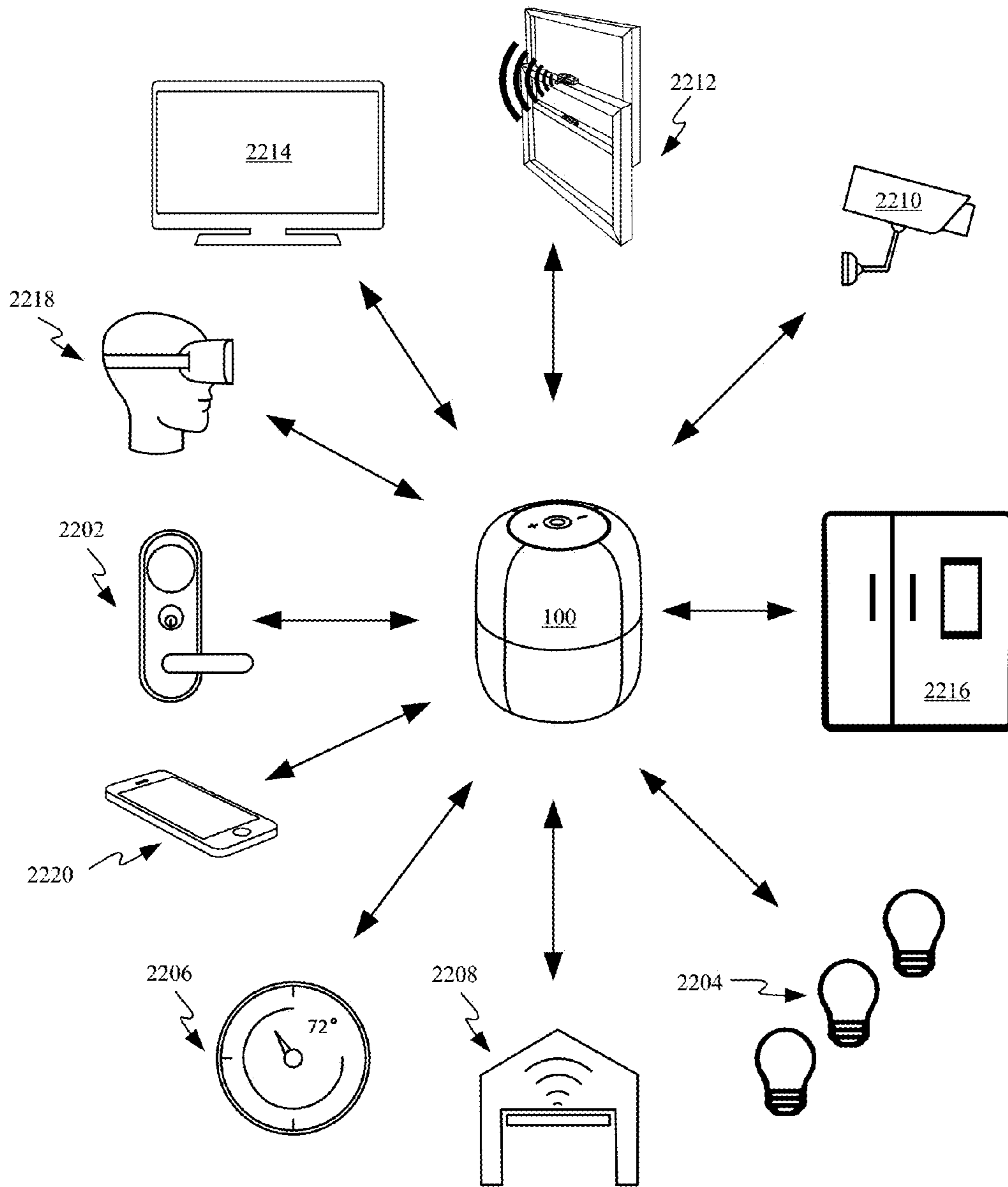


FIG. 22

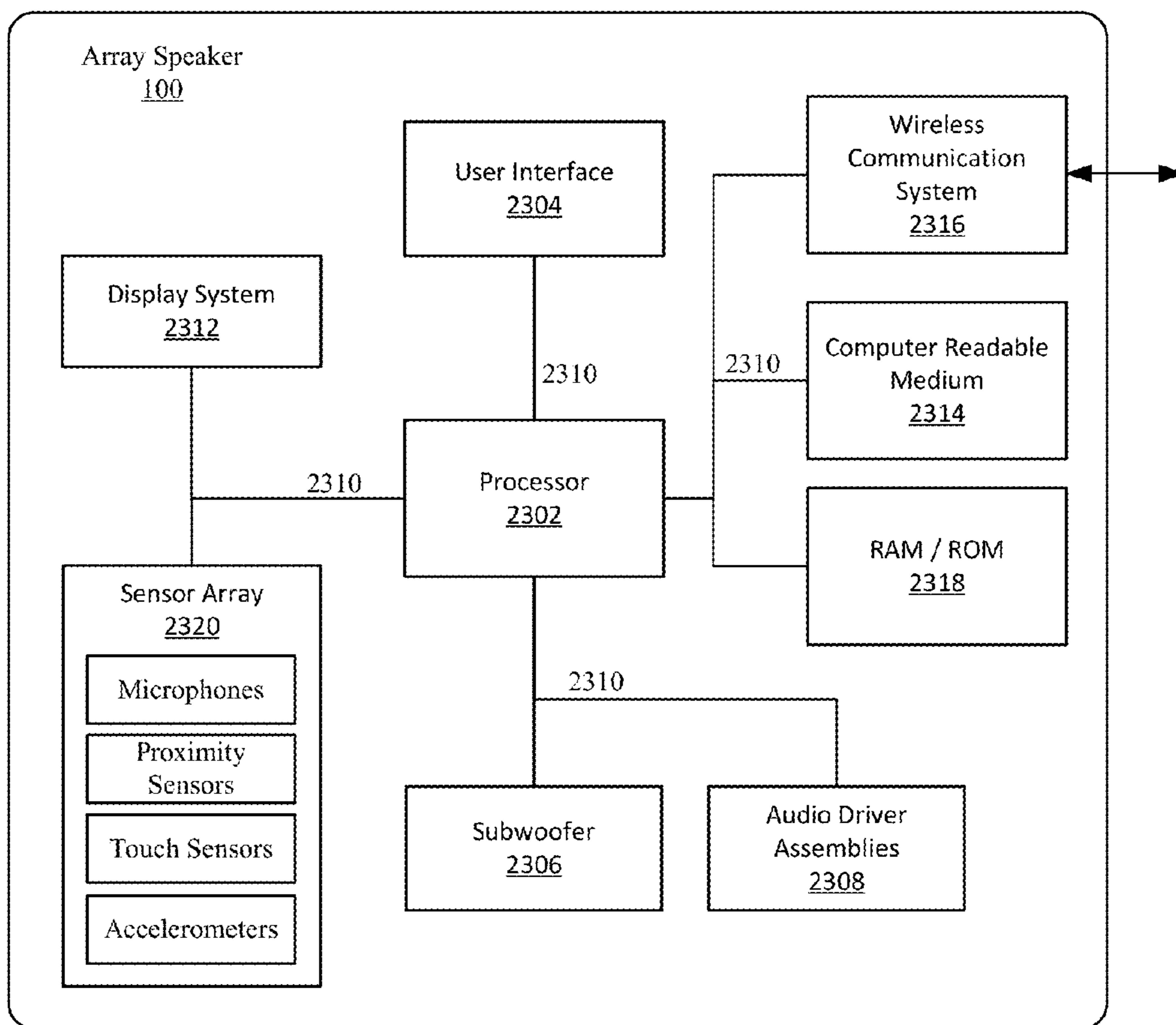


FIG. 23

AUDIO DRIVER AND POWER SUPPLY UNIT ARCHITECTURE

Matter enclosed in heavy brackets [] appears in the original patent but forms no part of this reissue specification; matter printed in italics indicates the additions made by reissue; a claim printed with strikethrough indicates that the claim was canceled, disclaimed, or held invalid by a prior post-patent action or proceeding.

CROSS-REFERENCES TO RELATED APPLICATIONS

This application is a continuation of U.S. patent application Ser. No. 15/613,054, filed Jun. 2, 2017, which claims priority to U.S. Provisional Patent Application No. 62/399,165, filed on Sep. 23, 2016, U.S. Provisional Patent Application No. 62/399,229, filed Sep. 23, 2016, U.S. Provisional Patent Application No. 62/399,262 filed on Sep. 23, 2016, U.S. Provisional Patent Application No. 62/399,293 filed on Sep. 23, 2016, U.S. Provisional Patent Application No. 62/399,288 filed on Sep. 23, 2016, and U.S. Provisional Patent Application No. 62/507,007 filed on May 16, 2017. Each of these references is hereby incorporated by reference in its entirety for all purposes. *This application is also a continuation-in-part of U.S. patent application Ser. No. 15/513,955, filed Mar. 23, 2017, which claim priority from International Application No. PCT/US2105/053025, filed Sep. 29, 2015, which claims priority to U.S. Provisional Application No. 62/057,992, filed Sep. 30, 2014.*

FIELD

This disclosure applies generally to speakers. In particular, an array of speakers housed within a cylindrical housing is described.

BACKGROUND

Conventional speakers are generally directional in nature, which can have the effect of leaving dead spots within a room. Often a large array of speakers is distributed around a room to achieve a substantially uniform level of audio performance throughout the room. Conventional speakers can also be subject to vibratory excursions in certain playback regimes. For example, a subwoofer can cause substantial buzzing and or motion of a speaker depending on the volume and frequency of the music being played back. Consequently, improvements in speaker design are desirable.

SUMMARY

This disclosure describes various embodiments that relate to an electronic device that incorporates a speaker or array of speakers.

An array speaker is disclosed and includes the following: an axisymmetric device housing; a number of audio driver assemblies distributed radially about an interior of the axisymmetric device housing; and a power supply unit positioned between two or more of the audio driver assemblies.

An electronic device is disclosed and includes a device housing; and audio driver assemblies arranged in a circular configuration within the device housing, diaphragms of each audio driver assembly arranged so that audio waves gener-

ated by the diaphragms are initially oriented toward a central region of the circular configuration.

An electronic device is disclosed and includes an axisymmetric housing; an array of audio driver assemblies disposed within the axisymmetric housing at a regular radial interval, each of the audio driver assemblies being configured to generate audio waves that exit the substantially axisymmetric housing through acoustic vents defined by a downward facing end of the axisymmetric housing.

An electronic device is disclosed and includes a subwoofer having a diaphragm, a coil coupled to the diaphragm and configured to emit a changing magnetic field, and a permanent magnet configured to interact with the changing magnetic field generated by the coil to move the diaphragm axially, the permanent magnet including lobes protruding radially therefrom.

A speaker is disclosed and includes a device housing, a subwoofer disposed within the device housing and having a diaphragm configured to oscillate in a direction aligned with a longitudinal axis of the device housing, the subwoofer including a permanent magnet comprising a plurality of protrusions distributed at a regular radial interval about the longitudinal axis of the device housing.

An electronic device is disclosed and includes: a device housing; a subwoofer disposed within the device housing and including a permanent magnet having lobes protruding radially therefrom; an audio driver assembly disposed within the device housing; and a capacitor configured to supply power to the audio driver assembly and positioned between two of the lobes.

An audio driver is disclosed and includes the following: a driver housing defining an audio exit opening; a diaphragm disposed within the driver housing; and a phase plug assembly disposed between the diaphragm and the audio exit opening. The diaphragm and phase plug assembly separate a front volume from a back volume and a portion of the back volume extends toward the audio exit opening and past the diaphragm.

An array speaker is disclosed and includes the following: a first audio driver assembly disposed between a second audio driver assembly and a third audio driver assembly, the first audio driver assembly comprising: a driver housing defining an audio exit opening; a diaphragm disposed within the driver housing; and a phase plug disposed between the diaphragm and the audio exit opening, the phase plug separating a front volume from a back volume, a portion of the back volume extending toward the audio exit opening and past the diaphragm.

An audio driver assembly is disclosed and includes the following: a driver housing defining an audio exit opening; a phase plug separating a front volume from a back volume, a portion of the back volume extending toward the audio exit opening; a U-cup engaged with the phase plug to define an interior volume; a diaphragm disposed within the interior volume and coupled with an electrically conductive coil configured to generate a changing magnetic field; and a driver magnet coupled to the U-cup and configured to interact with the changing magnetic field. The interaction between the changing magnetic field and a portion of a magnetic field disposed within an air gap positioned between a top plate and an interior-facing wall of the U-cup causes the diaphragm to oscillate within the interior volume.

A speaker is disclosed and includes the following: a device housing; a user interface assembly disposed at an end of the device housing; a printed circuit board (PCB) secured to an interior facing surface of the user interface assembly;

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and a subwoofer configured to push air toward the PCB during operation of the speaker.

An electronic device is disclosed and includes the following: a device housing; a user interface assembly; a printed circuit board (PCB) secured to an interior facing surface of the user interface assembly; and an audio component having a diaphragm configured to push air toward the PCB during operation of the electronic device.

An array speaker is disclosed and includes the following: an array of audio driver assemblies arranged in a circular geometry; a speaker housing defining an audio exit channel for each of the audio driver assemblies; and a foot supporting the speaker housing, the foot having a smaller diameter than the speaker housing, a surface of the foot cooperating with a surface of the speaker housing to define an outlet region for each of the audio exit channels, a first distance from a periphery of the foot to an outer edge of the speaker housing being greater than a second distance from a distal end of the foot to a downward facing surface of the speaker housing.

An electronic device is disclosed and includes the following: an axisymmetric device housing; audio driver assemblies disposed within the axisymmetric device housing; and a foot having a substantially smaller diameter than the axisymmetric device housing, the foot cooperating with a downward-facing surface of the axisymmetric device housing to define an audio exit region shaped to spread audio waves generated by the audio driver assemblies as the audio waves exit the axisymmetric device housing.

An electronic device is disclosed and includes the following: a device housing comprising an upper housing component and a lower housing component; an annular support member engaged with threading defined by the lower housing component; a subwoofer coupled to the annular support member; and a fastener extending through an opening defined by the upper housing component and engaging the annular support member.

An electronic device is disclosed and includes the following: a device housing, including first and second housing components cooperating to define an interior volume; an annular support member disposed within the interior volume and engaged with threading arranged along an interior-facing surface of the first housing component; and an audio component coupled to the annular support member, the audio component comprising a diaphragm configured to oscillate in a direction aligned with the longitudinal axis of the device housing.

A speaker device is disclosed and includes the following: an axisymmetric device housing comprising an upper housing component and a lower housing component coupled to the upper housing component; a support structure engaged with threading disposed along an interior facing surface of the lower housing component, the support structure including: a first annular member, and a second annular member coupled to the first annular member; a subwoofer coupled to the support structure and filling a central opening defined by the support structure; and a fastener extending through an opening defined by the upper housing component and engaging the annular support member.

A user interface is disclosed and includes the following: an exterior surface configured to receive touch inputs; light sources configured to direct light toward the exterior surface and arranged in a lens pattern; and a single piece lens array disposed between the light sources and the exterior surface, the lens array including lenses arranged in the lens pattern,

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each of the lenses protruding from a transparent substrate and having a surface facing a respective one of the light sources.

An electronic device is disclosed and includes the following: a device housing; and a user interface arranged along an exterior surface at a first end of the device housing, the user interface including: light sources configured to illuminate a region of the exterior surface, and a single piece lens array, including: lenses arranged in a lens pattern, each of the lenses protruding from a transparent substrate and having a concave surface facing a respective one of the light sources.

A speaker device is disclosed and includes the following: a device housing; a speaker driver assembly disposed within the device housing; and a user interface, including: a cosmetic surface configured to receive touch input and arranged along an exterior surface of the device housing; light sources configured to emit light toward the cosmetic surface; and a lens array disposed between the light sources and the cosmetic surface, the lens array including lenses arranged in a lens pattern, each of the lenses protruding from a transparent substrate and having a concave surface facing a respective one of the light sources.

Other aspects and advantages of the invention will become apparent from the following detailed description taken in conjunction with the accompanying drawings which illustrate, by way of example, the principles of the described embodiments.

BRIEF DESCRIPTION OF THE DRAWINGS

The disclosure will be readily understood by the following detailed description in conjunction with the accompanying drawings, wherein like reference numerals designate like structural elements, and in which:

FIG. 1 shows a perspective view of an array speaker;

FIG. 2A shows a cross-sectional view of the array speaker that includes only components disposed within the lower third of the array speaker;

FIG. 2B shows a simplified view of one side of the array speaker and an associated audio exit channel;

FIG. 2C shows an internal schematic view of the audio exit channel associated with one of the audio drivers of the array speaker and how audio waves are propagated through the audio exit channel;

FIGS. 3A-3B show cross-sectional views of the array speaker in accordance with section lines A-A and B-B of FIG. 2, respectively;

FIG. 4 shows a perspective view of a number of driver assemblies;

FIG. 5A shows a perspective view of a rear portion of a driver assembly;

FIGS. 5B-5C show cross-sectional views of different embodiments in which a fastener is used as a portion of an electrically conductive pathway;

FIG. 6 shows an exploded view of a driver assembly;

FIG. 7 shows a cross-sectional view of the driver assembly;

FIG. 8 shows a cross-sectional view of the array speaker that includes only components within a central portion of the array speaker;

FIG. 9A shows a subwoofer that includes a magnet, which extends radially from the subwoofer;

FIG. 9B shows the subwoofer depicted in FIG. 9A and a number of capacitors arranged around the subwoofer;

FIG. 9C shows a subwoofer with a magnet having a number of protruding lobes;

FIG. 9D shows the subwoofer depicted in FIG. 9C and a number of capacitors arranged between the lobes of the magnet;

FIG. 10A shows a perspective view of a subwoofer with a lip having multiple notches configured to receive fasteners;

FIG. 10B shows a grommet suitable for mounting the subwoofer;

FIG. 11A shows an exploded view of a convex user interface;

FIG. 11B shows a cross-sectional view of the convex user interface assembled;

FIG. 11C shows a cross-sectional view of the convex user interface installed within an array speaker;

FIGS. 12A-12C show various views of a seal for sealing a first interior portion of the device from a second interior portion of the device;

FIGS. 13A-13B show how an upper housing component can be attached to a lower housing component; and

FIGS. 14A-14D show various views of a cantilevered foot;

FIG. 15 shows an exploded view of another convex user interface;

FIG. 16A shows a downward facing surface of a lens array depicted in FIG. 15;

FIG. 16B shows a cross-sectional side view of a portion of the convex user interface depicted in FIG. 15 that includes the lens array in accordance with section line E-E depicted in FIG. 16A;

FIG. 17A shows a cross-sectional, exploded view of an expandable opening defined by one end of an exterior cosmetic fabric;

FIG. 17B shows a cross-sectional view of the exterior cosmetic fabric fully adhered together and how both ends of a drawstring can protrude from the same radial position of the exterior cosmetic fabric;

FIGS. 17C-17D show top views of the exterior cosmetic fabric installed around an upper housing component of the array speaker;

FIG. 18 shows an exploded view of a halo assembly;

FIG. 19 shows a partial cross-sectional view of a speaker device with the halo assembly installed therein;

FIG. 20 shows how an upper housing component can be secured to the halo assembly by a fastener;

FIG. 21 shows a perspective view of an alternative upper housing component defining diamond shaped vents;

FIG. 22 shows a diagram indicating different types of connected electronics that can communicate and/or interact with array speaker; and

FIG. 23 shows a block diagram illustrating communication and interoperability between various electrical components of an array speaker.

DETAILED DESCRIPTION

Representative applications of methods and apparatus according to the present application are described in this section. These examples are being provided solely to add context and aid in the understanding of the described embodiments. It will thus be apparent to one skilled in the art that the described embodiments may be practiced without some or all of these specific details. In other instances, well known process steps have not been described in detail in order to avoid unnecessarily obscuring the described embodiments. Other applications are possible, such that the following examples should not be taken as limiting.

In the following detailed description, references are made to the accompanying drawings, which form a part of the

description and in which are shown, by way of illustration, specific embodiments in accordance with the described embodiments. Although these embodiments are described in sufficient detail to enable one skilled in the art to practice the described embodiments, it is understood that these examples are not limiting; such that other embodiments may be used, and changes may be made without departing from the spirit and scope of the described embodiments.

Speaker configurations tend to be overly large when high quality audio playback is desired and the audio output can be very directional in nature. This often requires a user to be positioned in one particular location to get a desired quality level of audio content generated by the speakers. For example, a multi-channel speaker setup could require speakers to be mounted in multiple different corners of a room to achieve a substantially uniform distribution of sound within the room.

One way to reduce the size of a speaker configuration and simplify speaker setup while maintaining an even distribution of sound within a room, is to package multiple mid to high frequency drivers into a single housing. The drivers can be distributed within the speaker device so that audio exit channels associated with the drivers are distributed at a regular radial interval along a periphery of the speaker device. In some embodiments, beamforming techniques can be applied to improve audio performance by, adjusting audio exiting from adjacent audio exit openings in order to generate constructively interference. In one particular embodiment, the drivers can be positioned in a circular arrangement within a cylindrical housing to achieve an even radial distribution of sound. Destructive interference caused by reflections from the support surface on which the device is positioned can be prevented by orienting the audio exit openings next to the support surface.

In some embodiments, the size of the speaker device can be reduced by packaging the various internal components in close proximity. For example, a power supply unit can be positioned within a central recess defined by a circular arrangement of drivers. In some embodiments, capacitors can be located between a centrally located subwoofer and sidewalls of a device housing of the speaker device. In one particular embodiment, a magnet of the subwoofer can be shaped specifically to accommodate larger capacitors between the subwoofer and the sidewalls of the speaker device.

When the speaker device also includes processing components, heat rejection can also be important. In some embodiments, a main logic board of the speaker device can be positioned in front of the subwoofer so that air pushed by the subwoofer can convectively dissipate heat from heat emitting components of the main logic board.

Packaging a subwoofer within the speaker device can generate vibrations that could cause undesirable buzzing within or motion of the speaker device. In some embodiments, the subwoofer can be attached to mounting brackets within the device housing using a fastener with an elastomeric grommet. The elastomeric grommet can reduce the amount of vibrations imparted to the rest of the speaker device by the subwoofer.

In some embodiments, the mounting brackets can take the form of an annular support structure that is positioned within a device housing of the speaker device by rotating the annular support structure along threading arranged along an interior surface of the device housing. The mounting bracket can be configured to receive fasteners associated with an upper housing component of the device housing and the subwoofer. In some embodiments, the annular support struc-

ture can be formed of two separate rings that are compressed together by a series of fasteners.

In some embodiments, the speaker device can include a touch-based user interface positioned on a top surface of the speaker device. The touch-based user interface can include lighting that illuminates different regions of the touch-based user interface. For example, a central portion of the user interface could be illuminated with a shifting pattern of colors in response to a voice command being received or processed. The shifting pattern of colors could be produced by an array of LEDs embedded beneath an exterior surface of the touch-based user interface. Other illuminated controls on the touch-based user interface can include volume controls. The touch-based user interface can utilize a capacitive touch sensor or other touch sensor suitable for detecting gesture-based touch inputs.

These and other embodiments are discussed below with reference to FIGS. 1-23; however, those skilled in the art will readily appreciate that the detailed description given herein with respect to these figures is for explanatory purposes only and should not be construed as limiting.

FIG. 1 shows a perspective view of an array speaker 100. Array speaker 100 can have an unbroken, aesthetically pleasing exterior surface and a symmetric substantially cylindrical geometry. As used herein, the term “substantially cylindrical geometry” refers to a geometry that is completely cylindrical (i.e., a geometry that includes straight parallel sides and has a circular or oval cross-section) as well as a geometry in which the sides of the top and/or bottom edges are tapered and rounded more than an actual cylinder. Array speaker 100 can also have different geometries. For example, a device housing for array speaker could have many different axisymmetric shapes that allows audio device assemblies to be distributed radially within the device housing. An axisymmetric geometry refers to a shape having symmetry around at least one axis. In the described embodiments, the device housing exhibits an axisymmetric geometry that has symmetry about a longitudinal axis of the device housing. It should also be noted that the term axisymmetric may also be construed to cover shapes that are substantially symmetric about one axis. For example, a small recess or protrusion would not preclude the housing from being described as having an axisymmetric geometry for the purpose of the following description.

An upper portion of array speaker 100 can include a user interface 102. User interface 102 can allow a user to adjust settings for array speaker 100. For example, track selection and changes in volume can be handled by interacting with user interface 102. In some embodiments, user interface 102 can take the form of a touch sensitive surface. User interface 102 can include one or more light sources that illuminate various regions of user interface 102 to help a user interact with user interface 102. A majority of array speaker 100 can be covered by acoustic fabric 104. Acoustic fabric 104 can give array speaker 100 a consistent exterior surface. Some audio exit ports can be concealed by acoustic fabric 104 in a manner that results in minimal impact on the volume and/or quality of audio exiting array speaker 100.

FIG. 2A shows a cross-sectional view of array speaker 100 that includes only components disposed within the lower third of array speaker 100. In particular, the cross-section of one audio driver assembly 202 is depicted. Audio driver assembly 202 can include driver housing 204, which surrounds the audio components making up audio driver assembly 202 and defines a rectangular channel 206 for allowing the audio generated by diaphragm 207 of audio driver assembly 202 to exit driver housing 204. Audio driver

assembly 202 can be fastened to lower housing component 208 by fastener 210. Driver housing 204 can be rotated so that rectangular channel 206 aligns with audio exit channel 212 defined by lower housing component 208. Audio waves 214 exiting audio exit channel 212 pass through acoustic fabric 104 and travel along a supporting surface 216 upon which array speaker 100 rests due to the exit geometry of audio exit channel 212. In some embodiments, acoustic fabric 104 can have a pattern designed to conceal components or features positioned beneath acoustic fabric 104.

FIG. 2A also shows power receptacle 220. Power receptacle 220 can extend between two adjacent audio driver assemblies 202 to route power to various components within array speaker 100. Power receptacle 220 can be electrically coupled to power supply unit 222 by electrically conductive cable 224. In some embodiments, power supply unit 222 can be coupled to power supply board 226, which is in turn coupled to lower housing component 208. Power supply unit 222 extends into a recess defined by audio driver assemblies 202. Audio driver assemblies 202 are distributed radially at a regular interval about array speaker 100. In this way, power supply unit 222 utilizes the space available within the recess defined by audio driver assemblies 202. In some embodiments, amplifier board 228 and the components distributed thereon can also be electrically coupled to power supply unit 222 and power receptacle 220 by way of electrically conductive cable 224. FIG. 2A also depicts cantilevered foot 230, which supports the weight of array speaker 100 atop supporting surface 216. Cantilevered foot 230 can be formed of damping material such as silicone configured to minimize the amount of vibration transferred from array speaker 100 to supporting surface 216. Cantilevered foot 230 can be configured to dissipate forces transmitted in Z as well as moments acting about the X and/or Y axes. The wide aspect and symmetric footprint of cantilevered foot 230 also helps prevent rocking of the speaker due to moments acting about the X and/or Y axes.

FIG. 2B shows an interior cross-sectional view of one side of array speaker 100 depicting diaphragm 207 and an audio exit channel 212 associated with one of audio driver assemblies 202. Various dimensions of the exit of audio exit channel 212 are depicted in millimeters. In particular, the distance between the end of audio exit channel 212 and an edge 229 of a sidewall of lower housing component 208 is about 1.5 times greater than the height of a downward facing surface of array speaker 100 off a support surface supporting array speaker 100. The height of foot 230 just below an outlet region for audio exit channel 212 is about half the distance from supporting surface 216 and the top surface of audio exit channel 212. In some embodiments, a periphery of foot 230 has a thickness that is about $\frac{6}{11}$ of distance 231 between a distal end of foot 230 (or supporting surface 216) and the top surface of audio exit channel 212 at the outlet region. This geometry results in high-frequency audio waves moving around a corner of foot 230 and a corner of the outer edge of the housing in such a way that an even vertical directivity is achieved for both low and high-frequency audio waves. Distance 232 between the edge of lower housing component 208 and the periphery of the foot can be slightly longer than distance 231. This allows the downward facing surface of lower housing component 208 to help shape the audio waves as they travel away from the speaker device. In some embodiments, a ratio of distance 231 to distance 232 can be about 11/15.

FIG. 2C shows an interior schematic view of a lower region of array speaker 100. FIG. 2C depicts how diaphragm 207 associated with one of audio driver assemblies 202 can

be configured to emit audio through a number of vertical slots **233** defined by lower housing component **208**. Dashed lines **234** depicted within rectangular channel **206** and audio exit channel **212** represent sound waves generated by diaphragm **207**. In particular, dashed lines **234** are depicted turning within different regions of rectangular channel **206** and audio exit channel **212**. These channels are shaped deliberately to minimize destructive interference that could negatively affect the quality and/or volume produced by vibration of diaphragm **207**. For example, the turns in the audio channels direct acoustic waves in ways that preserve coherent wave fronts along the length of the audio channels. The shape of the audio channels also helps to direct the audio waves in a direction **236** oriented radially outward and upward, which results in spherically expanding wavefronts moving away from the supporting surface upon which lower housing component **208** rests. While audio waves are depicted two dimensionally by dashed lines **234** it should be appreciated that the audio waves have a three dimensional profile that extends circumferentially within and outside of lower housing component **208**. FIG. 2C also shows how audio waves generated by diaphragm **602** turn in a direction substantially orthogonal to an original direction in which the audio waves are initially generated. For example, audio waves could shift 70 to 80 degrees in direction before exiting driver housing **204** through audio exit opening **710**.

FIG. 3A shows a cross-sectional view of array speaker **100** in accordance with section line A-A of FIG. 2A. Each driver assembly includes an adapter **302** configured to position phase plug **304** within driver housing **204**. Phase plug **304** reduces destructive interference by guiding audio waves from the large surface area of the diaphragm to the small entrance area of the throat of the horn rather than allowing the audio waves to interact destructively near the diaphragm. Phase plug also helps shape the sound waves leaving audio driver assembly **202** to conform to a non-circular or in some cases more rectangular channel **206** and audio exit channel **212**. A periphery of a diaphragm associated with coil assembly **306** is engaged with phase plug **304** as depicted. Coil assembly **306** includes a coil of wire that is affixed to a central portion of the diaphragm and is configured to generate a shifting magnetic field configured to interact with permanent magnet **308**, thereby causing waves to be generated by the diaphragm. When the shifting magnetic field interacts with the field generated by permanent magnet **308** the diaphragm vibrates at a rate suitable for generating audio waves associated with a media file being played back by array speaker **100**. Behind permanent magnet **308** is a support assembly taking the form of a magnetic motor assembly that includes U-cup **310**, top plate **311** and permanent magnet **308**. In addition to providing a surface upon which magnet **308** can be mounted, U-cup **310** directs a magnetic field emitted by magnet **308** to the air gap where the coil is positioned. Behind U-cup **310** is a foam layer **312**, which can be formed from open-cell foam. Foam layer **312** can enhance the audio performance of audio driver assembly **202**. In some embodiments, foam layer **312** can increase the apparent size of a back volume of audio driver assembly **202**. Finally, cap **314** is secured to driver housing **204** to close an opening in the back of audio driver assembly **202**. This rear opening in driver housing **204** can be used to insert the audio components described above within driver housing **204**. FIG. 3A also shows how channels **206** leading out of driver housing **204** can be distributed at a regular radial interval.

FIG. 3B shows a cross-sectional view of array speaker **100** in accordance with section line B-B of FIG. 2. In this

view, top surfaces of driver housings **204** are depicted. Each driver housing has two driver screw terminals **316**. Driver screw terminals **316** can be used to create an electrically conductive pathway between the audio components within driver housing **204** and other components of array speaker **100**.

FIG. 4 shows a perspective view of each of audio driver assemblies **202**. In particular, caps **314** are shown closing rear openings leading into driver housings **204**. Each of audio driver assemblies **202** is also depicted with an alignment bracket **402**. Alignment bracket **402** can be configured to create a buffer between each of audio driver assemblies **202** and lower housing component **208**. Alignment brackets **402** can also be configured to help align amplifier board **228** with driver screw terminals **316**. Amplifier board **228** is configured to support capacitors **404** and other electronic components such as electronic components **406**. Capacitors **404** are configured to provide power for audio driver assemblies **202**. In particular, the power from capacitors **404** can be used to support separate amp channels to power each of audio driver assemblies **202**. Amplifier board **228** is also depicted with terminals **408**. Each of terminals **408** can be configured to receive a fastener for coupling amplifier board **228** to driver screw terminals **316**. In this way, amplifier board **228** can be securely coupled to each of audio driver assemblies **202**.

FIG. 5A shows a perspective view of a rear portion of audio driver assembly **202**. Cap **314** is removed from audio driver assembly **202** to reveal a rear-facing surface of U-cup **310**. U-cup **310** is coupled to peripheral tab portions **508** of phase plug **304**. Wires **502** are also depicted and can electrically couple audio components of audio driver assembly **202** to respective driver screw terminals **316**. Amplifier board **228** is shown secured to audio driver assemblies **202** by fasteners **504**, which are depicted engaging driver screw terminals **316**. FIG. 5A also shows a rear view of U-cup **310**, which includes engaging features **506** that engage tabs **508** of phase plug **304**.

FIG. 5B shows a cross-sectional view of fastener **504** engaging driver screw terminal **316**. Fastener **504** can be an electrically conductive fastener and can be configured to carry a signal received from terminal **408** disposed upon amplifier board **228**. In some embodiments, amplifier board **228** can also include a lower terminal **507** disposed on a lower surface of amplifier board **228**. In some embodiments, lower terminal **507** can be compressed against driver screw terminal **316**, allowing signals to be transferred or a grounding path to be established between lower terminal **507** and driver screw terminal **316** along electrically conductive pathway **509**. Those signals can then be transferred to wire **502**, which is soldered to a lower portion of driver screw terminal **316**. The signals can include instructions for generating audio using the audio components within driver housing **204**. In some embodiments, one of wires **502** can be used to receive instructions and the other can be configured to receive power. In some embodiments, one of wires **502** can function as a grounding pathway.

FIG. 5C shows another embodiment in which fastener **504** engages an opening defined by driver housing **204**. When driver housing **204** is made of electrically insulating materials, electrical signals and power can be routed into driver housing **204** by one or more of wires **502**. In some embodiments, sheet metal **510** can be positioned between driver housing **204** and amplifier board **228**. Sheet metal **510** can be bent in order to help define electrically conductive pathway **509** toward an exterior surface of driver housing **204**. Sheet metal **510** can also define an opening or a notch

configured to accommodate fastener **504**. In some embodiments, wire **502** can be soldered to sheet metal **510**.

FIG. **6** shows an exploded view of audio driver assembly **202**. Adapter **302** can be inserted into driver housing **204**. Driver housing **204** can include have internal features suited to receive adapter **302**. Adapter **302** can define an opening allowing audio waves to pass through adapter **302** and out of driver housing **204**. A rear-facing surface of adapter **302** can be configured to receive protrusions of phase plug **304**. Phase plug **304** defines a number of openings that shape the audio waves in a manner that prevents destructive interference as the audio waves are being directed toward the exit of driver housing **204**. Phase plug **304** is also depicted with tabs **508**, which are configured to be engaged by engaging features **506** of U-cup **310**.

FIG. **6** also depicts coil assembly **306**, which includes diaphragm **602** and coil **604**. Coil **604** is electrically coupled with a power source so that it is able to receive alternating current. The alternating current results in coil **604** outputting a shifting magnetic field that interacts with the magnetic field emitted by permanent magnet **308** of the magnetic motor assembly. This interaction results in coil assembly **306** traveling back and forth between phase plug **304** and U-cup **310**. The direction of travel of coil assembly **306** can be defined by the direction of the circumferential current flow in the coil and the direction of the radially oriented magnetic flux within the air gap between top plate **606** and U-cup **310** that is generated by permanent magnet **308**. The direction of force is perpendicular to both the flow of current in coil **604** and the magnetic flux lines. Motion is permitted in that direction by a compliant surround portion of diaphragm **602**. Plate **606** can be coupled to permanent magnet **308** and designed to help shape the flow of magnetic flux emitted by permanent magnet **308**. The force applied to coil **604** results in diaphragm **602** moving and generating audio waves that travel through phase plug **304** and then out of driver housing **204**.

FIG. **7** shows a cross-sectional view of audio driver assembly **202**. In particular, a back volume **702** of audio driver assembly **202** is depicted. Generally a back volume refers to an open area within the speaker housing containing air that is in fluid communication with a rear-facing surface of a diaphragm and not in fluid communication with a listener. Similarly, a front volume refers to another open area within the speaker housing containing air that is in fluid communication with both a forward-facing surface of the diaphragm and the listener. A larger back volume **702** increases the amount of air behind diaphragm **602** helping to increase low frequency output at a given power output for audio driver assembly **202**. An apparent size of back volume **702** can be increased by foam layer **312**, which by slowing air down within the back volume increases the apparent volume of back volume **702**. Back volume **702** can also be enlarged by a portion of back volume **704** that is forward of the diaphragm. By leaving a gap **706** between phase plug **304** and driver housing **204**, the additional open space can be added on to the total volume of back volume **702**. In some embodiments, this additional volume forward of diaphragm **602** can substantially improve audio performance when diaphragm **602** oscillates in the direction indicated by arrow **708**. In some embodiments, back volume **702** and forward back volume **704** can add up to about 17 CCs. FIG. **7** also shows magnetic flux flow lines **710** and how both U-cup **310** and plate **606** cooperate to define a flux flow path for the magnetic field emitted by permanent magnet **308**. In this

way, the magnetic field can be concentrated around the path along which coil **604** traverses during operation of audio driver assembly **202**.

FIG. **8** shows a cross-sectional view of array speaker **100** that includes only components within a central portion of array speaker **100**. FIG. **8** depicts both subwoofer **802** and microphones **804**. Subwoofer **802** includes a permanent ring magnet **806** for driving a coil **808** and a diaphragm **810** of subwoofer **802**. It should be noted that diaphragm **810** can also be referred to as a cone. While the cone terminology often refers to a rigid oscillating member associated with a subwoofer, for the purposes of this description, the oscillating member of the subwoofer will be described generally as a diaphragm. Subwoofer **802** can be mounted to lower housing component **208** by damped coupling **812**, which can minimize an amount of force and/or vibration transferred to lower housing component **208** from subwoofer **802**. A magnetic field emitted by ring magnet **806** can be shaped by pole structure **814** and plate structure **816**. An air gap between pole structure **814** and plate structure **816** can help localize the magnetic field emitted by ring magnet **806** around coil **808**.

The position of subwoofer **802** in the upper portion of the housing allows the region beneath subwoofer **802** to be used as a back volume for enhancing the audio produced by subwoofer **802**. While not depicted this back volume area includes audio driver assemblies **202**. This works well since the audio waves generated by audio driver assemblies **202** are isolated by housings **204** of audio driver assemblies **202** and the audio generated by audio driver assemblies **202** exits out the bottom end of the device housing.

FIG. **8** also shows how microphones **804** can be distributed radially as depicted in FIG. **8**. In some embodiments, a flexible ribbon cable or flexible PCB **818** can be utilized to electrically couple together each of microphones **804**. In some embodiments, microphones **804** can be configured to detect both internal audio sources and external audio sources. In some embodiments, microphones **804** can be configured to monitor the inside of array speaker **100** for distortion or overdriving to prevent speaker damage. In some embodiments, microphones **804** can be configured to relay audible user commands to a processor of array speaker **100**. For example, microphones **804** can be aligned with and sealed across an opening in the sidewall of the device housing, thereby allowing multiple microphones **804** to cooperatively triangulate the location of any audio detected by two or more of microphones **804**.

FIG. **9A** shows how magnet **806** of subwoofer **802** can extend radially around a periphery of subwoofer **802** according to an embodiment. Because magnet **806** extends radially from subwoofer **802**, capacitors **404** are limited in diameter. For this reason, as depicted in FIG. **9B**, more capacitors **404** can be needed to power audio driver assemblies **202** than would be needed with a greater diameter capacitor. Generally, using a greater number of capacitors **404** tends to be more expensive and takes up a larger amount of space on amplifier board **228**.

FIG. **9C** shows a subwoofer **902** according to some embodiments of the disclosure that includes a magnet **904** instead of magnet **806**. Magnet **904** includes a number of protruding lobes **906** that can extend radially near or in some cases all the way out to the interior facing surfaces of lower housing component **208**. While magnet **904** is depicted having three lobes **906** it should be appreciated that magnet **904** could have any number of lobes **906** as long as they are distributed at an even interval about magnet **904**. For example, four narrower lobes could also be utilized. The

even distribution of the lobes helps to keep the magnetic field emitted by magnet **904** from becoming asymmetric. In addition to lobes **906** it should be appreciated that an upper plate **908** directly above magnet **904** and a lower plate directly below magnet **904** can also be shaped to conform with lobes **906** of magnet **904**. FIG. 9D shows how lobes **906** of magnet **904** leaves sufficient room for larger diameter capacitors **912**. This configuration would allow audio driver assemblies **202** (not depicted) to be powered by larger diameter capacitors **912**. In some embodiments, this can allow more power to be delivered to audio driver assemblies **202** allowing for higher quality and/or louder audio output of driver assemblies **202**.

FIG. 10A shows a perspective view of subwoofer **802**. Subwoofer **802** includes a lip with multiple notches configured to receive fasteners. The lip is used to secure subwoofer **802** to a housing of array speaker **100**. Unfortunately, the inertia of the moving mass of subwoofer **802** creates forces in the Z axis and moments about the X and Y axes, which can lead to visible shaking and hopping of array speaker **100**. This could lead array speaker **100** to move laterally while playing music and become a drop hazard. The motion generated by subwoofer **802** can also create vibrations throughout the system, which can cause audible buzzing noises and potentially result in premature component failure or disconnection. Vertical motion of array speaker in the Z axis can also make a touch interface positioned on the top of array speaker **100** more difficult to use. For example, vertical motion of array speaker **100** could cause a user to touch the wrong portion of the touch interface or to make an input earlier than otherwise desired.

FIG. 10A shows a solution to this problem. A number of elastomeric grommets **1002** and shoulder screws **1004** can be used to secure a flange **1006** of subwoofer **802** to a mounting feature within array speaker **100**. This can be accomplished by sliding each grommet **1002** into a notch **1008** defined by flange **1006**. Once secured within notch **1008**, shoulder screw **1004** can be inserted through an opening defined by grommet **1002**. A shoulder portion of shoulder screw **1004** can be positioned within the opening defined by grommet **1002** and a threaded portion of shoulder screw **1004** can be used to engage the mounting feature.

FIG. 10B shows a perspective view of grommet **1002**, which can be made from highly damped rubber and have a specific geometry to achieve optimal stiffness properties to damp oscillations generated by subwoofer **802**. Grommet **1002** can define a U-shaped channel **1010** configured to allow grommet **1002** to slide into one of notches **1008**. When flange **1006** is engaged within U-shaped channel **1010**, the shape of U-shaped channel **1010** acts as an anti-rotation feature that prevents rotation of grommet **1002** within notch **1008**. This can be helpful when driving shoulder screws **1004** into an attachment feature. Grommet **1002** also includes protrusions **1012** protruding from upper flange **1014**. Protrusions **1012** also protrude from lower flange **1016**. Protrusions **1012** can also be configured to compress more easily when shoulder screw **1004** engages grommet **1002** through opening **1018**. The height and/or width of protrusions **1012** can be tuned to adjust the overall stiffness provided by grommet **1002**.

FIG. 11A shows an exploded view of a convex user interface **1100**. Cosmetic layer **1102** can be formed from glass or plastic and be configured to provide a smooth surface upon which a user can comfortably make inputs. The depicted pattern on cosmetic layer **1102** includes symbols corresponding to increasing and decreasing a setting. In some embodiments, the plus and minus signs can apply to

raising the volume or skipping tracks in a song. For example, a long press of the plus can be configured to increase volume while a short press could skip to the next track of a media playlist. Cosmetic layer **1102** can be coupled to adhesive layer **1104**. Adhesive layers **1104** can join cosmetic layer to wedge **1106** and wedge **1106** to touch/LED board **1108**. Adhesive layers **1104** can define a number of openings configured to reduce any attenuation in the touch signals caused by adhesive layers **1104**. Wedge **1106** can define the convex geometry of user interface **1100**. A dielectric constant of wedge **1106** can be tuned to efficiently pass touch inputs from cosmetic layer **1102** to touch/LED board **1108**. It should be noted that some of the openings defined by adhesive layers **1104** and wedge **1106** can be designed to accommodate fasteners **1110**, which secure touch/LED board **1108** to mounting frame **1112**. Light guides **1114** can be configured to direct light emitted by light sources coupled to touch/LED board **1108** toward cosmetic layer **1102** of user interface **1100**. In some embodiments, the openings defined by the different openings can be configured to allow light from LEDs disposed on touch/LED board **1108** to illuminate portions of cosmetic layer **1102**.

FIG. 11B shows a cross-sectional view of assembled convex user interface **1100**. LEDs **1116** are depicted on upper and lower surfaces of touch/LED board **1108**. In this way, upper LED **1116** can shine light directly toward cosmetic layer **1102**. Lower LEDs **1116** shine light into a recess defined by mounting frame **1112**. The light emitted by lower LEDs **1116** can then be redirected by light guides **1114** toward other openings situated below the plus and minus indicators of cosmetic layer **1102**.

FIG. 11C shows a cross-sectional view of array speaker **100** with convex user interface **1100** disposed at the top. Audio waves **1118** are shown being generated by the oscillation of subwoofer **802** in a vertical direction. In some embodiments, the oscillation can be aligned with a longitudinal axis of lower housing component **208**. In this instance, the term aligned is used to mean that the direction of motion is substantially parallel to the longitudinal axis of lower housing component **208**. Audio waves **1118** are configured to exit array speaker **100** through vents **1120**. Main logic board **1122** is shown secured to a bottom surface of convex user interface **1100**. Main logic board **1122** can include one or more heat generating components such as a processor. Audio waves **1118** incident to main logic board **1122** can dissipate heat generated by the heat generating components of main logic board **1122**. In some embodiments, heat generated by touch/LED board **1108** can be conducted to main logic board **1122**, where the heat can be convectively dissipated by the air displaced by audio waves **1118**. In some embodiments, subwoofer **802** can be configured to operate at a sub-sonic frequency designed to maximize the amount of air pushed past main logic board **1122**, when heat dissipation is a priority. In some embodiments, array speaker **100** can include various sensors within above subwoofer **802** that identify high heat loading conditions that could result in heat dissipation becoming a priority. For example, a heat sensor could be affixed to a surface of main logic board **1122**. Furthermore, various flow rate sensors could be positioned between subwoofer **802** and vents **1120** to identify any vent blockages. Subwoofer **802** can also be configured to oscillate at a frequency that generates haptic feedback along an exterior surface of convex user interface **100**. For example, subwoofer **802** could be commanded to operate at the frequency that generates the haptic feedback in response to one or more different types of user inputs.

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FIG. 11C also shows seal 1124, which is configured to seal the back volume of subwoofer 802. Seal 1124 can be useful in preventing upper housing component 1126 from buzzing against lower housing component 208. FIG. 11C also shows vibration ring 1125, which twists along threads 1128. Vibration ring 1125 formed of polymeric material that twists down until it engages channels defined by alignment brackets 402 of driver housings 204 of each driver in order to discourage vibration of audio driver assemblies 202. In some embodiments, vibration ring 1125 can include at least three rows of threads around the periphery of vibration ring 1125.

FIG. 12A shows a perspective view of seal 1124. Seal 1124 is arranged in a loop and capable of forming a seal around an audio component secured to lower housing component 208. Seal 1124 is configured to seal across parting lines and absorb tolerances of injection molded plastic parts. Seal 1124 can be made up of multiple layers. FIG. 12B shows a cross-sectional view of seal 1124 in accordance with section line C-C. The cross-sectional view shows how two compliant foam layers 1202 can be joined together by a stiff plastic layer 1204. The stiff plastic layer 1204 can make the installation more reliable by helping to retain the shape of seal 1124. This design can provide better performance at lower cost than a typical O-ring. FIG. 12C shows a close-up view of seal 1124 arranged between upper housing component 1126 and support halo 1206.

FIGS. 13A-13B show how upper housing component 1126 can be attached to lower housing component 208. Both upper and lower housing components 1126 and 208 include a number of discrete threading segments. The threading segments are arranged on an exterior-facing surface of upper housing component 1126 and an interior-facing surface of lower housing component 208. In order to attach upper and lower housing components 1126 and 208 together, threading segment 1302 of upper housing component 1126 can be aligned with threading segment 1304 of lower housing component 208. Upper housing component 1126 can then be lowered until the threading segments 1302 and 1304 contact each other. Upper housing component 1126 can then be twisted to shift threading segment 1302 to the right until threading segment 1302 clears threading segment 1304 and then contacts threading segment 1306. Once threading segment 1302 contacts threading segment 1306 upper housing component 1126 can be twisted in the opposite direction to move threading segment 1302 to the left until threading segment 1302 clears threading segment 1306 and contacts threading segment 1308. Upper housing component 1126 can continue to move in alternating directions until threading segment 1310 is secured against locking surface 1312 of threading segment 1314. Threading segment 1310 can have a locking feature 1316 configured to engage locking surface 1312. Locking feature 1316 is able to deflect due to an area surrounding locking feature 1316 being removed from upper housing component 1126. FIG. 13B shows upper housing component 1126 locked against lower housing component 208 by interaction between locking surface 1312 and locking feature 1316.

FIGS. 14A-14D show cantilevered foot 230. FIG. 14A shows cantilevered foot 230 just below array speaker 100. Cantilevered foot 230 is configured to support the weight of array speaker 100 above a support surface and to dissipate any vibrations propagating through array speaker 100. FIG. 14B shows a perspective view of cantilevered foot 230. An interior layer 1402 of cantilevered foot 230 can be formed of a somewhat rigid but deflectable material such as polycarbonate. An exterior layer 1404 formed of a more compliant

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material such as silicone can be configured to dissipate vibrations transmitted to cantilevered foot 230. Unfortunately, sometimes vibrations can be severe enough to cause bouncing or lateral shifting to occur with more standardized vibration dissipating feet.

FIG. 14C shows a top view of cantilevered foot 230 and in particular, a section line D-D bisecting cantilevered foot 230. FIG. 14D shows interior layer 1402 and exterior layer 1404. When a force 1406 acts upon cantilevered foot 230, instead of a thickness of exterior layer 1404 being solely responsible for dissipating any vibrations propagated to cantilevered foot 230, cantilevered arms 1408 flex radially to absorb some of force 1406 associated with the vibrations as depicted. This radial flexing results in the vertical vibrations being translated horizontally and substantially reducing the vertical vibrations. The other positive effect of the radial flexing is it places more of exterior layer 1404 in contact with the support surface, increasing the friction between cantilevered foot 230 and the support surface and consequently the resistance of array speaker to lateral shift. In some embodiments, cantilevered foot 230 and grommets 1002 work together to attenuate undesirable vibration of array speaker 100. In some embodiments, annular foam 1410 can be added along a periphery of cantilevered foot 230, which can be configured to prevent unwanted vibration of the periphery of cantilevered foot 230. In this way, foam 1410 is positioned to prevent vibrations that would otherwise generate distracting vibration when the speaker device generates audio waves likely to resonate within cantilevered foot 230.

FIG. 15 shows an exploded view of an alternative convex user interface 1500 that differs in some respects from the user interface depicted in FIGS. 11A-11C. In particular, convex user interface 1500 includes two distinct illuminated, touch interface regions. User interface 1500 includes a mounting frame 1502, which defines a channel 1503 running along a circumference of mounting frame 1502. Channel 1503 can be configured to receive a drawstring associated with acoustic fabric covering array speaker 100. Channel 1503 allows each end of the drawstring to be conveniently wrapped around mounting frame 1502 along channel 1503. Mounting frame 1502 also defines multiple recesses 1504 configured to receive and accommodate light emitting components. In particular, the light emitting components include LED array board 1506 and light sources 1508. LED array board 1506 includes an array of LEDs 1510. Each of LEDs 1510 can be configured to emit three or more colors of light. LEDs 1510 can also be configured to cooperatively generate various designs associated with a first touch interface region. Light sources 1508 can each include one or more LEDs for emitting one or more colors of light associated with a second touch interface region. Interposer board 1512 can be configured to set a standoff distance between LED array board 1506 and touch printed circuit board (PCB) 1514. Interposer board 1512 can define openings that allow light generated by LEDs 1510 to pass through interposer board 1512. Interposer board 1512 can take the form of an electrically insulating layer having electrically conductive edge plating arranged along its periphery for routing power and signals between touch PCB 1514 and LED array board 1506. In this way, light emitted by LEDs 1510 can be modulated in accordance with touch inputs processed by components associated with touch PCB 1514. Touch PCB 1514 defines a number of apertures through which light generated by the light emitting components generate. In particular, volume control openings 1516 can have the shape of plus and minus symbols associated

with increasing and decreasing respectively the volume of the speaker system associated with user interface 1500.

FIG. 15 also shows fasteners 1518, which can be configured to secure touch PCB 1514 to mounting frame 1502. In some embodiments, fasteners 1518 can be self-tapping screws that form threads within openings defined by mounting frame 1502. Touch PCB 1514 can be coupled to wedge 1520 by adhesive layer 1522. Both adhesive layer 1522 and wedge 1520 can include openings through which light emitted by the light-emitting components can pass. Adhesive layer 1522 and wedge 1520 can also include openings to accommodate the head portions of fasteners 1518. Wedge 1520, which has a substantially thicker central region than its peripheral region, can be configured to give user interface 1500 its curved or convex exterior geometry. The central region of wedge 1520 includes an opening for accommodating a diffuser assembly 1523 configured to spread light received from LEDs 1510. Diffuser assembly 1523 includes a lens array 1524 having discrete diffusing optics for each of LEDs 1510. In some embodiments, lens array 1524 can take the form of a single piece of glass spreading the light from each of LEDs 1510. In other embodiments, lens array 1524 can include multiple discrete lenses that spread the light. Lens array 1524 can be secured to touch PCB 1514 by adhesive foam ring 1526. In some embodiments, touch plate 1528 can be secured to a downward facing surface of lens array 1524. Openings defined by touch plate 1528 can accommodate lens protrusions of lens array 1524. Touch plate 1528 can take the form of a thin, electrically conductive plate that improves the capacitive coupling for touch inputs received by user interface 1500. Touch plate can be electrically coupled to touch PCB 1514. In some embodiments, the flat surface of touch plate 1514 can include a touch sensor that is optimized for reading the inputs made at the convex cosmetic touch surface of user interface 1500. For example, a density of a sensing grid associated with touch plate 1514 can have a varied density that allows inputs made to be adjusted for the curvature at the exterior surface. In this way, a consistent user input can be achieved across the entire exterior touch surface of user interface 1500, thereby avoiding the situation in which touch inputs are read at a different speed in the center than along a periphery of the touch sensor. An upward-facing surface of lens array 1524 can be secured to a first diffuser plate 1530 by adhesive strips 1532 arranged along the periphery of lens array 1524. A layer of diffuser film 1534 for additional light spreading can be positioned between first diffuser plate 1530 and lens array 1524. First diffuser plate 1530 can also be configured to increase the amount of diffusion of the light emitted by LEDs 1510.

In some embodiments, first diffuser plate 1530 can be formed from a clear polycarbonate resin that is doped with particles having a different index of refraction than the clear polycarbonate resin. For example, the polycarbonate resin could be doped with Titanium Oxide particles that both give a white appearance to first diffuser plate 1530 and help to further diffuse the light passing through first diffuser plate 1530. First diffuser plate 1530 is secured to a second diffuser plate 1536 by adhesive strips 1532 arranged along the periphery of first diffuser plate 1530. Adhesive strips 1532 can be sized to create a small air gap between the first and second diffuser plates. Second diffuser plate 1536 can have a dome-shaped surface helping diffuser assembly 1523 achieve the same curvature as wedge 1520. Finally a fade film 1538 can be applied to an upward facing surface of second diffuser plate 1536. Fade film can take the form of a radially graduated filter that feathers the intensity of light

along a periphery of the light emitted by LEDs 1510. In this way, fade film 1538 prevents adhesive layer 1540 from abruptly shifting from illuminated to unilluminated in a central region of a top cap 1542. Top cap 1542 can take the form of a layer of glass or transparent polymer material such as a polycarbonate material. In some embodiments, top cap 1542 can include a layer of ink that further diffuses light passing through top cap 1542. In some embodiments, light emitted by LEDs 1510 and diffused by the aforementioned diffusive elements can cooperatively generate a mix of light having a diameter of about three centimeters.

FIG. 16A shows a downward facing surface of lens array 1524. As depicted, lens array 1524 takes the form of a single piece of shaped glass having discrete optics for multiple different light sources. In particular, lens array 1524 includes protruding lenses 1602 for diffusing light from 19 LEDs 1510 that are arranged in a honeycomb pattern. It should be appreciated that a larger or smaller number of LEDs 1510 could be accommodated by lens array 1524. Furthermore, protruding lenses 1602 could be arranged in an irregular pattern or a different regular pattern such as a rectangular grid.

FIG. 16B shows a cross-sectional side view of a portion of convex user interface 1500 that includes lens array 1524 in accordance with section line E-E. It should be noted that the adhesive layers have been omitted from this view for clarity. In particular LEDs 1510 are shown attached to LED array board 1506. Five LEDs 1510 are shown emitting light into lens array 1524. Protruding lenses 1602 of lens array 1524 diffuse the light received from LEDs 1510 prior to the light entering first and second diffuser plates 1530 and 1536. As depicted, each of protruding lenses 1602 include a concave surface oriented toward a respective one of LEDs 1510. The diffuser plates can be configured to further diffuse this light prior to the light exiting through top cap 1542. By the time the light exits through top cap 1542, the light emitted from each LED 1510 can be mixed with light from adjacent ones of LEDs 1510. In this way, a relatively small number of LEDs can cooperate to produce a mixed pattern of lights at an exterior surface defined by top cap 1542. In some embodiments, the light appearing along the surface can have a total diameter of about 30 mm and light from each LED 1510 can be spread across a diameter of about 7 mm.

FIG. 17A shows a cross-sectional, exploded view of an expandable opening defined by one end of fabric 1700. Fabric 1700 can take the form of a tube having a fixed size opening at a first end and elastic and/or expandable second end. FIG. 17A depicts the second expandable end. Fabric layers 1702, 1704 and 1706 can be configured to provide a cosmetically pleasing exterior surface for a speaker device without inhibiting the passage of audio waves generated by the speaker device. Fabric layers 1702, 1704 and 1706 can be formed of materials such as polyester, nylon and polyurethane. In some embodiments, fabric layer 1702 can have a diamond shaped pattern defining an array of diamond shaped openings that limit the amount of resistance generated by fabric layer 1702. Fabric layer 1702 can be adhered to fabric layer 1704 by adhesive layer 1708. While adhesive layer 1708 is depicted as a solid layer it should be appreciated that the adhesive can be formed to have the same pattern as fabric layer 1702. In this way, an exterior surface of fabric 1700 can be free of exposed adhesive material. An inner lip of fabric layer 1704 can be coupled to fabric layer 1706 by adhesive ring 1710. Fabric layer 1706 can then be

secured to upper housing component 1126 (not shown, see FIG. 13B). In this way, fabric 1700 can be securely coupled to the speaker device.

FIG. 17A also shows stitched threading 1712. In some embodiments, stitched threading 1712 can be sewn to a lip of fabric layer 1702. Stitched threading 1712 can take the form of a fiber arranged in a number of loops arranged along a lip of fabric 1700 and sized to accommodate drawstring 1714. Drawstring 1714 can be threaded through the openings defined by the loops of stitched threading 1712. By pulling on or releasing both ends of drawstring 1714 the lip of fabric 1700 the opening can be expanded or contracted in order to respectively install and remove fabric 1700 from the speaker device.

FIG. 17B shows a cross-sectional view of fabric assembly 1700 fully adhered together and how both ends of drawstring 1714 can protrude from the same radial position of fabric assembly 1700. Drawstring 1714 can be long enough to wrap around a mounting frame associated with a user interface of the speaker device, which allows for the drawstring to smoothly contract the opening 1716 defined by fabric 1700. In some embodiments, stitched fabric 1712 and drawstring 1714 can be replaced by an elastic loop insert-molded around the lip of fabric 1700. The elastic loop can act similarly to a rubber band and have the resilience to securely keep the fabric in place while also allowing the fabric defining opening 1716 to be expanded for removal of fabric assembly 1700 off of the speaker device.

FIG. 17C shows a top view of fabric assembly 1700 installed around a portion of upper housing component 1126. FIG. 17C shows drawstrings 1714 only partially tightened, leaving an annular gap between the opening defined by fabric assembly 1700 and the opening defined by upper housing component 1126. FIG. 17D shows how drawstring 1714 can be routed through an opening 1708 defined by mounting frame 1502 and then tightened causing fabric assembly 1700 to cinch evenly around a periphery of mounting frame 1502.

FIG. 18 shows an exploded view of a halo assembly 1800. Halo assembly includes an upper ring 1802 and a lower ring 1804 that are coupled together by fasteners 1806. Both upper and lower rings 1802 and 1804 respectively define cooperatively define threading around their periphery. The threading allows the rings to twist into place within an interior volume of a speaker housing. The bottom surface of upper ring 1802 and the top surface of lower ring 1804 have complementary geometries that allow the two rings to be radially aligned. Furthermore, when the rings are radially aligned the peripheral threading continues smoothly across the interface between the two rings. For example, lower ring includes ramp feature 1808, which aligns with recessed feature 1810, when the two rings are radially aligned. Radial alignment of rings 1802 and 1804 also results in fastener openings 1812 being aligned with fastener openings 1814. Upper ring 1802 can include additional openings adjacent to each of openings 1812, which are configured to receive additional fasteners for securing other internal components to halo assembly 1800. An interior facing surface of upper ring 1802 can include protrusions helping to thicken portions of upper ring 1802 that include openings configured to receive fasteners. Halo assembly 1800 also includes seal 1124, which can be positioned within groove 1816 and function to prevent audio waves from propagating around the periphery of halo assembly 1800.

FIG. 18 also depicts flex connector 1820. Flex connector assembly 1820 can be configured to electrically couple components distributed throughout a speaker enclosure. In

particular, flex connector assembly can extend through opening 1818 in upper ring 1802 to reach electrical component connectors disposed above halo assembly 1800. In some embodiments, ring 1804 can also include an opening aligned with opening 1818 to allow for the passage of flex connector substrate 1822. Flex connector substrate 1822 can take the form of a polyimide substrate. In some embodiments, flex connector assembly 1820 includes board to board connector 1824 that is configured to electrically couple with an electrical component such as touch PCB 1514 (see FIG. 15). Flex connector assembly 1820 can include other connectors such as connector 1826 that is configured to be electrically coupled with speaker drivers at the lower end of an associated speaker device.

FIG. 19 shows a partial cross-sectional view of a speaker device with halo assembly 1800 installed therein. Upper ring 1802 is depicted in direct contact with lower ring 1804. Fastener 1806 is shown securing upper ring 1802 and lower ring 1804 together after rotating the two rings along threads 1902 of housing component 208. Prior to fastener 1806 securing the upper and lower rings 1802 and 1804 together, threading 1904 and 1906 could fit somewhat loosely between threading 1902. In this way, halo assembly is configured to rotate easily into housing component 208. Once the correct position has been achieved, fastener 1806 causes threading 1904 and 1906 to bear against threading 1902, which secures halo assembly in place and prevents vibration of halo assembly 1800 relative to housing component 208. FIG. 19 also shows how fastener 1004 associated with flange 1006 secures flange 1006 of subwoofer 802 to upper ring 1802 of halo assembly 1800.

FIG. 20 shows how upper housing component 1126 can be secured to halo assembly 1800 by fastener 2002. Upper housing component 1126 can include a fastener opening allowing fastener 2002 to extend vertically through upper housing component 1126 and engage upper ring 1802 of halo assembly 1800. A cosmetic plug 2004 can be inserted in a recess that surrounds the opening configured to accommodate fastener 2002. Cosmetic plug 2004 prevents a fabric covering from protruding into the recess and adversely affecting the cosmetic appearance of the speaker device. FIG. 20 also shows how seal 1124 can be positioned between upper ring 1802 and lower housing component 208, which is operative to prevent audio waves from propagating around a periphery of upper ring 1802. The speaker can also include seal 2006, positioned between upper ring 1802 and flange 1006, that can help prevent audio waves from propagating through a central opening of upper ring 1802. FIG. 20 also illustrates the relative position of stepped threading 1302 of upper housing component 1126 and stepped threading 1304 of lower housing component 208.

FIG. 21 shows a perspective view of an alternative upper housing component. Upper housing component 2100 includes diamond shaped vents 2102. Diamond shaped vents 2102 can have a shape similar to a pattern of acoustic fabric covering upper housing component 2100. Even when diamond shaped vents 2102 are substantially larger than the pattern of the acoustic fabric, having a similar pattern results in the pattern contours being aligned. This alignment can make the vent openings beneath the acoustic fabric substantially less likely to be seen by a user of a speaker device associated with upper housing component 2100. In some embodiments, the pattern of the acoustic fabric could be aligned with vents 2102. For example, the acoustic fabric could be aligned so that a pattern of 4 or 16 diamond patterns is aligned within each of vents 2102. In this way the edges of the patterns could be aligned, further reducing the like-

likelihood of vents **2102** being visible to a user. Upper housing component **2100** can also include protruding support members **2104** configured to support a convex user interface along the lines of convex user interface **1500** as depicted in FIG. **15**.

FIG. **22** shows a diagram indicating different types of connected electronics that can communicate and/or interact with array speaker **100**. In some embodiments, array speaker **100** can act as a central hub to facilitate home automation. Memory on-board array speaker **100** or memory accessible through a network, which is accessible by array speaker **100**, can be used to store rules governing the interaction of the various depicted device types. Array speaker can then send instructions to the disparate devices in accordance with the stored rules. Microphones disposed within array speaker **100** can be configured to receive voice commands to carry out specific actions related to connected electronics within a user's home. In some embodiments, convex user interface can receive commands for adjusting various settings on a particular connected electronic device. For example, array speaker **100** can be configured to receive commands to make adjustments to smart locking device **2202**. In some embodiments, array speaker **100** can include instructions allowing it to lock and unlock smart locking device **2202** in response to a voice command. Furthermore, array speaker **100** can be configured to alert occupants within a house that smart locking device **2202** has been unlocked. In some embodiments, array speaker **100** can announce the identity of the user who unlocked smart locking device **2202**. In such a circumstance, smart locking device **2202** can be configured to open in response to a command received from an electronic device such as a mobile phone. Array speaker **100** can then identify the user when a user is associated with that mobile phone. In some embodiments, array speaker **100** can be configured to interact with other devices in response to actuation of smart locking device **2202**. For example, array speaker could direct the illumination of one or more of lights **2204** and adjust a temperature of an HVAC system associated with smart thermometer **2206** in response to the unlocking event.

FIG. **22** also shows communication between array speaker **100** and smart garage opener **2208**. In response to detecting an opening event of smart garage opener **2208**, array speaker could be configured to perform similar actions described above with respect to the operation of smart locking device **2202**. In some embodiments, different ones of lights **2204** could be illuminated in anticipation of the user entering the housing from a different direction.

Array speaker **100** could also be configured to operate different smart devices in accordance with various calendar events associated with an electronic calendar. For example, array speaker could be configured to disable surveillance camera **2210** during an event located in the same room as surveillance camera **2210** when that event is marked as private. Array speaker could also be configured to notify one or more users if window sensor **2212** indicates a window remains open after a particular time of day or night. In some embodiments, array speaker **100** can act as a media hub cooperating with other components such as television/monitor **2214** to present both video and audio content in response to various user inputs and/or smart device activities. For example, televisions/monitor **2214** could present a status screen and/or progress monitor indicating the status and/or activity being performed by other components that may or may not have the ability to present a graphical interface to a user of array speaker **100**. In some embodiments, array speaker could be configured to remotely direct refrigerator

2216 to send the user images of interior areas of refrigerator **2216** shortly before a user has a grocery shopping trip scheduled. While these various operations could be stored in internal memory of array speaker **100**, array speaker **100** can also be in communication with a cloud service provider helping to coordinate various activities with users that may or may not be connected with a local area network with array speaker **100**. For example, a user could connect remotely with array speaker **100** with a device such as a smart phone to activate certain tasks for smart components with which array speaker **100** is in communication.

In some embodiments, array speaker can be configured to interact with wearable display **2218**. Wearable display **2218** can take the form of augmented reality or virtual reality goggles that present digital content to a user. When wearable display **2218** is an augmented reality display, wearable display **2218** can overlay various control interfaces around array speaker **100**. For example, virtual content could overlay convex user interface atop array speaker **100** to make the user interface larger. In some embodiments, the enlarged user interface could include an expanded display and enlarged control manipulation regions that allow a user to control array speaker **100** with more efficiently and/or with a greater degree of options. For example, user interface could be configured to display a virtual graphics equalizer allowing a user to increase or reduce treble and/or bass output associated with the audio being generated by array speaker **100**. In some embodiments, a user could be presented with an overlay that visualized the various regions of the room covered by each of a number of speaker drivers contained within array speaker **100**. The user could then be able to adjust audio output specific to a particular region associated with one or more speaker drivers. For example, the user could identify only the depicted regions containing individuals listening to the audio output from array speaker **100**. Furthermore, the user could reduce the audio output for a first user positioned in a first region of the array speaker associated with a first audio driver and increase the audio output for a second user positioned in a second region of the array speaker associated with a second audio driver. In this way, listeners can enjoy audio at a desired volume and the virtual interface allows the user to quickly identify the regions within which various listeners are located. In some embodiments, array speaker **100** can include various indicia that help circuitry and sensors associated with wearable display **2218** to orient the virtual content relative to array speaker **100**. For example, since array speaker **100** is cylindrical it could be difficult to determine a radial position of each of the speaker drivers within array speaker **100**. Small indicia such as decorative symbols could be embedded within acoustic fabric covering array speaker **100**. In this way, the various listening zones could be more accurately associated with array speaker **100**. In some embodiments, array speaker **100** can include optical sensors configured to identify the position of various listeners in a room and then change the audio output to improve the audio experience for the identified listeners.

In some embodiments, wearable display device can be configured to receive optical commands from array speaker **100**. For example, a display associated with a user interface can be configured to output particular patterns of light. Optical sensors of wearable display device **2218** can identify the patterns of light and in response vary the display in some manner. For example, the type, size and orientation of virtual controls displayed by wearable display **2218** can be varied in accordance with the output of the display associated with the user interface.

FIG. 23 shows a block diagram illustrating communication and interoperability between various electrical components of array speaker 100. Processor 2302 can be in communication with the depicted electrical components. User interface 2304 can receive user inputs that are then received by processor 2302. In response to the user inputs, processor 2302 can interpret and relay signals corresponding to the received user inputs to other electrical components. For example, user interface can receive user inputs directing an increase in output of both subwoofer 2306 and audio driver assemblies 2308. In some embodiments, the electrical components can all be linked together by electrically conductive pathways established by components such as flex connector 1820, which is able to route electrical signals to various electrical components distributed throughout a device housing of array speaker 100. Array speaker 100 can also include display system 2312. Display system 2312 can be configured to provide visual feedback to a user of array speaker 100. For example, the visual feedback can be provided in response to interaction with a voice assistant such as the Siri® voice assistant produced by Apple Inc., of Cupertino, Calif. In some embodiments, an array of colorful mosaic patterns could be presented while a voice request is being processed and/or as the voice assistant is waiting for the voice request. Array speaker can also include a computer-readable medium 2314. Computer-readable medium 2314 can be configured to store or at least cache an amount of media files for playback by subwoofer 2306 and audio driver assemblies 2308. In some embodiments, the media files stored on computer-readable medium 2314 can include, e.g., movies, TV shows, pictures, audio recordings and music videos. In some embodiments, a video portion of a media file can be transmitted to another device for display by wireless communication system 2316. This could be desirable even when display system 2312 is showing the video portion since another device may have a larger or more easily viewable display for a particular user. For example, the other display device could be selected in accordance with a user's position within a room.

FIG. 23 also shows RAM/ROM component 2318. RAM/ROM component 2318 can include RAM (random access memory) for short term caching of frequently used information and/or information cued just prior to playback. ROM (read only memory) can be used to store computer code such as device drivers and lower level code used in the basic operation of array speaker 100. In some embodiments, RAM/ROM component 2318 can take the form of two separate components.

FIG. 23 also shows how array speaker 100 can also include a sensor array 2320 that includes microphones, proximity sensors, touch sensors, accelerometers and the like. Microphones of sensor array 2320 could be configured to monitor for voice commands. In some embodiments, the microphones could be configured to process voice commands only after recognizing a command phrase indicating the user's intent to issue a voice command. Microphones can be interspersed radially along the outside of the device housing so that the housing doesn't mask or obscure the voice commands. Multiple microphones can also be utilized to triangulate a position of a user within the room. In certain instances it may be desirable to optimize audio output or cue additional smart devices (see FIG. 22) in accordance with a determined location of the user.

In addition to identifying a user's location by triangulation with spatially dispersed microphones, proximity sensors can be distributed along the exterior surface of array speaker 100 in order to help identify the presence of users and/or

obstructions surrounding array speaker 100. In some embodiments, the proximity sensors can be configured to emit infrared pulses that help characterize objects surrounding array speaker 100. The pulses reflected back to the sensor can be processed by processor 2302, which can then make a characterization of any objects surrounding array speaker 100. In some embodiments, an audio output of array speaker 100 can be adjusted in situations where surrounding objects substantially change the expected audio output of array speaker 100. For example, if array speaker 100 is positioned against a wall or column the infrared sensors could identify the obstruction and attenuate or cease output of speaker drivers pointed toward the wall or column. The reflected pulses and audio triangulation data can be combined to further refine the position of a user delivering instructions to array speaker 100. Sensor array 2320 can also include touch sensors that allow a user to input commands along an exterior surface of array speaker 100. For example, touch PCB 1514 of the convex user interface depicted in FIG. 15 is configured to detect user gestures made along top cap 1542 and interpret the gestures as various instructions to be carried out by one or more components of array speaker 100.

Sensor array 2320 can also include one or more accelerometers. The accelerometers can be configured to measure any tilt of array speaker 100 with respect to a gravitational reference frame. Since array speaker 100 is optimized to evenly distribute audio content in a room when positioned on a flat surface, placing array speaker 100 on an inclined or declined surface could negatively impact the acoustic output of array speaker 100. In response to the accelerometer determining array speaker 100 is tilted at an angle of greater than 2 degrees, array speaker could be configured to prompt the user to find a flatter surface to place array speaker on. Alternatively, array speaker can be configured to alter the sound output to compensate for the tilted angle. In some embodiments, accelerometers could also be configured to monitor for any resonant vibrations within array speaker 100. Processor 2302 could then be configured to adjust the audio output to help subwoofer 2306 and/or audio driver assemblies 2308 avoid or reduce the generation of frequencies that cause array speaker 100 to vibrate at one or more resonant frequencies.

The various aspects, embodiments, implementations or features of the described embodiments can be used separately or in any combination. Various aspects of the described embodiments can be implemented by software, hardware or a combination of hardware and software. The described embodiments can also be embodied as computer-readable code on a computer-readable medium for controlling operation of the array speaker. In some embodiments, the computer-readable medium can include code for interacting with other connected devices within a user's home. For example, the array speaker could be configured to use its ambient light sensor to identify human activity and to learn when to activate and deactivate certain devices within the user's home. The computer-readable medium is any data storage device that can store data, which can thereafter be read by a computer system. Examples of the computer-readable medium include read-only memory, random-access memory, CD-ROMs, HDDs, DVDs, magnetic tape, and optical data storage devices. The computer-readable medium can also be distributed over network-coupled computer systems so that the computer-readable code is stored and executed in a distributed fashion.

The foregoing description, for purposes of explanation, used specific nomenclature to provide a thorough under-

standing of the described embodiments. However, it will be apparent to one skilled in the art that the specific details are not required in order to practice the described embodiments. Thus, the foregoing descriptions of specific embodiments are presented for purposes of illustration and description. 5 They are not intended to be exhaustive or to limit the described embodiments to the precise forms disclosed. It will be apparent to one of ordinary skill in the art that many modifications and variations are possible in view of the above teachings.

What is claimed is:

1. A voice-controlled electronic device, comprising:
 - an axisymmetric device housing;
 - a wireless communication system disposed within the axisymmetric device housing;
 - a computer-readable memory disposed within the axisymmetric device housing;
 - a microphone disposed at an exterior surface of the axisymmetric device housing;
 - one or more processors disposed within the axisymmetric device housing and coupled to the computer-readable memory, the one or more processors configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone after recognizing a command phrase indicating a user's intent to issue a voice command;
 - audio driver assemblies distributed radially about an interior of the axisymmetric device housing, each of the audio driver assemblies including a diaphragm and an audio channel providing a path for sound generated by the diaphragm to exit a driver housing; and
 - a power supply unit suspended above the of audio driver assemblies, a portion of the power supply unit protruding between the audio driver assemblies, the power supply unit being operatively coupled to provide power to the one or more processors, the wireless communication system, the microphone and the audio driver assemblies.
2. The voice-controlled electronic device as recited in claim 1 further comprising:
 - an amplifier board electrically coupled to each of the audio driver assemblies, the amplifier board defining a central opening through which a longitudinal axis of the axisymmetric device housing extends.
3. The voice-controlled electronic device as recited in claim 2,
 - wherein the power supply unit extends through the central opening defined by the amplifier board.
4. The voice-controlled electronic device as recited in claim 2 further comprising:
 - amplifiers disposed on the amplifier board, at least one of the amplifiers being associated with each of the audio driver assemblies.
5. The voice-controlled electronic device as recited in claim 2 wherein the amplifier board is electrically coupled to each of the audio driver assemblies by way of a conductive fastener.
6. The voice-controlled electronic device as recited in claim 1 wherein each of the audio driver assemblies comprises drive screw terminals having a threaded aperture configured to receive a conductive fastener and an internal terminal coupled to an electrically conductive wire electrically coupled to one or more audio components disposed within the audio driver assemblies.
7. An electronic device, comprising:
 - a device housing;

- a computer-readable memory disposed within the device housing;
- a microphone disposed within the device housing;
- a processor disposed within the device housing and coupled to the computer-readable memory, the processor configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone;
- a wireless communication system disposed within the device housing and configured to transmit the voice commands to a remote server for further processing; and
- audio driver assemblies arranged in a circular configuration within the device housing, each audio driver assembly including:
 - a diaphragm dividing an interior volume within the audio driver assembly into a front volume and a rear volume
 - a voice coil assembly disposed within the rear volume, each audio driver assembly oriented such that audio waves generated by the diaphragm within the front volume are initially oriented toward a central region of the circular configuration.
- 8. The electronic device as recited in claim 7 wherein each of the audio driver assemblies is connected to a channel that reorients a portion of the audio waves toward a periphery of the device housing.
- 9. The electronic device as recited in claim 7 further comprising a plurality of microphones distributed radially about the device housing.
- 10. The electronic device as recited in claim 9 wherein the further processing done by the remote server includes voice recognition.
- 11. The electronic device as recited in claim 7 further comprising:
 - a power supply unit positioned between two or more of the audio driver assemblies and configured to provide power to the processor, the wireless communication system and the microphone.
- 12. The electronic device as recited in claim 11 further comprising a subwoofer positioned above the power supply unit.
- 13. The electronic device as recited in claim 7 wherein each audio driver assembly has a discrete housing enclosing the diaphragm and the voice coil assembly.
- 14. The electronic device as recited in claim 7 further comprising:
 - an annular printed circuit board electrically coupled to one or more of the audio driver assemblies.
- 15. An electronic device, comprising:
 - an axisymmetric housing;
 - a computer-readable memory disposed within the axisymmetric housing;
 - a microphone;
 - a processor disposed within the axisymmetric housing and coupled to the computer-readable memory, the processor configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone;
 - a wireless communication system disposed within the axisymmetric housing and configured to relay the voice commands to a remote server for further processing; and
 - an array of audio driver assemblies disposed within the axisymmetric housing at a regular radial interval, each of the audio driver assemblies being configured to

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generate audio waves that exit the axisymmetric housing through acoustic vents defined by a downward facing end of the axisymmetric housing.

16. The electronic device as recited in claim 15 further comprising:

a power supply unit suspended above the array of audio driver assemblies, the power supply unit having a first portion protruding between two or more of the audio driver assemblies.

17. The electronic device as recited in claim 16 wherein the first portion of the power supply intersects a longitudinal axis of the axisymmetric housing.

18. The electronic device as recited in claim 16 wherein an electrically conductive cable supplying power to the power supply unit is routed between two of the audio driver assemblies.

19. The electronic device as recited in claim 15 wherein the audio driver assemblies are pressed against one end of the axisymmetric housing by a threaded annular ring that engages threading defined by an interior facing surface of the axisymmetric housing.

20. An electronic device, comprising:

a device housing;

a computer-readable memory disposed within the device housing;

a microphone disposed within the device housing;

a processor disposed within the housing and coupled to the computer-readable memory, the processor configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone;

a wireless communication system disposed within the device housing and configured to transmit the voice commands to a remote server for further processing; and

audio driver assemblies distributed radially about an interior of the device housing, diaphragms of each audio driver assembly arranged so that audio waves generated by the diaphragms are initially oriented toward a central region of the device housing and then reoriented toward a periphery of the device housing by a channel coupled to each of the audio driver assemblies.

21. A voice-controlled electronic device, comprising:

a device housing;

a wireless communication system disposed within the device housing;

a computer-readable memory disposed within the device housing;

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a microphone disposed at an exterior surface of the device housing;

one or more processors disposed within the device housing and coupled to the computer-readable memory, the one or more processors configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone after recognizing a command phrase indicating a user's intent to issue a voice command;

audio driver assemblies distributed radially about an interior of the device housing, each of the audio driver assemblies including a diaphragm and an audio channel providing a path for sound generated by the diaphragm to exit a driver housing;

an amplifier board electrically coupled to each of the audio driver assemblies, the amplifier board defining a central opening through which a longitudinal axis of the device housing extends; and

a power supply unit positioned between two or more of the audio driver assemblies and operatively coupled to provide power to the one or more processors, wireless communication system, microphone and audio driver assemblies,

wherein the power supply unit extends through the central opening defined by the amplifier board.

22. An electronic device, comprising:

a device housing;

a computer-readable memory disposed within the device housing;

a microphone disposed within the device housing;

a processor disposed within the housing and coupled to the computer-readable memory, the processor configured to execute computer instructions stored in the computer-readable memory for interacting with a user and processing voice commands received by the microphone;

a wireless communication system disposed within the device housing and configured to transmit the voice commands to a remote server for further processing;

audio driver assemblies distributed radially about an interior of the device housing, diaphragms of each audio driver assembly arranged so that audio waves generated by the diaphragms are initially oriented toward a central region of the device housing; and

an annular circuit board electrically coupled to and supported by two or more of the audio driver assemblies.

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

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APPLICATION NO. : 15/965552
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INVENTOR(S) : Craig Stanley et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page

Column 2, In the Abstract:

Delete "can be configured reduce the" and insert --can be configured to reduce the--

In the Claims

Column 25, Claim 1:

Delete "and a power supply unit suspended above the of audio driver" and insert --and a power supply unit suspended above the audio driver--

Signed and Sealed this
Tenth Day of September, 2024
Katherine Kelly Vidal

Katherine Kelly Vidal
Director of the United States Patent and Trademark Office